MITSUBISHI



REVISIONS

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* The manual number is given on the bottom left of the back cover.

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Nov.,1993	IB (NA) 66446-A	First edition
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		A1SX41-S1, AISX42-S1, A1S65B-S1, A1S68B-S1, A1S52B-S1, A1S55B-S1, A1S58B
		Correction
		CONTENTS, SAFETY CAUTIONS, Section 10.4.2
		Addition
		Sections 1, 2.2, 4.4.4, 5, 6, 8, 8.1, 8.2, 8.3, 8.4, 10
		Sections 1, 2.2, 4.4.4, 5, 6, 8, 8.1, 8.2, 8.3, 8.4, 10

SAFETY CAUTIONS

(You must read these cautions before using the product)

In connection with the use of this product, in addition to carefully reading both this manual and the related manuals indicated in this manual, it is also essential to pay due attention to safety and handle the product correctly.

The safety cautions given here apply to this product in isolation. For information on the safety of the PC system as a whole, refer to the CPU module User's Manual.

These SAFETY CAUTIONS are classified into two grades: "DANGER" and "CAUTION".



Safety caution given when incorrect handling could result in hazardous situations involving the possibility of death or serious injury.

Safety caution given when incorrect handling could result in hazardous situations involving the possibility of moderate or light injury or damage to property.

Note that, depending on the circumstances, failing to follow a A CAUTION may also have very serious consequences.

Both of these classes of safety caution are very important and must be observed. Store this manual carefully in a place where it is accessible for reference whenever necessary, and forward a copy of the manual to the end user.

[System Design Precautions]



[System Design Precautions]



[Cautions on Mounting]

 Use the PC in an environment that conforms to the general specifications in the manual. Using the PC in environments outside the ranges stated in the general specifications will cause electric shock, fire, malfunction, or damage to/deterioration of the product. 			
 Insert the tabs at the bottom of the module into the holes in the base unit, and correctly tighten the module fixing screws with specified torque. Improper installation may acuse erroneous operation, accidents, or the module to fall out. 			
 Extension cables should be securely connected to base unit and module connectors. Check for loose connection after installation. A poor connection could result in contact problems and erroneous inputs/outputs. 			
 Plug the memory cassette firmly into the memory card mounting connector. Check for loose connection after installation. A poor connection could result in erroneous operation. 			
• Do not directly touch the module's conductive parts or electronic components. Doing so could cause malfunction or trouble in the module.			

[Cautions on Wiring]

DANGER
 Switch off the external power supply before staring installation and wiring work.

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Failure to do so could result in electrical shocks and equipment damage.

 After installation and wiring is completed, be sure to attach the terminal cover before switching the power ON and starting operation.
 Failure to do so could result in electrical shocks.



[Cautions on Startup and Maintenance]



[Cautions on Disposal]

Dispose of this product as industrial waste.	

INTRODUCTION

1 2

Thank you for choosing the Mitsubishi MELSEC-A Series of General Purpose Programmable Controllers. Please read this manual carefully so that the product is used to its optimum. A copy of this manual should be forwarded to the end user.

This manual describes specifications and requirements related to safety, installations, wiring and maintenance of the AnS series PC. For functional information, please refer to detail manuals of each module.

Guidelines for the safety of the user and protection of the AnS series PC

This manual provides information for the installation and use of the AnS series PC. The manual has been written to be used by trained and competent personnel. Please read the manual carefully before installation and/or operations of the product. If the product is used in a manner not specified by the manual, the protection provided by the product may be impaired.

Note: Definition of 'trained and competent personnel' is as follows:

- a) Any engineer who is responsible for the planning, design and construction of automatic equipment using the product associated with this manual should be of a competent nature, (trained and qualified to the local and national standards required to fulfill that role). These engineers should be fully aware of all aspects of safety with regards to automated equipment.
- b) Any commissioning or service engineer must be of a competent nature, trained and qualified to the local and national standards required to fulfill that job. These engineers should also be trained in the use and maintenance of the completed product. This includes being completely familiar with all associated documentation for the said product. All maintenance should be carried out in accordance with established safety practices.
- c) All operators of the completed product should be trained to use that product in a safe and co-ordinated manner in compliance to established safety practices. The operators should also be familiar with all documentation which is connected with the actual operation of the completed equipment.

Note: the term 'completed equipment' refers to a third party constructed device which contains or uses the product associated with this manual.

Note's on the symbols used in this manual

At variouse times through out this manual, certain symbols are used to highlight points of information which are intended to ensure the users personal safety and protect the integrity of the equipment. Whenever any of the following symbols are encountered, its associated note must be read and understood. Each of the symbols used are listed with a brief description of its meaning.



R Indicates that the identified danger possibly cause serious physical injury and/or death.



Indicates that the idetified danger possibly cause physical injury or property damage.

Notification of CE marking CE

The following products have shown compliance through direct testing (to the identified standards) and design analysis (forming a technical construction file) to the European Directive for Electromagnetic Compatibility (89/336/EEC)

Products:

Type: Programmable Logic Controller (Open Type equipment, Installation category II) Model: AnS-Series

(Applicable units listed below)

Harmonised	European Standards	IEC Standard	s
Reference No.	Date of Issue	Reference No.	Date of Issue
EN50081-2	1992	IEC801-2	1984
prEN50082-2	1992	IEC801-3	1984
		IEC801-4	1988

AnS-Series Programmable Logic Controllers Range of products:

Models					
A1S32B	A1S65B	A1SI61	A1SX10EU	A1SY18A	A2USCPU
A1S33B	A1S65B-S1	A1SJ51T64	A1SX20EU	A1SY18AEU	A2USCPU-S1
A1S35B	A1S68AD	A1SJ71AP21	A1SX30	A1SY22	A2USCPU-S30
A1S38B	A1S68B	A1SJ71AP21-S3	A1SX40	A1SY28A	A64DAIC
A1S52B	A1S68B-S1	A1SJ71AR21	A1SX40-S1	A1SY28EU	A64DAVC
A1S52B-S1	A1S68DAI	A1SJ71AT21B	A1SX40-S2	A1SY40	A68ADC
A1S55B	A1S68DAV	A1SJ71E71-B2	A1SX41	A1SY41	AD61C
A1S55B-S1	A1S68TD	A1SJ71E71-B5	A1SX41-S2	A1SY42	AJ55TB2-4R
A1S58B	A1SCPU	A1SJ71LP21	A1SX42	A1SY50	AJ55TB2-8R
A1S58B-S1	A1SCPU-S1	A1SJ71PT32-S3	A1SX42-S2	A1SY60E	AJ55TB3-4D
A1S61P	A1SD51S	A1SJ71C24-PRF	A1SX71	A1SY68A	AJ55TB3-8D
A1S61PEU	A1SD61	A1SJ71C24-R2	A1SX80	A1SY71	AJ55TB32-4DR
A1S62DA	A1SD70	A1SJ71C24-R4	A1SX80-S1	A1SY80	AJ55TB32-8DR
A1S62P	A1SD71-S2	A1SJ71UC24-PRF	A1SX80-S2	A1SY81	AX40Y50C
A1S62PEU	A1SD71-S7	A1SJ71UC24-R2	A1SX80-S2	A1SY81	AX80Y14CEU
A1S62RD3	A1SD75-P1	A1SJ71UC24-R4	A1SX81	A2ASCPU	AX80Y80C
A1S62RD4	A1SD75-P2	A1SJ72T25B	A1SX81-S2	A2ASCPU-S1	AX81C
A1S63ADA	A1SD75-P3	A1SJCPU-S3	A1SY10	A2ASCPU-S30	AY15CEU
A1\$63P	A1SG62	A1SP60	A1SY10EU	A2SCPU	AY51C
A1S64AD	A1SH42	A1ST60	A1SY14EU	A2SCPU-S1	AY81C

The products listed above must be used as directed by the associated documentation in order to provide full compliance. Please contact your local Mitsubishi Sales office or distributor for further details.

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1. GENERAL DESCRIPTION

1.1 General Description

This manual describes the specifications and functions of the A1SJCPU, A1SJCPU-S3 programmable controller (hereinafter referred to as the A1SJCPU) and the specifications of the I/O modules, power supply modules, and extension base units used with the A1SJCPU.

The A1SJCPU has a compact building-block type body in which a CPU module, power supply module, and a base unit are built together to form one solid structure. It is characterized by high cost performance.

Since its performance and functions are equal to those of the A1SCPU, the sequence programs (instructions), I/O modules, and special function modules compatible with the A1SCPU are compatible also with the A1SJCPU.

Slim type I/O combination modules (input 32 points, output 24 points) for use exclusively with the A1SJCPU are also available. The three sizes when the slim type is used with the A1SJCPU are 330 mm (W) \times 130 mm (H) \times 82 mm (D) (13.0 inch \times 5.12 inch \times 3.23 inch).

This user's manual refers to the peripheral devices (A6GPP, A6PHP, A6HGP, IBM PC/AT, A7PU, A7PUS, and A8PUE) as abbreviated as mentioned below.

A6GPP, A6PHP, A6HGP, and IBM PC/AT
(started up with SW□IVD-GPPA, MELSEC-MEDOC)
Abbreviated as "GPP function".
A7PU, A7PUS, and A8PUE Abbreviated as "PU".

<Reference manuals>

Refer to the following manuals if necessary:

- ACPU Programming Manual (Fundamentals) (IB 66249) Information such as programming procedures, device names, parameters, classification of programs, and memory area allocation which are necessary for programming are described.
- ACPU Programming Manual (Common Instructions) (IB66250) The methods of use of sequence instructions, basic instructions, application instructions, and microcomputer programs are described.
- AnS Module type I/O User's Mannual (IB66541) The specifications of compact building block type I/O modules are described.

1.2 Differences Between A1SJCPU and A1SJCPU-S3

The differences between A1SJCPU and A1SJCPU-S3 are indicated in the table below.

	Differences	A1SJCPU	A1SJCPU-S3
1	Operating switches	RESET is a pushbutton switch. RUN, STOP, and L.CLR are toggle switches.	RESET, RUN, STOP and L.CLR are incorporated in a single key switch.
1	Front cover	Opens the entire CPU module (power supply part and CPU part).	Opens only part of the CPU module (CPU part).

Table of Difference

A1SJCPU and A1SJCPU-S3 have identical functions and performance.

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2. SYSTEM CONFIGURATION

This section describes the applicable system configuration, cautions on the system configuration, and component devices of the A1SJCPU.

2.1 Overall Configuration

The following figure shows a configuration when the A1SJCPU is used independently.



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To A1SJCPU



2.2 Cautions on System Configurations

The following describes the hardware and software that can be used with the A1SJCPU.

2.2.1 Hardware

(1) I/O module

An A[]N or A[]A building type I/O module can be used by loading the module to the A5[]B/A6[]B extension base.

- (2) Special function module
 - (a) An A[]N or A[]A special function module can be used by loading the module to the A5[]B/A6[]B extension base.
 - (b) The following special function modules can be used up to the number of modules specified herein.

AD51 (S3) AD51FD AJ71C22 AJ71C24 (S3/S6/S8) AJ71P41	AD51H (S3) AD57G (S3) AJ71UC24 AJ71E71(S3)	Up to two modules can be used			
A1SJ71E71(S3) A1SJ71UC24-R2 (PRF/R4)					
AI61 (S1)		Only one module can be used.			
A1SI61					
AJ71AP21 AJ71LP21 AJ71AT21B	AJ71AR21 AJ71BR11				
A1SJ71AP21 A1SJ71LP21 A1SJ71T21B	A1SJ71AR21 A1SJ71BR11	Only one module can be used			



- (3) Peripheral device
 - (a) Use an A6WU P-ROM writer of which the version is "E" or after.
 - (b) The A6WU P-ROM writer unit cannot be directly installed (add-on type) to the A1SJCPU.
 It can be connected as a hand-held unit to the A1SJCPU with a cable.
 - (c) Only the A7PUS programming unit (among A7PU, A7PUS, and A8PUE) can be directly installed (add-on type) to the A1SJCPU. Other types of units (A7PU and A8PUE) are connected as hand-held units to the A1SJCPU with a cable.

(4) EPROM memory cassette ROM partition

Partitioning the ROM in the A1SMCA-8KP EPROM with an A6GPP (SW4GP-GPPAEE)/A6WU requires an A6WA-28P memory write adapter (option).

- (5) Write at RUN when an operation is done with EEPROM (equipped with A1SMCA-2KE/A1SMCA-8KE).
 - (a) When an operation is done using the EEPROM, writing at RUN gives to the peripheral devices the following messages:
 - When the SW3GP-GPPA is used: "PC COMMUNICATIONS ERROR ERROR CODE = 17" is displayed;
 - When the A7PU is used: "PC NOT RESPOND" is displayed.
 - (b) It is not possible to write a program from a computer link module or a peripheral device connected to another station in a MELSECNET system.
 Write programs from a peripheral device connected to the BS-422

Write programs from a peripheral device connected to the RS-422 interface of the A1SJCPU.

(c) When writing a program to an A1SMCA-2KE, set the main sequence program capacity in the parameters to 2K steps or less. If you attempt to write a program with the main sequence program capacity set to 3K steps or greater, the program will not run correctly. Mismatches will also occur in verification between the A1SJCPU and a peripheral device.

2.2.2 Software packages

(1) System startup software and module name specification at startup

When using any of the software packages for programming or monitoring on-line, "A2", "A1S" or "A0J2H" should be set for the PC type selection. If the EPROM write facility is required, then this should be carried out off-line and either "A0J2H" or "A1S" should be selected as the PC type if the software package has these selections. In the event that the software package does not have any of these two selections, then the EPROM write facility is not available. Please refer to the table below as a reference guide to the software packages available and the correct PC type selection for the A1SJCPU.

Peripheral	Software	СР	[•] U Туре	D
device	package	On-line	Off-line	hemarks
ACDUD	SW3GP-GPPAEE	A2		EPROM write not possible.
AOFHP	SW4GP-GPPAEE	A0J2H	A0J2H/A1S	Set "A1S" when software of version "R" or later.
	SW3-GPPAEE	A2		EPPOM write pet peopible
A6GPP	SW3GP-GPPAEE	R2	-	
SW4GP-GPPAEE		A0J2H	A0J2H/A1S	Set "A1S" when software of version "R" or later.
A6HGP	SW3-HGPAEE	A2		EPROM write not possible.
	SW0IX-GPPAE	A1S	A0J2H/A1S	
IBM PC/AT	MEDOC	A2	_	EPPOM with not accelible
	MELSEC-MEDOC	A1S		
A6WU		A1S		 "A1S" is displayed when the system is started up. (Software version "E" or later) Cannot be used. (Software version "D" or before.)
				An add-on (direct) installment is not possible.
A7PU		A2	_	 "A2" is displayed when the system is started up. (Software version "E" or before) Cannot be used. (Software version "F" or later)
				An add-on (direct) installment is not possible.
A7PUS, A8F	VE	A1S	—	"A1S" is displayed the system is started up.

POINTS

- (1) When an A6GPP, A6HGP, or A6PHP is used, use an SW3-GPPAEE, SW3-HGPAEE, SW3GP-GPPAEE, or SW4GP-GPPAEE as the system startup software. Other old software packages cannot be applied
 - Other old software packages cannot be applied.
- (2) Specifying the PC CPU name using the above-mentioned devices allows more than 256 I/O signals input from the keyboard. However, those signals cannot be used in the A1SJCPU.

(2) Utility package

Applicable utility packages are shown below.

- SW0GHP-UTLPC-FN1
- SW0GHP-UTLP-FD1
- SW1GP-AD57P
- SW0GHP-UTLPC-PID
- SW0-AD57PSWOC-UTLP-FID

SW0GHP-UTLPC-FN0

- SWOC-UTLP-FNO
- (a) Select "A2CPU" when an SW0GHP-UTLPC-FN1 or SW0GHP-UTLP-FD1 is started up.
- (b) If both an SW1GP-AD57P and another utility package combined are used, specify "AD57P-COM" as the file name.

2.3 System Equipment

The following table shows the system equipment consisting of various modules and devices which can be used.

Module Model		Description		Number of Inputs/	Current Consumption		Remarks	* Approved Standard
	• • • • • • • • • • • • • • • • • • •		Outputs	5 VDC(Å)	24 VDC(A)		Stanuaro	
CPU	A1SJCPU	See the "Performance Specifications	in Section 4				RAM	
module	A1SJCPU -S3	(Number of I/O points : 256, memory Kbytes)	capacity : 32	-	0.40		memory embedded	
	A1S61P	5 VDC, 5 A	Input 100/200 VAC				Londad	UL/CSA
Power	A1S61PEU		Input 200 VAC				the slot for power	
supply module	A1S62P	5 VDC, 3 A/24 VDC 0 6A	Input 100/200 VAC	—	-	-	supply for main base or extension	UL/CSA
	A1S62PEU		Input 200 VAC				base	
	A1S63P	5 VDC, 5 A	Input 24 VDC					
	A1SX10	16-input 100 VAC input module		16 [16 inputs]	0.05			UL/CSA
	A1SX10EU	16-input 100 VAC input module		16 [16 inputs]	0.05			
	A1SX20	16-input 200 VAC input module		16 [16 inputs]	0.05			
	A1SX20EU	16-input 200 VAC input module		16 [16 inputs]	0.05			
	A1SX30	16-input 12/24 VDC, 12/24 VAC inpu	16 [16 inputs]	0.05				
	A1SX40	16-input 12/24 VDC input module		16 [16 inputs]	0.05	_		UL/CSA
	A1SX40- S1	16-Input 24 VDC input module	16 [16 inputs]	0.05				
	A1SX40- S2	16-input 24 VDC input module		16 [16 inputs]	0.05			
Input	A1SX41	32-input 12/24 VDC input module		32 [32 inputs]	0.08	-		UL/CSA
module	A1SX41- S1	32-input 24 VDC input module		32 [32 inputs]	0,12			
	A1SX41- S2	32-input 24 VDC input module		32 [32 inputs]	0.08			
	A1SX42	64-input 12/24 VDC input module		64 [64 inputs]	0.09			UL/CSA
	A1SX42- S1	64-input 24 VDC input module		64 [64 inputs]	0.16]	
	A1SX42- S2	64-Input 24 VDC input module		64 [64 inputs]	0.09]	
	A1SX71	32-input 5/12 VDC input module		32 [32 inputs]	0.075]	
	A1SX80	16-input 12/24 VDC sink/source input	ut module	16 [16 inputs]	0.05	_		UL/CSA
	A1SX80- S1	16-input 24 VDC sink/source input n	nodule	16 [16 inputs]	0.05			
	A1SX80- S2	16-input 24 VDC input module		16 [16 inputs]	0.05			
	A1SX81	32-input 12/24 VDC sink/source input	ut module	32 [32 inputs]	0.08			UL/CSA
	A1SX81- S2	32-input 24 VDC input module		32 [32 inputs]	0.08	_		

* : Class 2 power supply specified by the UL/CSA Standard must be used.

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Module	Model	Model Description		Current Consumption		Remarks	* Approved Standard
			Outputs	5 VDC(A)	24 VDC(A)		
	A1SY10	16-output relay contact output module (2 A)	16 [16 outputs]	0.12	0.09		UL/CSA
	A1SY10EU	16-output relay contact output module (2 A)	16 [16 outputs]	0.12	0.09		
-	A1SY14EU	12-point relay contact output module (2 A)	16 [16 outputs]	0.12	0.1		
	A1SY18A	8-point relay contact output module (2 A) All points independent	16 [16 outputs]	0.24	0.075		
	A1SY18 AEU	8-point relay contact output module (2 A) All points independent	16 [16 outputs]	0.24	0.75		
	A1SY22	16-output triac output module (0.6 A)	16 [16 outputs]	0.27	(200 VAC) 0.004		UL/CSA
	A1SY28A	8-point triac output module (1 A) All points independent	16 [16 outputs]	0.11	_		
	A1SY28EU	8-point triac output module (0.6 A)	16 [16 outputs]	0.27			
	A1SY40	16-output 12/24 VDC transistor output module (0.1 A) sink type	16 [16 outputs]	0.27	0.016		
Output module	A1SY41	32-output 12/24 VDC transistor output module (0.1 A) sink type	32 [32 outputs]	0.50	0.016		
	A1SY42	64-output 12/24 VDC transistor output module (0 1 A) sink type	64 [64 outputs]	0.93	0.016		
	A1SY50	16-output 12/24 VDC transistor output module (0.5 A) sink type	16 [16 outputs]	0.12	0.12		
	A1SY60	16-output 24 VDC transistor output module (2 A) sink type	16 [16 outputs]	0.12	0.015		
	A1SY60E	16-output 12 VDC transistor output module (1 A) source type	16 [16 outputs]	0.20	0.01		
	A1SY68A	8-point 5/12/24/48 VDC transister output module sink/source typeAll points independent	16 [16 outputs	0.13			1
	A1SY71	32-output 5/12 VDC transistor output module (0 016 A) sink type	32 [32 outputs	0.40	0.15		
	A1SY80	16-output 12/24 VDC transistor output module (0.8 A) source type	16 [16 outputs	0.12	0.04		
	A1SY81	32-output 12/24 VDC transistor output module (0.1 A) source type	32 [32 outputs	0 50	0.016		
input/	A1SH42	32-input 12/24 VDC input module 32-output 12/24 VDC transistor output module (0.1 A) sink type	32 [32 inputs/ outputs]	0.50	0.008		
output combi- nation	A1SX 48Y18	8-input 24 VDC input module (sink type) 8-output relay contact output module (2 A)	16 [8 inputs/ outputs]	0.085	0.045		
module	A1SX 48Y58	8-input 24 VDC input module (sink type) 8-output 12/24 VDC transistor output module (0.5 A)	16 [8 inputs/ outputs]	0.06	0.06		
i/O combi-	A1SJ- 56DR	32-point 24 VDC input (sink type)24-point 24 VDC/240 VAC relay contact output (2 A)	128 points Slot 0: 64 outputs	0.22	0.14		
nation module	A1SJ-56D1	32-point 24 VDC input (sink type) 24-point 24 VDC transistor output (0.5 A) sink type	Slot 1 to slot 4: Vacant 16 points	j 0.22	_		
Dynamic input module	A1S42X	16-, 32-, 48- and 64-point 12/24 VDC dynamic input module	Number o set points (Inputs []	f ; 0.08			
Dynamic output module	A1S42Y	16-, 32-, 48-, and 64-point 12/24 VDC dynamic output module	Number o set points (Outputs	f 0.10	0.008		

* : Class 2 power supply specified by the UL/CSA Standard must be used.

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ltem	Model	Description		Number of Inputs/	Cur Consu	rent mption	Remarks	* Approved
		2000.101		Output	5 VDC(A)	12 VDC(A)		Stangard
Blank cover	A1SG60	Keeps unused slots fro	om dust	16 [empty]	-			UL/CSA
Dummy module	A1SG62	16-, 32-, 48-, and 64-ir selectable module	nput "	Number of set points ([] inputs)	_	_		
	A6CON1	Soldered joint type	Sink type					
	A6CON1E	Soldered Joint type	Source type					
40-pin	A6CON2	Solderless	Sink type	_		_		UL/CSA
connector	A6CON2E	attachment type	Source type					
	A6CON3	Brossed joint type	Sink type					
	A6CON3E	Pressed joint type	Source type					
	A1SD70	Analog output, 1 axis		48 (first half	03	_		
Positioning	A1SD71-S2	Pulse output, 2 axes		vacant 16 points, second	08			
module	A1SD71-S7	Pulse output, 2 axes (used)	MPG can be	half special 32 points)	0.8	-		
MELSECNET/ MINI-S3 data link module	A1SJ71PT32- S3	Master module for fiber-optic/ twisted-wire pair cable		32/45 (special 32 points/special 48 points)	0 35	_	The number of occupying points in I/O exclusive mode: 32, in extension mode: 48	
Analog I/O module	A1S63ADA	Analog Input. 2 chann Analog output: 1 chan	els nel	32 (speical 32 points)	0.8	_		
Pulse catch module	A1SP60	Pulse input module wi time (Pulse : min. 0.5 msec inputs	th short ON c) 16-point	16 [16 outputs]	, 0.055	-		
Analog timer module	A1ST60	For changing timer se 1.0 sec, 1 to 10 sec, 1 60 to 600 sec) by usir adjustment knobs. Analog timer 8 points	t values(0.1 to 10 to 60 sec, ng volume	16 [16 outputs]	0.055	_		
Interruption module	A1SI61	Interruption module for program execution de (Input for interruption	or interruption signation : 16 points)	32 [Special 32- point]	0.057	_		
High-speed counter module	A1SD61	32-bit signed binary 50 KBPS, 1 channel		32 [Special 32- point]	0.35			
A-D converter module	A1S64AD	4 to 20 mA / 0 to 10 V Analog 4 channels	/	32 [Special 32- point]	0.4	_]	
Temperature- digital	A1S62RD3	For connecting a Pt10 Temperature input: 2	00 (3-lead type) channels	32 [Special 32- point]	0.54	-		UL/CSA
converter module	A1S62RD4	For connecting a Pt10 Temperature input: 2	00 (4-lead type) channels	32 [Special 32- point]	0.44	-		
D-A converter module	A1S62DA	4 to 20 mA / 0 to 10 V Analog output: 2 char	/ nnels	32 [Special 32 point]	0.8	_		

* : Class 2 power supply specified by the UL/CSA Standard must be used.

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ltem Model		Model	Description	Number of Inputs/	Cur Consu	rent Imption	Remarks	* Approved Standard
				Output	5 VDC(A)	12 VDC(A)		Fundard
		A1SJ71UC24- R2	Computer link function RS-232C: 1 channel	32 [Special 32- point]	0.1	-		UL/CSA
Computer link module	¢	A1SJ71UC24- PRF	Computer link and printer functions RS-232C: 1 channel	32 [Special 32- point]	0.1	-		
		A1SJ71UC24- R4	Computer link and multidrop link functions RS-422/485: 1 channel	32 [Special 32- point]	0.1			~
		A1SJ71AP21	For master or local station of MELSECNET (II) optical data link	32 [Special 32- point]	0.5	-		
module		A1SJ71AR21	For master or local station of MELSECNET (II) coaxial data link	32 [Special 32- point]	0.9	-		
MELSECNET /B data link module		A1SJ71T21B	For master or local station of MELSECNET/B data link system	32 [Special 32- point]	0.66	_		UL/CSA
MELSECNET		A1SJ71LP21	For normal station of MELSECNET/10 Optical network	32 [Special 32- point]	0.65			
module		A1SJ71BR11	For normal station of MELSECNET/10 coaxial network	32 [Special 32- point]	0.8	—		¢
		A1S52B(S1)	Up to two I/O modules can be loaded.	_	_	-	Power supply module	
		A1S55B(S1)	Up to five I/O modules can be loaded.		-	_	loaded. (Power is	UL/CSA (except for S1 type)
Extension base unit		A1S58B(S1)	Up to eight I/O modules can be loaded.	_	_	-	from the main base module.)	
		A1S65B(S1)	Up to five I/O modules can be Need powe modules can be Need powe modules can be		Needs a			
		A1S68B(S1)			module.			
		A1SC01B	55 mm (2.17 inch) long flat cable	_	-	-	For extension on the right side	UL/CSA
		A1SC03B	330 mm (11.8 inch) long	-	-	_		
Extension		A1SC07B	700 mm (27.6 inch) long			_	Extension	
ble	a-	A1SC12B	1200 mm (47.24 inch) long	-	-		connection	
		A1SC30B	3000 mm (118.11 lnch) long	_	-	-	cable	UDUGA
		A1SC60B	6000 mm (236.22 inch) long		_	-		
		A1SC05NB	450 mm (17.72 inch) long				A[]N, A[]A	UL/CSA
		A1SC07NB	700 mm (27.6 inch) long] –	-	-	base cable	
	EPROM	A1SMCA-8KP	8K steps equipped with ROM (directly)	-		_	Needs a memory write adapter.	
Memory cassette	WO	A1SMCA-2KE	2K steps equipped with 4K EROM (directly)	-	_	-	Direct write/read	UL/CSA
EEPRO	EEPR	A1SMCA-8KE	8K steps equipped with 16K ROM (directly)	_	-	-	peripheral devices can be done.	

* : Class 2 power supply specified by the UL/CSA Standard must be used.

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2. SYSTEM CONFIGURATION

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ltem	Model	Description	Number of Inputs/	Cur Consu	rent Imption	Remarks	Approved
			Output	5 VDC(A)	12 VDC(A)		otandard
Memory write adapter	A6WA-28P	Used for memory cassette connector/EPROM 28-pin.	-		_	Used to partition ROM in EPROM memory cassette.	UL/CSA
Battery	A6BAT	IC-RAM memory backup	_	_	_		

ltem	Model	Description	Applicable Model
	АбТВХҮЗб	For sink type input module and sink type output module (standard type)	A1SX41(S2), A1SX42(S2), A1SY41, A1SY42, A1SH42
	A6TBXY54	For sink type input module and sink type output module (2-wire type)	AX42(S1), AY42(S1/S3/S4), AH42
Connector/ terminal block	A6TBX70	For sink type input module (3-wire type)	A1SX41(S2), A1SX42(S2), A1SH42, AX42(S1), AH42
conversion mod- ule	A6TBX36-E	For source type input module (standard type)	A1SX81(S2), AX82
	A6TBY36-E	For source type output module (standard type)	A1SY81, AY82EP
	A6TBX54-E	For source type input module (2-wire type)	A1SX81(S2), AX82
	A6TBY54-E	For source type output module (2-wire type)	A1SY81, AY82EP
	A6TBX70-E	For source type input module (3-wire type)	A1S81(S2), AX82
	AC05TB	0.5 m (1.64 ft) for source module	
	AC10TB	1 m (3.28 ft) for source module	A6TBXY36
	AC20TB	2 m (6.56 ft) for source moduel	A6TBXY54
Cable for	AC30TB	3 m (9.84 ft) for source module	A6TBX70
connector/ terminal block	AC50TB	5 m (16.4 ft) for source module	
conversion mod- ule	AC05TB-E	0.5 m (1 64 ft) for source module	A6TBX36-E
	AC10TB-E	1 m (3.28 ft) for source module	А6ТВҮЗ6-Е
	AC20TB-E	2 m (6.56 ft) for source module	A6TBX54-E
	AC30TB-E	3 m (9.84 ft) for source module	A6TBY54-E
	AC50TB-E	5 m (16.4 ft) for source module	A6TBX70-E

REMARK

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I/O cables with connectors for I/O modules of 40-pin connector specifications (A1SX41, A1SX42, A1SY41, A1SY42, etc.) or 37-pin D-sub connector specifications (A1SX81, A1SY81) are available.

Consult the nearest Mitsubishi representative for the I/O cables with connectors.

• Peripheral devices

ltem	Module		Remarks			
		A6PHP				
Plasma bandy		• SW[]GP-GPPAEE	A-series GPP function system disk			
graphic program-	A6PHP-SET	• SW[]GP-GPPKEE	K-series GPP function system disk			
		• SW0-GPPU User da	ısk (2DD)			
		• AC30R4 RS-422 ca	uble (3 m (9 84 ft) length)			
		A6GPP				
		• SW[]GP-GPPAEE	A-series GPP function system disk			
Intelligent GPP	A6GPP-SET	• SW[]GP-GPPAEE	K-series GPP function system disk			
		• SW0-GPPU User d	isk (2DD)			
		• AC30R4 RS-422 ca	able (3 m (9 84 ft) length)			
		• A6HGP				
Hee du su d		• SW[]GP-HGPAEE.	A-series GPP function system disk			
nanoy graphic programmer	A6HGP-SET	• SW[]GP-HGPKEE	K-series GPP function system disk			
		• SW0-GPPU User d	lisk (2DD)			
		• AC30R4 RS-422 ca	able (3 m (9 84 ft) length)			
Composite video cable	AC10MD	Connects between	A6GPP and monitor display (1 m (3 28 ft) length)			
RS-422 cable	AC30R4	3 m (9 84 ft) length				
HUMAZ CADIO	AC300R4	30 m (98 4 ft) length				
المرام موموا	SW0-GPPU	200	Lised for storing liser program (2.5 met. formation			
USUT CISK	SW0S-USER	2HD	See is storing user program (s s inch, formatted)			
Cleaning disk	SW0-FDC	Applicable to A6GPP/A6PHP	Used for cleaning disk drive			
Drosse	A7PU	Connected directly t to read and write a p The product package cassette recorder	o the CPU with an RS-422 cable (AC30R4, AC300R4) srogram. Provided with an MT function 9 includes a cable used to connect to an audio			
r rogramming unit	A7PUS	Connected directly to and wirte a program	the CPU with an RS-422 cable (AC30R4-PUS) to read			
	A8PUE	Connected directly to AC20R4-A8PU) to rea	the CPU with an RS-422 cable (AC30R4-PUS, id and wirte a program			
	AC30R4 AC300R4	Used to connect the A Length 3 m/30 m (9 8	17PU to the CPU. 14/98 4 ft)			
RS-422 cable	AC30R4-PUS	Used to connect the A Length 3 m (9 84 ft)	17PUS or A8PUE to the CPU			
	AC20R4-A8PU	Used to connect the A Length 2 m (6 56 ft)	ASPUE to the CPU.			
P-ROM writer	AGWU	 Used for writing a program from ROM 	program in CPU/A6PHP to ROM, or for reading a CPU			
		Connected to CPU	A6PHP using an AC30R4/AC03WU cable			
RS-422 cable	AC30R4, AC300R4	Connects between CF	2U and A6WU. 3 m/30 m (9.84/98 4 ft) length			
	AC03WU	Connects between CF	2U and A6WU 0 3 m (0 98 ft) length			

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2.4 Overview of System Configuration

This section describes the system configuration, numbers of I/O points, I/O allocations, etc., for a stand-alone A1SJCPU system.



3. GENERAL SPECIFICATIONS

3. GENERAL SPECIFICATIONS

3.1 General Specifications

Table 3.1 General Specifications

ltem	Specifications						
Operating ambient temperature	0 to 55°C						
Storage ambient temperature	–20 to 75°C						
Operating ambient humidity	10 to 90%RH, no dewing						
Storage ambient humidity	10 to 90%RH, no dewing						
		For intermittent vi	bration				
		Frequency	Acceleration	Amplitude	Sweep Count		
	Conforms to * JIS B 3501, IEC 1131-2	10 to 57Hz		0.075mm (0.003 inch)			
Vibration		57 to 150Hz	9.8 m/s ² {1G}		10 times		
		For continuous vi	each in X, Y and Z				
		Frequency	Acceleration	Amplitude	directions (80 minutes)		
		10 to 57Hz		0.035mm (0.001 inch)			
		57 to 150Hz	4.9 m/s ² {0.5G}				
Shock resistance	Conforms to JIS (147 m/s ² (15G)	B 3501, IEC 1131-2 × 3 times in 3 direction	ons)				
Operating atomosphere	To be free of cor	rosive gases					
Altitude	Up to 2,000 m						
Insulation site	Inside a control c	Inside a control cabinet					
Overvoltage category	11 or lower	11 or lower					
Degree of contamination	No greater than 2	2		_			

REMARK

* JIS: Japanese Industrial Standard

4. A1SJCPU

4.1 Performance Specifications

(1) Performance specifications of A1SJCPU unit

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Table 4.1 Performance Specifications of A1SJCPU unit

Item	Туре	A1SJ	ICPU			
Control system		Repeated operation (using stored program)				
I/O control meti	nod	Refresh mode/Direct mode selectable				
Programming la	inguage	Language dedicated to sequence contro and logic symbolic language, MELSAP-I	I (Combined use of relay symbol type I(SFC)			
	Sequence instructions	26				
Number of instructions	Basic instructions	31				
	Application instructions	104				
Processing spee instructtion) (μ s	ed (sequence sec/step)	Direct : 1.0 to 2.3 Refresh : 1.0				
I/O points		256				
Watchdog timei	r (WDT)(msec)	10 to 2000				
Memory capaci	ty *1	32K byte (RAM)				
Program capacity		Main sequence program + main microcomputer program = 8K steps max. Internal microcomputer program can be set to 7K steps (14K bytes) max. (subsequence program not available).				
Internal relay (M) (point)		1000 (M0 to 999)				
Latch relay (L)	(point)	1048 (L1000 to 2047)The number of M + L + S = 200 (Defaults to no value)(set in parameters)				
Number of step	relays (S) (point)					
Link relay (B) (point)	1024 (B0 to 3FF)				
	Number of points	256				
Timer (T)	Specifications	100 msec timer: setting time 0.1 to 310 msec timer: setting timer 0.01 to100 msec: depending on settinretentive timer(setting time 0.1 to	276.7 sec (T0 to 199) 327.67 sec (T200 to 255) g 3276.7 sec)			
	Number of points	256				
Counter (C)	Specifications	Normal counter : Setting ran Interrupt program counter : Setting ran Counter to be used	nge 1 to 32767 (C0 to 255) Set in nge 1 to 32767 para- in interrupt program meters			
Data register ([D) (points)	1024 (D0 to D1023)				
Link register (V	V) (points)	1024 (W0 to W3FF)				
Annunciator (F)) (points)	256 (F0 to F255)				
File register (R) (points)	Max. 4096 (R0 to R4095)				
Accumulator (A) (points)		2 (A0, A1)				
Index register (V,Z) (points)		2 (V,Z)				
Pointer (P) (poi	ints)	256 (P0 to P255)				
Interrupt pointer (I) (points)		32 (10 to 131)				
Special relay (I	M) (points)	256 (M9000 to M9255)				

Table 4.1 Performance Specifications of A1SJCPU unit (Continued)

Type		A1SJCPU	
Special register (D) (points)	256 (D9000 to D9255)		
Comment (points) *2	Max. 1600 (Specify in batches of 64 points)		
Self-diagnostic functions	Watchdog error monitor, Memory error detection, CPU error detection, I/O error detection, battery error detection, etc.		
Operation mode at the time of error	STOP/CONTINUE		
STOP \rightarrow RUN output mode	Output data at time of STOP restored/data output after operation execution		
	Year, Month, Date, Hour, Minutes, Seconds, Day (Leap year automatically detected.) Clock accuracy		
Clock function	Ambient Temperature (°C)	Accuracy (Weekly difference, sec)	
	+ 55	within ± 8	
	0	within ± 7	
Allowable momentary power failure time	20 msec		
Current consumption (5 VDC)	0.4 A		
Weight (kg) (lb)	1.00 (2.19)		

*1 The total memory used for parameters, T/C set values, program capacity, file registers, number of comments, sampling trace, and status latch is 32K bytes. Memory capacity is fixed to 32 Kbytes. No expansion memory is available. Section 4.9.1 gives how to calculate the memory capacity.

*2 Up to 1600 comments can be stored in the A1SJCPU. In the GPP/PHP/HGP, 4032 comments can be written.

(2) Performance specifications for the A1SJCPU built-in power supply.

1.1.5

Table 4.2 Performance Specifications for the A1SJCPU Built-In Power Supply

Item Type	A1SJCPU
Input power supply	100-120 VAC ± 18 % (85 to 132 VAC) 200-240 VAC ± 18 % (170 to 264 VAC)
Input frequency	50/60 Hz ± 3 Hz
Input maximum apparent power	100 VA
Rush current	20 A 8 msec or less
Rated output	5 VDC 3 A
Overcurrent protection *1	3.3 A or over
Overvoltage protection	Not provided
Efficiency	65 % or over
Power supply indication	POWER LED indicator
Terminal screw size	M3.5 X 8
Applicable cable size	0.3 to 2 mm ²
Applicable solderless terminal	1.25-3.5, V1.25-YS3A, 2-3.5, 2-YS3A, V1.25-M3, V2-YS3A, V2-S3, V2-YS3A
Allowable momentary power failure	20 msec or less (100 VAC or over)

POINT

*1: Overcurrent protection

When a current larger than the specification value flows through the 5 VDC circuit, the overcurrent protection device cuts off the circuit and stops the system.

The POWER LED turns off or lights dimly due to the voltage drop. If this device operated, remove causes of failures such as current capacity shortage and short-circuit and restart the system.

4.1.1 A1SJCPU operation processing

This section explains the operation processing which takes place from the time the A1SJCPU power ON until the sequence program is executed. A1SJCPU processing is generally divided into the following four types:

(1) Initial processing

This is the pre-processing for executing sequence operations. Initial processing is executed once at start up or reset.

- (a) Initialize by resetting the I/O module.
- (b) Initialize the data memory's unset latch range (bit device turned OFF, word device set to 0).
- (c) I/O module addresses are automatically assigned in accordance with the I/O module number and where the module is installed in the extension base unit.
- (d) Automatic diagnostic check of parameter settings and operation circuits is executed (see Section 4.1.4).
- (e) If the A1SJCPU is used in the master station of an MELSECNET/B, data linking begins after setting the link parameter data to the data link module.
- (2) I/O module refresh processing

If the refresh mode for both input and output is set by the I/O control switch, the I/O module is refreshed. (The ACPU programming manual (Fundamentals) gives details.)

(3) Sequence program operation processing

The sequence program written to the PC CPU is executed from step 0 to the END instruction.

(4) END processing

When the sequence program operation processing has been completed, the sequence program is returned to step 0.

- (a) Self-diagnosis checks for blown fuses, I/O module verification, low battery voltage, etc. are executed (see Section 4.1.4).
- (b) T/C present values are updated and contacts are turned ON/OFF. (The ACPU Programming Manual (Fundamentals) gives details.)
- (c) Data is read from computer link modules (A1SJ71C24-R2, AJ71C24(S3), AD51(S3), etc.) and PC CPU and computer link module data is replaced when the write instruction is executed.
- (d) Link refresh processing is executed when the link refresh request is given from the MELSECNET/B data link.

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Fig. 4.1 A1SJCPU Operation Processing

4.1.2 Operation processing in the RUN, STOP, PAUSE states

The PC CPU can be operated in the RUN, STOP and PAUSE states as described below.

(1) RUN operation processing

RUN indicates repeated operations of the sequence program from step 0 to the END (FEND) instruction.

When the CPU is set to RUN, the output status at the time of STOP is provided in accordance with the STOP \rightarrow RUN output mode parameter setting.

The PC CPU needs processing time before starting a sequence program operation. It requires two to three seconds after a power ON or reset, and one to three seconds after the mode is changed from STOP to RUN.

(2) STOP operation processing

STOP indicates a stop of the sequence program operation by executing a STOP instruction or using the remote STOP.

When the CPU is set to STOP, the output status is saved and all outputs are switched OFF. Data other than the outputs (Y) is retained.

(3) PAUSE operation processing

PAUSE indicates a stop of the sequence program operation with the output and data memory states retained.

POINT

The following processing is executed whether or not the A1SJCPU is in the RUN, STOP, or PAUSE state:

- Refresh processing of I/O module when the refresh mode is set,
- Data communications with computer link modules,
- Link refresh processing.

Therefore, the following operations are possible even when the A1SJCPU is set in the STOP or PAUSE state:

- Monitoring I/O status and testing using a peripheral device,
- Read/write with a computer link module, and
- Communications with other stations in the MELSECNET/B.

4.1.3 Operation processing when a momentary power failure occurs

When voltage below the specified range is supplied to the power supply module, the A1SJCPU detects a momentary power failure.

If the A1SJCPU detects a momentary power failure for 20 msec (the allowable momentary power failure period) of less, the following operations are executed:

- (1) Momentary power failure within 20 msec
 - (a) The operation processing is stopped with the output retained.
 - (b) The operation processing is resumed when the normal status is restored.
 - (c) The watchdog timer (WDT) keeps timing while the operation is stopped.

For example, if a momentary power failure of 20 msec occurs when the scan time is 190 msec, a watchdog timer error (200 msec) occurs.

(2) Momentary power failure over 20 msec

The A1SJCPU will return to the initial start status. The necessary operations are the same as when the CPU power is turned ON or when the CPU is reset.



Fig. 4.2 Operation Processing When a Momentary Power Failure Occurs
4.1.4 Self-diagnosis

The self-diagnosis function permits the A1SJCPU to detect its own errors.

Self-diagnosis is carried out when the PC power supply is turned ON and if an error occurs while the PC is in the RUN state. If the A1SJCPU detects an error, it displays an error message and stops to prevent a faulty PC operation.

The A1SJCPU may operate in one of two modes when an error is detected by the self-diagnosis function. In the stop mode, the PC operation is stopped when the error is detected; in the continuous mode, the PC operation is continued. In the continuous mode, however, parameters can be set to cause the operation to stop if specified errors occur.

When an error occurs, the error occurrence and the error content are stored in special relay (M) or special register (D). In the continuous mode, in particular, the program should read the details of the error and take appropriate action to prevent faulty PC and machine operations.

Operation stops and all outputs (Y) are turned immediately OFF after the self-diagnosis function detects an error which stops the PC operation.

If the self-diagnosis function detects an error during which the PC operation continues, the part of the program where the error was detected is skipped and the rest of the program is executed.

If an I/O module verify error is detected, the operation is continued with the I/O addresses at the time the error occurred.

Explanations of the errors detected by the self-diagnosis function are given in Table 4.3.

REMARKS

- (1) In Table 4.3, in the I/O error I/O module verify, fuse blown, special-function module error, and operation check error diagnoses, the CPU status can be selected between stop and run; and the RUN LED status between flashing and ON by using peripheral devices.
- (2) The LED Display Message column in Table 4.3 lists messages displayed by the peripheral devices' PC diagnosis.

Table 4.3 Self-Diagnosis

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Diagnosis	Diagnosis Timing	CPU Status	"RUN" LED Status	LED Display Message
Memory error Instruction code check	When the corresponding instruction is executed			INSTRUCT. CODE ERR
Parameter setting check	When power is switched ON or a reset is done When switched from STOP/PAUSE to RUN			PARAMETER ERROR
No END instruction	When M9056 or M9057 is switched ON When switched from STOP/PAUSE to RUN	Cto-	Flooping	MISSING END INS.
Instruction execution disable	When CJ, SCJ, JMP, CALL(P), FOR and NEXT instruction is executed When switched from STOP/PAUSE to RUN	ыор	riasning	CAN'T EXECUTE (P)
Format (CHK instruction) check	When switched from STOP/PAUSE to RUN			CHK FORMAT ERR.
Instruction execution disable	When interrupt occurs When switched from STOP/PAUSE to RUN			CAN'T EXECUTE (I)
CPU error RAM check	When power is switched ON or a reset is done When M9084 is switched ON during STOP			RAM ERROR
Operation circuit check	When power is switched ON or a reset is done			OPE CIRCUIT ERR.
Watchdog error check	When an END instruction is executed	Stop	Flashing	WDT ERROR
END instruction not executed	When an END instruction is executed			END NOT EXECUTE
Endless loop execution	At any time			WDT ERROR
I/O error I/O module verify	When an END instruction is executed (Not checked when M9084 is on)	Stop	Flash- ing	UNIT VERIFY ERR
Fuse blown	When an END instruction is executed (not checked when M9084 is ON)	Run	ON	FUSE BREAK OFF.
Special function mod- ule error Control bus check	When a FROM, TO instruction is executed			CONTROL-BUS ERR
Special-function module error	When a FROM, TO instruction is executed			SP. UNIT DOWN
Link module error	When power is switched ON or a reset is done When switched from STOP/PAUSE to RUN	Stop	Flashing	LINK UNIT ERROR
I/O interruption error	When an interruption occurs			1/O INT ERROR
Special-function module assignment	When power is switched ON or a reset is done. When switched from STOP/PAUSE to RUN			SP. UNIT LAY. ERR.
Special-function module error	When a FROM, TO instruction is executed	Stop Run	Flash- ing ON	SP UNIT ERROR
Link parameter error	When power is switched ON or a reset is done. Run ON LINK When switched from STOP/PAUSE to RUN Run ON LINK		LINK PARA ERROR	
Battery error Battery low	At any time (not checked When M9084 is ON)	Run	ON	BATTERY ERROR
Operation check error	neck error When the corresponding instruction is executed OPE Run ON		OPERATION ERROR	

4.1.5 Devices

A device is any contact, coil, or timer used in PC program operations.

A1SJCPU devices and their range of use are shown below. The items marked "*" can be used by setting parameters for peripheral devices or by changing their range of use.

Set parameters which are compatible with the system to be used and its program. Section 4.1.6 gives details about parameter settings.

	Device	Application Range (Number of points)		Explanation
x	Input	X, Y0 to FF		Provides the PC command and data from an external device, e.g. pushbutton, select switch, limit switch, digital switch.
Y	Output		(5)	Provides the program control result to an external device, e.g. solenoid, magnetic switch, signal light, digital display.
Z	Special relay	M9000 to M9255	(256 points)	Redefined auxiliary relay for special purposes and for use in the PC.
м	Internal relay*	M0 to M999 (1000 points)		Auxiliary relay in the PC which cannot be directly output.
L	Latch relay*	L1000 to L2047 (1048 points)	Number of M + L + S = 2048	Auxiliary relay in the PC which cannot be directly output. Backed up during power failure.
s	Step relay*	Can be used by setting the parameter (0)		Used in the same manner as an internal relay (M), e.g. as a relay indicating the stage number of a step-by-step process operation program.
в	Link relay	B0 to B3FF (1024	points)	Internal relay for data link which cannot be output. May be used as an internal relay if not set for link initial data.
F	Annunciator	F0 to F255 (256 points)		Used to detect a fault. When switched ON during RUN by a fault detection program, it stores a corresponding number in special register D.
т	100 msec timer*	T0 to T199 (200 points)		
т	10 msec timer*	T200 to T255 (56 points)		Forward timers are available in 100 msec, 10 msec and
т	100 msec retentive timer*	Can be used by setting the parameter (0 point)		i inserver i pes.
С	Counter*	C0 to C255 (256 points)		Forward counters are available in pormal and interrupt
с	Interrupt counter*	Can be used by s (0 point)	etting parameter.	types.
D	Data register	D0 to D1023 (102	4 points)	Memory for storing PC data.
D	Special register	D9000 to D9255 ((256 points)	Predefined data memory for special purposes.
¥	Link register	W0 to W3FF (1024 points)		Data register for use with data link. Any range not set with link parameters can be used for data registers.
R	File register*	Can be used by setting the parameter (0 point)		Extends the data register utilizing the user memory area.
A	Accumulator	A0, A1 (2 points)		Data register for storing the operation results of basic and application instructions.
Z	Index register	Z (1 point)		Used to modify devices (X, Y, M, L, B, F, T, C, D, W. R.
ν	Index register	V (1 point)		K, H, P).
Ν	Nesting	N0 to N7 (8 levels	\$)	Indicates the nesting of master controls.

Table 4.4 Devices

	Device	Application Range (Number of points)	Explanation
P	Pointer	P0 to P255 (256 points)	Indicates the destination of the branch instruction (CJ, SCJ, CALL, JMP).
1	Pointer for interruption	10 to 131 (32 points)	Indicates the destination of an interrupt program corresponding to the interrupt factor which has occurred
к	Decimal constant	K-32768 to 32767 (16-bit instruction) K-2147483648 to 2147483647 (32-bit instruction)	Used to specify the timer/counter set value, pointer number, interrupt pointer number, the number of bit device digits, and basic and application instruction values.
н	Hexadecimal constant	H0 to FFFF (16-bit instruction) H0 to FFFFFFFF (32-bit instruction)	Used to specify the basic and application instruction values.

Table 4.4 Device (Continued)

REMARK

The step relay (S) may be used in the same manner as the internal relay (M). The step relay is useful when writing a program which has two functions or applications, i.e., the step relay can be used specifically in accordance with the function or application, independently of the internal relay.

4.1.6 Parameter setting ranges

Parameter setting involves specifying various PC functions and device ranges as well as assigning the user memory (32 K bytes). The set data is stored in the parameter memory area.

As shown in Table 4.5, default values can be used as set in parameter data. Setting ranges shown here can be changed depending on their purpose. Parameters are set with peripheral devices.

The operating manual of each peripheral device gives details parameter settings.

Setting		Default Value	Setting Range	Valid Peripheral Devices	
Item				PU	GPP
Main sequence p	rogram area	6K steps	1 to 8K steps (in units of 1K steps)	0	0
File register capa	city	Absent	1 to 4K points (in units of 1K points)	0	o
Comment capacit	у	Absent	0 to 1600 points (in units of 64 points)	-	o
	Memory capacity		0/8 to 16K bytes		
Status latch	Data memory	Absent	Absent/present] _	0
	File register		Absent/present (2 to 8K bytes)		
	Memory capacity		0/8K bytes	_	
	Device setting		Device number		
Sampling trace		Absent	Per scan		0
	Execution condition		Per time		
	Sampling count		0 to 1024 times (in units of 129 times)		
Microcomputer program capacity		Absent	0 to 14K bytes (in units of 2K bytes)	-	0
Sotting of latch	Link relay (B)	Only for L1000 to L2047. Absent for others.	B0 to B3FF (in units of 1 point)		
	Timer (T)		T0 to T255 (in units of 1 point)	0	
(power failure compensation)	Counter (C)		C0 to C255 (in units of 1 point)		0
range	Data register (D)		D0 to D1023 (in units of 1 point)		
	Link register (W)		W0 to W3FF (in units of 1 point)		
	Number of link stations		1 to 64		
Setting of link range	Input (X)		X0 to XFF (in units of 16 points)		
	Output (Y)	Absent	Y0 to YFF (in units of 16 points)		0
	Link relay (B)		B0 to B3FF (in units of 16 points)		
	Link register (W)		W0 to W3FF (in units of 1 point)	_	
I/O assignment		Absent	X/Y0 to X/Y1FF (in units of 16 points)	-	0

Table 4.5 Parameter Setting Ranges

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	Setting	Default Value	Setting Range	Va Perip Devi	lid heral ices
item				PU	GPP
Setting of interna latch relay (L) step relay (S) set	l relay (M) ting	M0 to M999 L1000 to L2047 Absent for S	M/L/S 0 to 2047 (M, L, S are serial numbers)	o	o
Watchdog timer s	setting	200 msec	10 msec to 2000 msec (in units of 10 msec)	0	0
Setting of timer		100 msec: T0 to T199 10 msec: T200 to T255	256 points of 100 msec, 10 msec, and integrating timers (in units of 8 points) Timers have serial numbers.	o	0
Setting of counter		Not provided for interrupt counter	256 points (in units of 8 points) for counters and interrupt counters Must be consecutive numbers	-	0
Setting of remote RUN/PAUSE contact		Absent	X0 to XFF 1 point for each of RUN and PAUSE contacts. Setting of only PAUSE contact cannot be done	-	0
	Fuse blown	Continuation			
Operation	I/O verify error	Stop			
mode at the	Operation error	Continuation	Stop/continuation	-	0
	Special function unit check error	Stop			
STOP \rightarrow RUN display mode		Operation status prior to STOP Is re-output	Output before STOP or after operation execution	-	0
Print title entry		Absent	Up to 128 characters	-	0
Keyword entry		Absent	Max. 6 digits in hexadecimal (0 to 9, A to F)	o	0

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Table 4.5	Parameter	Setting	Ranges	(Continued)
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4.1.7 Memory capacity settings (main programs, file registers, comments, etc.)

The A1SJCPU provides 32K bytes of user memory area (RAM). Data for parameters, T/C set values, main programs, sampling trace, status latch, file registers, and comments can be stored in the user memory area.

(1) Calculating memory capacity

The user memory area should be utilized after setting parameters to determine the type of data to be stored and the memory capacity. Calculate the memory capacity according to Table 4.6.

Table 4.6 Parameter	Settings and Memory	Capacity
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	ltem	Setting Unit	Memory Capacity	Storage onto ROM	Remark
	Parameter, T/C set values	-	4K bytes (fixed)		
Main program	Sequence program	1K steps	(Main sequence program capacity) x 2K bytes	Possible	Occupies 4K bytes for parameters and T/C set values
	Microcomputer program	2K bytes	(Main microcomputer program capacity) x 1K byte		
Sampling t	race	Not available/ available	0/8K bytes		
	Data memory	Not available/ available	0/8K bytes		The memory capacity for the file register
Status latch	File registers	egisters Not available/ (File registers' memory capacity) available 1K byte Impos		Impossible	status latch is determined by the number of file register points set using parameters.
File registers		1K points	(File registers' number of points) x 2K bytes		
Comments		64 points	(Number of comments) 64 + 1K byte		1K byte is occupied by the system when setting comments capacity.

(2) How to store user memory

All data set by parameters is stored in the following sequence. When the memory protect switch is turned ON, 20K bytes (beginning with the head address) is memory-protected.

Make sure that the sampling trace area and the file register areas are not within this 20K byte memory-protected range.

- (a) The parameter area, T/C setting area, and main program area are stored in order from the head address of the user memory.
- (b) Comments, file registers, status latch, and sampling trace are stored in order from the last address of the user memory.



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Fig. 4.3 User Memory Assignments

POINT

Even if parameters or the main sequence program are stored in ROM, the memory capacity of the sampling trace, status latch, file registers, and comments cannot be increased.

4.2 Functions

The following table describes the functions of the A1SJCPU. The ACPU programming manual (Fundamentals) gives details.

Table 4.7 List of Fun	ctions
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Function	Description
Constant scan	 Executes the sequence program at the predetermined intervals independently of the scan time.
	Setting allowed between 10 and 2000 msec.
Latch (power failure	 Retains device data if the PC is switched OFF or reset or a momentary power failure of 20 msec or longer occurs.
compensation	• L, B, T, C, D and W can be latched
Remote RUN/STOP	 Allows remote RUN/STOP from external device (e.g. peripheral, external input, computer) with the RUN/STOP switch in RUN position.
r	• Stops operation with the output (Y) status retained.
PAUSE	 Pause function may be switched ON by any of the following ways:
	Remote PAUSE contact
	Peripheral device
Status latch	 Stores all device data in the status latch area in the A1S when the status latch condition is switched ON.
Status laten	• The stored data can be monitored by the peripheral device.
Sampling trace	 Samples the specified device operating status at predetermined intervals and stores the sampling result in the sampling trace area in the A1S.
	 The stored data can be monitored by the peripheral device.
Offline switch	 Allows the device (Y, M, L, S, F, B) used with the OUT instruction to be disconnected from the sequence program operation processing.
Priority setting ER- ROR LED	• Sets ON/OFF of the ERROR LED in case of an error .
	Execute clock operation in the CPU module.
Clock	 Clock data includes the year, month, day, hour, minute, second, and day of the week.
	 Clock data can be read from special registers D9025 to D9028.

REMARK

The A1SJCPU cannot do "step operation", "PAUSE using RUN/STOP key switch", and "I/O module replacement at online".

4.3 Handling Instructions

This section gives handling instructions from unpacking to installation of the A1SJCPU, I/O modules and extension base unit, etc.

- (1) Since the case, terminal block connector, and pin connector of the unit are made of plastic, do not drop them or subject them to mechanical shock.
- (2) Do not remove the printed circuit board of any unit from its case Removal may cause board damage.
- (3) When wiring, take care to prevent entry of wire offcuts into the unit. If any conductive debris enters the unit, make sure that it is removed.
- (4) Tighten the unit mounting screws and terminal screws as indicated below.

Screw	Tightening Torque Range N•cm (Kg•cm) [Ib•inch]
Unit mounting screw (M4 screw)	78.4(8)[6.93] to 117.6(12)[10.39]
I/O module terminal block terminal screw (M3.5 screw)	58.8(6)[5.2] to 88.2(9)[7.79]
Power supply module terminal block terminal screw (M3.5 screw)	58.8(6)[5.2] to 78.4(8)[6.93]

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4.4 Names and Purposes of Parts and Settings

The names and purposes of parts of the A1SJCPU and the switch settings necessary for operating the A1SJCPU are explained below.

4.4.1 Names of parts of A1SJCPU

(1) Name of parts of A1SJCPU



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No.	Name	Purpose	
(10)	Module mounting screw	Used to secure the module to the base. M4 x 12 screw	
_ (11) `	RUN / STOP switch	RUN / STOP: Used to run or stop the sequence program operation. L.CLR (LATCH CLEAR): Used to clear (OFF or 0) data in the latch area designated by parameter setting. (Data in other than the latch area are also cleared by LATCH CLEAR:) See Section 4.4.4 for the latch clear operation.	
_ (12)	RESET switch	Used to perform hardware reset. Used when an operation error occurs and to initialize the operation.	
(13)	POWER LED	Used to indicate the 5 VDC power supply.	
(14)	RUN LED	 Lit: Indicates the execution of sequence program with the RUN/STOP switch set in the RUN position. (When an error which does not cause the sequence program execution to stop occurs (see Section 10.3), this LED remains lit.) Unlit: The RUN LED does not light in the following cases: The 100/200 VAC power is not supplied to the A1SJCPU. The RUN/STOP switch is set in the STOP position. Remote STOP is executed. Remote PAUSE is executed. Flash: The RUN LED flashes in the following cases: An error to stop the sequence program execution is detected by the self-diagnosis check. Latch clear is executed. 	
(15)	ERROR LED	 Lit: A self-diagnosis error is detected. (When an error which has been set for "unlit" with the LED indication priority setting is detected, this LED remains unlit.) Unlit: The operation is normal, or when an error is detected by a CHK instruction execution. Flash: Annunciator (F) is turned ON by the sequence program. 	

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1 (2) Name of parts of A1SJCPU-S3



No.	Name	Purpose
(10)	Module mounting screw	Used to secure the module to the base. M4 x 12 screw
(11)	RUN / STOP switch	RUN / STOP: Used to run or stop the sequence program operation. L.CLR (LATCH CLEAR):Used to clear (OFF or 0) data in the latch area designated by parameter setting. (Data in other than the latch area are also cleared by LATCH CLEAR.) See Section 4.4.4 for the latch clear operation. RESET: Used to perform hardware reset. Used when an operation error occurs and to initualize the operation.
(12)	POWER LED	Used to indicate the 5 VDC power supply.
(13)	RUN LED	 Lit: Indicates the execution of sequence program with the RUN/STOP switch set in the RUN position. (When an error which does not cause the sequence program execution to stop occurs (see Section 10.3), this LED remains lit.) Unlit: The RUN LED does not light in the following cases: The 100/200 VAC power is not supplied to the A1SJCPU-S3. The RUN/STOP switch is set in the STOP position. Remote STOP is executed. Remote PAUSE is executed. Flash: The RUN LED flashes in the following cases: An error to stop the sequence program execution is detected by the self-diagnosis check. Latch clear is executed.
(14)	ERROR LED	 Lit: A self-diagnosis error is detected. (When an error which has been set for "unlit" with the LED indication priority setting is detected, this LED remains unlit.) Unlit: The operation is normal, or when an error is detected by a CHK instruction execution. Flash: Annunciator (F) is turned ON by the sequence program.

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4.4.2 I/O control switch setting

The I/O control system uses either a direct or a refresh mode. Use the dip switch (SW2-1) to switch the I/O control mode.

When shipment from the factory, both inputs and outputs are set for direct mode (SW2-1: ON).



Make sure that the power is OFF when the I/O control mode is switched.

4.4.3 Memory protect switch setting

The memory protect switch is used for protecting RAM memory data from being overwritten by a peripheral device malfunction. (When the CPU installed with a memory cassette is operated using ROM or E^2 PROM, the memory switch setting will be invalid.) Use the DIP switch (SW2-2) to switch the memory protect setting.

This memory protect function protects the first 20K bytes of the user memory area (32K bytes).

The function prevents overwriting and deleting the program once it has been written. When the contents of RAM memory are changed, make sure that the memory protect switch is OFF.

When shipment from the factory, the memory protect function is turned OFF (SW2-2: OFF).



POINT

Do not use the memory protect function when either a sampling trace or a status latch is executed. If the protect function is used, the data cannot be stored to memory.

4.4.4 Latch clear

Follow the procedures mentioned below to execute latch clear by using the RUN/STOP switch.

Devices outside the latch range are also cleared by the latch clear operation.

(1) Operating procedure for latch clear



(2) Canceling latch clear part way through

Latch clear can be canceled part way through by using either of the methods (a) and (b) below.

- (a) Turn the RUN/STOP keyswitch to "RUN" to set the A1SJCPU to the RUN status.
- (b) Turn the RUN/STOP keyswitch to the RESET position to reset the A1SJCPU.

(Or, press the RESET switch to reset the A1SJCPU.)

REMARK

It is possible to perform latch clear by using the GPP function operation.

For example, when an A6GPP is used, latch clear can be done by using the "Device Memory All Clear" of the test function in PC mode

See the GPP function operating manual for the operation procedure.

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5. POWER SUPPLY MODULE

5.1 Specifications

Table 5.1 shows the specifications of power supply modules.

Table 5.1 Power Supply Module Specifications

Item		Specifications					
Rem		A1S61PEU *4	A1S61P	A1S62PEU *4	A1S62P	A1S63P	
Base loading slot		Power supply mod	lule loading slot				
Rated input voltage		200 to 240 VAC +10%/-15%	100 to 120/ 200 to 240 VAC +10%/-15%	200 to 240 VAC +10%/-15%	100 to 120/ 200- to 240 VAC +10%/-15%	24 VDC +30%/ -35%	
Rated input frequency		50/60 Hz ±3%					
Max. input apparent pow	er	20 A within 8 ms				81 A within 1 ms	
Inrush current		105 VA				41 W	
Rated output current	5 VDC	5 A		3 A		5 A	
nated bulput corrent	24 VDC±10%			0 6 A	0 6 A		
Overcurrent protection	5 VDC	5.5 A or higher		3.3 A or higher		5.5 A or higher	
•1	24 VDC			0.66 A or higher			
Overvoltage protection	5 VDC	5.5 to 6.5 V					
•2	24 VDC			<u> </u>			
Efficiency		65% or higher					
Insulation withstand	Between primary and 5 VDC	1780 VAC	1500 VAC	1780 VAC	1500 VAC	500 VAC	
voltage	Between primary and 24 VDC			1780 VAC	1500 VAC		
Noise immunity		IEC801-4, 2 kV					
Power indication		Power LED indication					
Terminal crew size		M3.5 × 7					
Applicable wire size		AWG16 to 22					
Applicable tightenig torq	ue	83 to 113 N-cm (8.5 to 11.5 kg-cm) [7.4 to 10.1 lb inch]					
External dimension mm	(inch)	130 × 55.94 (5 12	× 2.17 × 3 70)				
Weight kg (lb)		0.53 (1.17)	0.53 (1 17)	0.55 (1.21)	0.55 (1.21)	0.5 (1.1)	
Allowable momentary po	wer failure time *3	Within 20 ms Within 1 ms					

*1: Overcurrent protection

The overcurrent protection device shuts off the 5 V, 24 VDC circuit and stops the system if the current flowing in the circuit exceeds the specified value. When this device is activated, the power supply module LED is switched OFF or dimly lit. If this happens, eliminate the cause of the overcurrent and start up the system again.

*2 Overvoltage protection

The overvoltage protection device shuts off the 5 VDC circuit and stops the system if a voltage of 5.5 to 6.5 V is applied to the circuit When this device is activated, the power supply module LED is switched OFF. If this happens, switch the input power OFF, then ON to restart the system. The power supply module must be changed if the system is not booted and the LED remains OFF.

*3: Allowable momentary power interruption time

This value indicates the momentary power interruption time allowed for the PC CPU and

varies according to the power supply module used with the PC CPU module. The allow -able momentary power interruption time for a system in which an A1S63P is used is defined as starting when the primary power supply of the 24 VDC stabilized power supply of the A1S63P is turned OFF and lasting until the 24 VDC becomes less than the specified voltage (15 6 VDC).

*4: A1S61PEU and A1S62PEU comply with EN61010-1 and safety aspects of IEC 1131-2 to meet the Low Voltage Directive which will be mandatory from the 1st of January 1997.

5.1.1 Selection of a power supply module

Select a power supply module by considering the total current consumption of the I/O modules, special function modules and peripheral devices to be supplied with power by the module. In addition, if using an A1S52B (S1), A1S55B(S1), A1S58B(S1), A52B, A55B, or A58B extension base unit, note that this unit will also draw its power from the power supply module on the main base unit, and this must also be taken into consideration.

For details on the 5 VDC current consumption of I/O modules, special function modules and peripheral devices, refer to Section 2.3.



(1) Selection of a power supply module when using A1S52B(S1), A1S55B(S1), A1S58B(S1), A52B, A55B, A58B extension base units When using A1S52B(S1), A1S55B(S1), A1S58B(S1), A52B, A55B, A58B extension base units, the 5 VDC power supply is taken from the main base unit via the extension cable. Accordingly, the following cautions must be observed when using one of these extension base units. (a) Make sure that the 5 VDC capacity of the selected power supply module on the main base unit will cover the 5 VDC current consumption of the A1S52B(S1), A1S55B(S1), A1S58(S1), A52B, A55B, or A58B.

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[Example]

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- Assume that the 5 VDC current consumption at the main base unit is 3 A, and the 5 VDC current consumption at the A1S55B(S1) is 1 A:Since the capacity of the power supply module on the main base unit (3 VDC, 3A) is exceeded, it is necessary to establish a separate power supply using an A1S65B(S1) or A1S68B(S1).
- (b) Since power is supplied to the A1S52B(S1), A1S55B(S1), A1S58B(S1), A52B, A55B, and A58B through an extension cable, there is some voltage drop. The power supply module and cable length must be selected to ensure that at least 4.75 VDC reaches the receiving terminals.
- (c) For details on voltage drop and other topics, see Section 6.1.3 extension base unit.

5.2 Names and Purposes of Parts and Settings



The names and purposes of parts of the power supply module are described below.

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(5)	LG terminal	Used to ground the power supply filter. Provided with a potential half the input voltage.
(6)	Power input terminal	Used to connect to 100 or 200 VAC power supply.
(7)	Power input terminal	Used to connect to 200 to 240 VAC power supply.
(8)	Power input terminal	Used to connect to a 24 VDC power supply.
(9)	Terminal screw	M3.5 x 7
(10)	Terminal cover	Used to protect the terminal block
(11)	Module mounting screw	Used to secure the module to the base unit.

POINT

If the power supply voltage setting is different from actual power supply voltage, the following problem will occur.

	Power Supply Voltage		
	100 VAC	200 VAC	
Setting for 100 VAC (the operating voltage switch- ing terminals are shorted)		The power supply module will be destroyed. (The CPU will not cause problem.)	
Setting for 200 VAC (the operating voltage switch- ing terminals are open)	The power supply module will not cause problem The CPU will not operate.		

5. POWER SUPPLY MODULE

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(7) The common current of an A1SY60 varies according to ambient temperature. Select a common current referring to the chart shown below.



- (8) The A1SX41 and A1SX42 input modules and the A1SY41 and A1SY42 output modules are supplied with soldering-type 40-pin connectors. The 40-pin connectors of pressure-displacement type and crimp contact type are also available. Tools for the pressure-displacement and crimp contact type connectors must be procured from the following suppliers:
 - (a) Soldering-type 40-pin connector

	Model name	:	A6CON1	
(b)	Crimp-contact-type 40-	pi	n connec	otor
	Model name	:	A6CON2	2
	Tool	:	Fujitsu	FCN-363-T005/H
	Applicable wire size	:	AWG #2	4 to 28

(c) Pressure-displacement-type 40-pin connector

Model name	: A6CON3
ΤοοΙ	: Fujitsu FCN-367T-T012/H (locator plate) FCN-707T-T001/H (cable cutter) FCN-707T-T101/H (hand press)
Applicable wire size	: AWG #28 (twisted) AWG #30 (single wire)

(d) Supplier's offices:

Fujitsu Limited

North and South America:

Fujitsu Component of America, Inc. 3545 North First Street, San Jose, CA 95134-1804 U.S.A. Phone: (408) 922-9000 Telex: (910) 338-0190 Fax: (408) 428-0640

Europe:

Fujitsu Microelectronik GmbH

Am Siebestein 6-10 6072, Dreieich-Buchschtag, F.R. Germany Phone: (061) 03-690-0 Telex: 411963 Fax: (061) 03-690-122

Asia:

Fujitsu Microelectronics Asia PTE, Limited #06-04 to #06-07 Plaza, By The Park, No.51 Bras Basah Road, Singapore 0719 Phone: 336-1600 Telex: 55573 Fax: 336-1609

5.2 Input Module Specifications

5.2.1 A1SX10 AC input module

Model		AC Input Module		
Specification	s	A1SX10	Appear	ance,
Number of input points		16 points		
Insulation method		Photocoupler	A1SX10	
Rated input-voltage		100 to 120 VAC- 50/60 Hz	; 8	
Rated input cu	urrent	Approx. 6 mA (100 VAC 60 Hz)		
Operating volt	lage range	85 to 132 VAC (50/60 Hz ±5%)	;8	
- Maxsimultan points	eous.input	100% simultaneously ON (at 110 VAC) 60% simultaneously ON (at 132 VAC)		
Inrush current	L	Max. 200 mA, within 1 ms (132 VAC)		
ON voltage/O	N current	80 VAC or higher/5 mA or higher	0	
OFF voltage/0	OFF current	30 VAC or lower/1 mA or lower		
Input impedar	nce	Approx 18 kΩ (60 Hz), Approx. 21 kΩ (50 Hz)	2	
Response	$OFF \rightarrow ON$	20 ms or less (100 VAC 60 Hz)	3	
time	$ON \rightarrow OFF$	35 ms or less (100 VAC 60 Hz)	4	
Common term arrangement	nnal	16 points/common (common terminals: TB9, TB18)	6	
Operating Ind	icator	ON state is indicated (LEDs)	7	
External conn	ections	20-point terminal block connector (M3.5 x 7 screws)	8	
Applicable wi	re size	0 75 to 1.5 mm ²	9	
Applicable cri	imp terminals	1.25-3 5 1.25-YS3A 2-3.5 2-YS3A V1.25-M3 V1.25-YS3A V2-S3 V2-YS3A	A	
Accessories		None	C	
Insulation withstand voltage		1500 VAC	D	
Noise immuni	ity	1000 VAC '		
Internal current consumption (5 VDC) 50 mA (T		50 mA (TYP, all points ON)		
Weight kg (lb) 0.21		0.21 (0 46)		
		External Connections		
	_		Terminal No.	Signal Name
			TB1	X00
		Internal circuit	TB2	X01
	-		ТВЗ	X02
	┍──┲┷╼─┤		TB4	X03
			TB5	X04
			TB6	X05
			TB7	X06
			TB8	X07
			TB9	COM
1	, т		TB10	X08
	+	╧╧╪╅╘╝┾╪╌╤╌╤╌┥╷╴╷┝────╔╽	TB11	X09
			TB12	XOA
			TB13	X0B
1			TB14	XOC
1	. т	·B17	TB15	XOD
	<u>است من من المناسبة ا</u>		TB16	X0E
1		<u>1818</u> A	TB17	XOF
	100 VA	c	TB18	СОМ
			TB19	Vacant
L			TB20	Vacant

5.2.2 A1SX10EU AC input module

	Model	AC input Module		
Specifications		A1SX10EU	Appearance	
Number of input points		16 points		
Insulation metho	od	Photocoupler	A1SX10EU	
Rated input volt	tage	100 to 120 VAC 50/60 Hz	18	8:
Rated input cur	rent	Approx. 7 mA (120 VAC 60 Hz)		
Operating volta	ige range	85 to 132 VAC (50/60 Hz ±5%)	;8	8 ;
Max. simultane points	ous input	100% simultaneously ON		
Inrush current		Max. 200 mA, within 1 ms (132 VAC)		Ì
ON voltage/ON	current	80 VAC or higher/5 mA or higher	0	
OFF voltage/OF	FF current	30 VAC or lower/1 mA or lower	1	
Input impedanc	ce	Approx. 18 kΩ (60 Hz), Approx. 21 kΩ (50 Hz)	2	Ì
Response	$OFF \rightarrow ON$	20 ms or less (100 VAC 60 Hz)	3	
time	$ON \rightarrow OFF$	35 ms or less (100 VAC 60 Hz)	4	
Common termir arrangement	nal	16 points/common (common terminals: TB9, TB18)	6	
Operating indic	cator	ON state is indicated (LEDs)	7	
External conne	ections	20-point terminal block connector (M3.5 x 7 screws)	8	
Applicable wire	ə size	0.75 to 1.5 mm ² (AWG15 to AWG19)	9	
Applicable crim	np terminals	RAV1.25-3.5	A	
Accessories		None	В	
Insulation withs voltage	stand	1780 VAC		
Noise immunity	y	1000 VAC		
Internal current consumption (5 VDC)		50 mA (TYP, all points ON)	F	
Weight kg (lb) 0.21 (0.46)		0.21 (0.46)	1	
		External Connections		· · · · · ·
			Terminal No.	Signal Name
			TB1	X00
		Internal circuit	TB2	X01
			ТВЗ	X02
			TB4	X03
			TB5	X04
	(TB6	X05
		тре	TB7	X06
			TB8	X07
		твэ-	TB9	COM
	┝───		TB10	X08
			TB11	X09
)		TB12	XOA
	/		TB13	X0B
			TB14	XOC
	<u>↓</u>	<u>, TB17</u>	TB15	XOD
		NTB18	TB16	XOE
			TB17	XOF
	100 V	AC	TB18	Сом
			TB19	Vacant
			TB20	Vacant

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5. INPUT AND OUTPUT MODULE

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5.2.3 A1SX20 AC input module

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A 8 C 0 E F
D E F
]
Signal
Name
X00
X01
X02 X03
X04
X05
X06
X07
COM
X08
X09
XOA
X0B
XOC
XOD
X0E
XOF
COM
Vacant
Vacant

5.2.4 A1SX20EU AC input module

	Model	AC Input Module			
Specifications	5	A1SX20EU	Appear	Appearance	
Number of input	ut points	16 points			
Insulation method		Photocoupler	A1SX20EL		
Rated input voltage		200 to 240 VAC 50/60 Hz			
Rated input cu	rrent	Approx 11 mA (240 VAC 60 Hz)			
Operating volta	age range	170 to 264 VAC (50/60 Hz ±5%)] ; =		
Max. simultane points	eous input	60% simultaneously ON (at 220 VAC)			
Inrush current		Max. 500 mA, within 1 ms (264 VAC)			
ON voltage/ON	V current	80 VAC or higher/4 mA or higher			
OFF voltage/C	OFF current	30 VAC or lower/1 mA or lower			
Input impedan	ce	Approx. 22 kΩ (60 Hz), Approx. 27 kΩ (50 Hz)	2		
Response	$OFF \rightarrow ON$	30 ms or less (200 VAC 60 Hz)	3	l	
time	$ON \rightarrow OFF$	55 ms or less (200 VAC 60 Hz)			
Common term arrangement	inal	16 points/common (common terminals: TB9, TB18)	5		
Operating indi	cator	ON state is indicated (LEDs)	7		
External conn	ections	20-point terminal block connector (M3.5 x 7 screws)	8		
Applicable wir	e size	0.75 to 1.5 mm ² (AWG15 to AWG19)	9		
Applicable crir	mp terminals	RAV1.25-3.5	A		
Accessories		None	В		
Insulation with voltage	nstand	2830 VAC			
Noise immunit	ty	1000 VAC		i	
Internal current consumption (5 VDC) 50 mA (TYP, all points ON)		50 mA (TYP, all points ON)	F		
Weight kg (lb)	Weight kg (lb) 0.23 (0.50)				
		External Connections			
			Terminal No.	Signal Name	
		Internal circuit	TB1	X00	
			TB2	X01	
	6		TB3	X02	
			TB4	X03	
			TB5	X04	
	(TB6	X05	
			TB7	X06	
		A (TB8	X07	
		твэ-ң	TB9	СОМ	
	÷		TB10	X08	
			TB11	X09	
			TB12	XOA	
	(1B13	XOB	
			TB14	XOC	
	ـــهـــــه	5 ^{TB17}	TB15	XOD	
		ТВ18	TB16	XOE	
			TB17	XOF	
	200 V		TB18	СОМ	
			1819	Vacant	
			1820	Vacant	

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5. INPUT AND OUTPUT MODULE

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5.2.5 A1SX30 DC/AC input module

Model			DC/AC Input Module		
Specifications		A1S	Appearance		
Number of inp	out points	16 points			
Insulation met	thod	Photocoupler		A1SX30	
Rated input vo	oltage	12/24 VDC	12/24 VAC 50/60 Hz		
Rated input cu	urrent	4.2 mA (12 VDC/VAC), 8 6 mA (24	4 VDC/VAC)		
Operating volt	tage range	10 2 to 26 4 VDC (ripple: less than 5%)	10 2 to 26 4 VAC (50/60 Hz ±5%)	;]	
Max. simultan points	eous input	75% simultaneously ON			
ON voltage/OI	N current	7 VDC/AC or higher/2 mA or high	er	0	
OFF voltage/C	OFF current	2.7 VDC/AC or lower/0.7 mA or lo	wer	1	
Input impedan	nce .	Approx. 2.7 kΩ		2	
Response	$OFF \rightarrow ON$	20 ms or less (12/24 VDC)	25 ms or less (12/24 VAC 60Hz)	3	
time	$ON \rightarrow OFF$	20 ms or less (12/24 VDC)	20 ms or less (12/24 VAC 60Hz)	5	
Common term arrangement	ninal	16 points/common (common term	inals [.] TB9, TB18)	7	
Operating Ind	licator	ON state is indicated (LEDs)		8	
External conn	ections	20-point terminal block connector	(M3.5 x 7 screws)	9	
Applicable wir	re size	0.75 to 1.5 mm ²		A	
Applicable cri	mp terminals	1.25-3.5 1.25-YS3A 2-3.5 2-YS V1.25-M3 V1.25-YS3A V2-S3 V	3A '2-YS3A	B	
Accessories		None		D	
Insulation with voltage	hstand	500 VAC		E	
Noise immunity		1500 VAC		F	
Internal curre consumption	nt (5 VDC)	50 mA (TYP, all points ON)			
Weight kg (lb))	0.2 (0 44)			
		External Co	nnections		
				Terminal No.	Signal Name
		Internal circui	•	TB1	X00
			·	TB2	X01
		· -	150	TB3	X02
	Tee-	B1		TB4	X03
	(Internal ~	TB5	X04
				TB6	X05
				TB7	X06
		ъв 🗸		TB8	X07
		A		TB9	COM
	Т	310	LED	TB10	X08
	+ <u>`</u>			TB11	X09
			Internal circuit	TB12	XOA
				TB13	XOB
				TB14	XOC
тв17		B17		TB15	XOD
		B18		TB16	XOE
				TB17	XOF
				TB18	СОМ
				TB19	Vacant
				TB20	Vacant

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5.2.6 A1SX40 DC input module (sink type)

Model DC Input Module (Sink Type)					
Specifications		A15X40		Appearance	
Number of input points		16 points			
Insulation method		Photocoupler			
Rated input voltage		12 VDC 24 VDC			
Rated input current		Approx. 3 mA Approx 7 mA			
Operating volt	tage range	10.2 to 26.4 VDC (ripple: less than 5%)		, ē	
Max. simultaneous input points		100% simultaneously ON (at 26.4 VDC)			
ON voltage/O	N current	8 VDC or higher/2 mA or higher			
OFF voltage/C	OFF current	4 VDC or lower/1 mA or lower			
Input impedar	nce	Approx. 3.3 kΩ		2	
Response	OFF → ON	10 ms or less (24 VDC)		3	
time	ON → OFF	10 ms or less (24 VDC)		4	
Common term arrangement	ninal	16 points/common (common terminals: TB9, TB18)		5	
Operating ind	icator	ON state is indicated (LEDs)		6	
External conn	ections	20-point terminal block connector (N	13.5 x 7 screws)	7	
Applicable wit	re size	0.75 to 1.5 mm ²		8	
Applicable cri terminals	mp	1.25-3 .5 1.25-YS3A 2-3.5 2-YS3A V1.25-M3 V1.25-YS3A V2-S3 V2-YS3A		9 A	
Accessories		None		В	
Insulation withstand voltage		500 VAC		C	
Noise immuni	ity	500 VAC			
Internal current consumption (5 VDC)		50 mA (TYP, all points ON)		F	
Weight kg (lb)	0.2(0.44)			
		External Conr	nections		
				Terminal No.	Signal Name
		Internal circuit	al circuit		X00
				TB2	X01
				TB3	X02
				TB4	<u>X03</u>
			\rightarrow	1B2	X04
			[180	X05
		тва 🗸			X06
		A			X0/
					X08
					X00
					XOA
					XOR
					XOC
					XOD
					XOF
TB18				TB17	XOF
- + ► ► A					COM
. 12/24 VDC			TB19	Vacant	
-					Vacant

5.2.7 A1SX40-S1 DC input module (sink type)

Model DC Input Module (Sink Type)					
Specification	5	A1SX40-S1	Appearance		
Number of input points		16 points	••••		
Insulation method		Photocoupler	A15X40-51		
Rated input voltage		24 VDC			
Rated input current		Approx. 7 mA			
Operating volt	age range	19 2 to 26 4 VDC (ripple: less than 5%)	; <u> </u>	ō,	
Max. simultaneous input points		100% simultaneously ON (at 26.4 VDC)			
ON voltage/OI	N current	14 VDC or higher/4 mA or higher]		
OFF voltage/OFF current		6 5 VDC or lower/1 7 mA or lower			
Input impedan	сө	Αρριοχ. 3 3 κΩ	2		
Response time	$OFF \rightarrow ON$	0 1 ms or less (24 VDC)	3		
	ON → OFF	0 2 ms or less (24 VDC)	4		
Common term arrangement	inal	16 points/common (common terminals' TB9, TB18)	5		
Operating indi	cator	ON state is indicated (LEDs)	6		
External conn	ections	20-point terminal block connector (M3.5 x 7 screws)	_ <mark>7</mark>		
Applicable wir	e size	0 75 to 1.5 mm ²	8		
Applicable crit terminals	mp	1 25-3 1.25-YS3A 2-3.5 2-YS3A V1.25-3 V1.25-YS3A V2-S3 V2-YS3A	9 A		
Accessories		None	В		
Insulation withstand voltage		500 VAC	С		
Noise immunity		500 VAC			
Internal current consumption (5 VDC)		50 mA (TYP, all points ON)	F		
Weight kg (lb) 0 2 (0.44)					
		External Connections			
		Terminal	Signal		
		Internal circuit	TRI		
			TR2	X01	
			TRA	X02	
	1		TB4	X02	
			TB5	X04	
TB9 TB9 TB9 TB9 TB10 R R A LED LED LED Circuit			TB6	X05	
			TB7	X06	
			TB8	X07	
			TB9	СОМ	
			TB10	X08	
			TB11	X09	
			TB12	XOA	
			TB13	XOB	
			TB14	XOC	
TB17			TB15	XOD	
				XOE	
				XOF	
24 VDC			1818	COM	
			1819	Vacant	
			1820	i vacant	

5.2.8 A1SX40-S2 DC input module (sink type)

Model DC Input Module (Sink Type)						
Specifications		A1SX40-S2	Appearance			
Number of input points		16 points				
Insulation method		Photocoupler	A1SX40-S2			
Rated input voltage		24 VDC				
Rated input cu	urrent	Approx. 7 mA				
Operating volt	age range	19.2 to 26.4 VDC (ripple: less than 5%)	; =			
Max simultaneous input points		100% simultaneously ON (at 26.4 VDC)				
ON voltage/O	N current	14 VDC or higher/3.5 mA or higher				
OFF voltage/C	OFF current	6 5 VDC or lower/1.7 mA or lower				
Input impedan	ce	Approx 3.3 kΩ	2			
Response	$OFF \rightarrow ON$	10 ms or less (24 VDC)	3]		
time	$ON \rightarrow OFF$	10 ms or less (24 VDC)	4			
Common term arrangement	inat	16 points/common (common terminals: TB9, TB18)	5			
Operating ind	icator	ON state is indicated (LEDs)	6			
External conn	ections	20-point terminal block connector (M3.5 x 7 screws)	7			
Applicable wir	re size	0.75 to 1.5 mm ²	8			
Applicable cri terminals	тр	1.25-3 1.25-YS3A 2-3.5 2-YS3A V1 25-M3 V1 25-YS3A V2-S3 V2-YS3A	9 A			
Accessories		None	В			
Insulation withstand voltage		500 VAC	C			
Noise immuni	ty	500 VAC	5			
Internal current consumption (5 VDC)		50 mA (TYP, all points ON)	F			
Weight kg (lb) 0.2 (0.44)						
		External Connections				
		latoraal airavit	Terminal No.	Signal Name		
			TB1	X00		
		TB1 LED	TB2	X01		
			TB3	X02		
				X03		
			TRE	X05		
				X06		
A A				X07		
твэ-				COM		
TB10 LED				X08		
	TB11	X09				
	TB12	XOA				
				XOB		
				XOC		
	TB15	XOD				
	TB16	XOE				
	TB17	XOF				
	TB18	СОМ				
				Vacant		
				Vacant		

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5.2.9 A1SX41 DC input module (sink type)



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5.2.10 A1SX41-S2 DC input module (sink type)

Model DC Input Module (Sink Type)							
Specification	5	A1SX41-S2			Арр	earance	
Number of inp	ut points	32 points					
Insulation met	hod	Photocoupler			Aisx	41-S2	
Rated input vo	ltage	24 VDC			A 12		P
Rated input cu	irrent	Approx. 7 mA					2
Operating volt	age range	19.2 to 26 4 VDC (ripple: less than 5%)		Į.	3888	j	
Max. simultan points	eous input	60% (20 points/common) simultaneously O	N (at 26.4 VDC)				
ON voltage/OI	N current	14 VDC or higher/3.5 mA or higher					
OFF voltage/C	FF current	6.5 VDC or lower/1.7 mA or lower				,	
Input impedan	се	Approx 3.3 kΩ					.
Response	$OFF \rightarrow ON$	10 ms or less (24 VDC)				의태표	37
time	$ON \rightarrow OFF$	10 ms or less (24 VDC)]][]]][]]]]	분]
Common term arrangement	inal	32 points/common (common terminals: B1,				파비	
Operating ind	cator	ON state is indicated (LEDs)			訓日	북]	
External conn	ections	40-pin connector			케! 봄	황네	
Applicable wir	e size	0.3 mm ²		:))): 표	관 1		
Accessories		Connector (1 pce) for external wiring (sold	lering type)			: = 1	쓰레
Insulation with voltage	nstand	500 VAC					
Noise immuni	ty	500 VAC				키브	<u> </u>
Internal current consumption	nt (5 VDC)	80 mA (TYP, all points ON)			DC2	4V 7mA A1SX	41- S2
Weight kg (lb)		0.21(0.46)					
		External Connection	15	_	-		
			Pin Arrangement	Pin No.	Signal Name (FH)	Pin No.	Signal Name (FH)
External		Internal circuit		B20	X00	A20	X10
switch			\sim	B19	X01	A19	X11



Arra	Pi	n em	ent	Pin No.	Signal Name (FH)	Pin No.	Signal Name (FH)
				B20	X00	A20	X10
1	\frown	_		B19	X01	A19	X11
820	0	0	A20	B18	X02	A18	X12
B19 B18	0	0	A19 A18	B17	X03	A17	X13
B17	0	0	A17	B16	X04	A16	X14
B16 B15	ŝ	0 0	A16 A15	B15	X05	A15	X15
814	•	•	A14	B14	X06	A14	X16
B13 B12		0	A13 A12	B13	X07	A13	X17
B11	0	0	A11	B12	X08	A12	X18
810 B9		0	A10 A9	B11	X09	A11	X19
B8	0	•	A8	B10	XOA	A10	X1A
87 86	°	0	A7 A6	B9	X0B	A9	X1B
B5	°	•	A5	B8	X0C	A8	X1C
B4 83	8	0	A4 A3	B7	XOD	A7	X1D
B2		0	A2	B6	XOE	A6	X1E
BI	Ľ		/ A1	B5	X0F	A5	X1F
				B4	Vacant	A4	Vacant
Fro	nt v	iew		B3	Vacant	A3	Vacant
				B2	COM	A2	Vacant
				B1	COM	A1	Vacant

*1: Arrangement of pins A and B shown above is opposite to the arrangement of pins of the connector on the module.

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5.2.11 A1SX42 DC input module (sink type)

												_	_
	Model	J	DC	C Input	Modu	le (Sin	к Тур	e) (
Specification	IS		A1SX	42						Ap	pearar	nce	
Number of inp	out points	64 points										۰.	
Insulation met	thod	Photocoupler								Aisx	42		
Rated input vo	oltage	12 VDC		24 VDC	;				_	15			
Rated input cu	urrent	Approx. 2 mA		Approx	. 5 m A			·	4				
Operating volt	tage range	10 2 to 26"4' VDC (ripple: less	s than	5%)						15	188	8;	
Max. simultan points	neous input	50% (16 points/common) sim	multaneously ON (at 24 VDC)							F	<u> </u>		1
ON voltage/O	N current	8 VDC or higher/2 mA or high	ner										
OFF voltage/C	OFF current	4 VDC or lower/0.6 mA or low	bwer						-		БĘ	<u>_</u>	
Input impedan	nce	Approx. 5 kΩ											
Response	OFF → ON	10 ms or less (24 VDC)								LIN	ᆀᆔ	읫	
time	ON → OFF	10 ms or less (24 VDC)]用	::)	
Common term arrangement	ninal	32 points/common (common	termin	als: 1B	1, 1B2	2, 2B1,	2B2)						
Operating ind	licator	ON state is indicated (LEDs)	, 32-bi	it indica	tion b	y switc	h						
External conn	nections ·	40-pin connector									目		
Applicable wire size 0.3 mm ²													
Accessories		Connectors (2 pces.) for exte	ernal v	viring (s	olderi	ng type	ə)						
Insulation with voltage	hstand	500 VAC] =		
Noise Immuni	ity	500 VAC							_		기	0	
Internal curre consumption	nt (5 VDC)	90 mA (TYP, all points ON)								DC12/2	24V 2/5m/	A1SX42	
Weight kg (lb)	0.28(0 62)										1	
		Extern	al Cor	nectio	ns								
			Pin	Arrangei	ment	Pin No	Signal Name	Pin No.	Signal	Pin No.	Signal Name	Pin No.	Signal
	lr	nternal circuit				1820	(FH) X00	1420	(PH) X10	2820	(LH) X20	2420	(LH) X20
switch		·		\sim		1819	X01	1419	X11	2B19	X21	2419	X31
			B20	00	A20	1818	X02	1418	X12	2B18	X22	2418	X32
	F	internal circuit	B19	0 0	A19	1B17	X03	1A17	X13	2B17	X23	2A17	X33
			B17	0 0	A18 A17	1B16	X04	1A16	X14	2B16	X24	2A16	X34
145	5.	LED	B16	0 0	A16	1B15	X05	1A15	X15	2B15	X25	2A15	X35
182		side a lindication	B14	0 0	A15	1B14	X06	1A14	X16	2B14	X26	2A14	X36
12/24 VDC	(forme	r half)	B13 B12	0 0 0 0	A13	1813	X07	1A13	X17	2B13	X27	2A13	X37
1B1	Righ (latte	t side	B11	0 0	A12	1812	X08	1A12	X18	2812	X28	2A12	X38
iÃi [switching	B10 B9	0 0	A10	1B11	X09	1A11	X19	2B11	X29	2A11	X39
2B20		╶┑┌──┤──>│	B8	0 0	A9 A8	1B10	XOA	1A10	X1A	2B10	X2A	2A10	ХЗА
1. (ل ۲ ،		87 86	00	A7	189	XOB	1A9	X1B	289	X2B	2A9	ХЗВ
			20	0 0	A6 A5	1B8	XOC	1A8	X1C	2B8	X2C	2A8	ХЗС
	_		65				1		1		1		
245			B4 B2	00	A4	187	XOD	1A7	X1D	287	X2D	2A7	X3D
2A5	·· [5		B3 B3 B2	0 0 0 0 0 0	A4 A3 A2	187 186	X0D X0E	1A7 1A6	X1D X1E	287 286	X2D X2E	2A7 2A6	X3D X3E
2A5 - + 2B2	· · ∫ ∫		B3 B4 B3 B2 B1	0000	A4 A3 A2 A1	187 186 185	XOD XOE XOF	1A7 1A6 1A5	X1D X1E X1F	287 286 285	X2D X2E X2F	2A7 2A6 2A5	X3D X3E X3F
2A5 - + 2B2 12/24 VDC 2B1			B3 B4 B3 B2 B1	0 0 0 0 0 0 0 0 0	A4 A3 A2 A1	187 186 185 184	X0D X0E X0F Vacant	1A7 1A6 1A5 1A4	X1D X1E X1F Vacant	287 286 285 284	X2D X2E X2F Vacant	2A7 2A6 2A5 2A4	X3D X3E X3F Vacan
2A5 - + 2B2 12/24 VDC 2B1. 2A2			B3 B4 B3 B2 B1		A4 A3 A2 A1	187 186 185 184 183	XOD XOE XOF Vacant Vacant	1A7 1A6 1A5 1A4 1A3	X1D X1E X1F Vacant Vacant	287 286 285 284 283	X2D X2E X2F Vacant Vacant	2A7 2A6 2A5 2A4 2A3	X3D X3E X3F Vacan Vacan
2A5 - + 2B2 12/24 VDC 2B1. 2A2 2A1			B3 B4 B3 B1 B1	o o o o o o	A4 A3 A2 A1	187 186 185 184 183 182	X0D X0E X0F Vacant Vacant COM1	1A7 1A6 1A5 1A4 1A4 1A3 1A2	X1D X1E X1F Vacant Vacant	287 286 285 284 283 283 282	X2D X2E X2F Vacant Vacant COM2	2A7 2A6 2A5 2A4 2A3 2A2	X3D X3E X3F Vacan Vacan

*1 : In the pin number column, the pins beginning with "1[][]" are left connector pins and those beginning with "2[][]" are right connector pins.

*2 : With the switch set to the left side position, the status of former half devices (X00 to X1F) is displayed by LEDs. When it is set to the right side, the status of latter half devices (X20 to X3F) is displayed by LEDs.

*3 : Arrangement of pins A and B shown above is opposite to the arrangement of pins of the connector on the module.

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5.2.12 A1SX42-S2 DC input module (sink type)

	Model		DC Input Module (Sink Type)										
Specification	5	- A	1SX42	2-52						Арр	earan	ce	
Number of inp	ut points	64 points				-							
Insulation met	hod	Photocoupler]	AISX	42-52		1 I
Rated input vo	oltage	24 VDC]	415			
Rated input cu	irrent	Approx. 5 mA]				
Operating volt	age range	19 2 to 26 4 VDC (ripple: less	than	5%)]			9	
Max simultane points	eous input	50% (16 points/common) sim	ultaneously ON (at 24 VDC)										1
ON voltage/Of	N current	17 5 VDC or higher/3.5 mA o	or higher										
OFF voltage/C	OFF current	7 VDC or lower/1 7 mA or low	/er]		n f	<u>-</u>	1 1
Input impedan	ice	Approx. 4.7 kΩ			,								
Response	$OFF \rightarrow ON$	10 ms or less (24 VDC)]		2444	의	
time	ON → OFF	10 ms or less (24 VDC)]		三日		
Common term arrangement	inal	32 points/common (common	termin	als: 1B	1, 1B2	, 2B1,	2B2)						
Operating indi	Operating indicator ON state is indicated (LED				tion by	switch	n]				
External connections 40-pin connector]	떼	詣曰		ן ונ
Applicable wir	e size	0.3 mm ²]				
Accessories		Connectors (2 pces) for exte	ernal v	viring (s	olderır	ng type	;)						
Insulation with voltage	hstand	500 VAC									JF		
Noise immuni	ty	500 VAC	_								>	0	
Internal current consumption	nt (5 VDC)	90 mA (TYP, all points ON)]	DC24	V 5mA A	ISX42-52	<u> </u>
Weight kg (lb))	0 28(0.62)			1		_						
		Externa	al Cor	nnectio	ns								
External	11	nternal circuit	Pin	Arrange	nent	Pin No.	Signal Name (FH)	Pin No.	Signal Name (FH)	Pin No.	Signal Name (LH)	Pin No.	Signal Name (LH)
switch					,	1B20	X00	1A20	X10	2820	X20	2A20	X30
1111		Internal				1819	X01	1A19	X11	2B19	X21	2A19	X31
		circuit	1 1	\frown	•	1B18	X02	1A18	X12	2B18	X22	2A18	X32
	(820 B19	00	A20	1B17	X03	1A17	X13	2817	X23	2A17	X33
145		S (The second sec	B18	0 0	A18	1816	X04	1A16	X14	2B16	X24	2A16	X34
- + 182	Left	side e Indication	B17	0 0	A17 A16	1B15	X05	1A15	X15	2815	X25	2A15	X35
24 VDC	(forme	switching circuit	B15	0 0	A15	1814	X06	1A14	X16	2B14	X26	2A14	X36
1A2 -	مناعد اatte	r half) Indication	B14	0 0	A14	1B13	X07	1A13	X17	2B13	X27	2A13	X37
1A1		switching	B12	0 0	A12	1B12	X08	1 A 12	X18	2B12	X28	2A12	X38
			B11 B10	0 0	A11	1811	X09	1A11	X19	2B11	X29	2A11	X39
	Li Li	circuit	B9	0 0	A9	1810	XOA	1A10	X1A	2810	X2A	2A10	ХЗА
			B8 B7	0 0	A8 A7	1B9	XOB	1A9	X1B	289	X2B	2A9	ХЗВ
2A5	15		B6	0 0	A6	1B8	XOC	1A8	X1C	288	X2C	248	X3C
- + 282	· · · · · · · · · · · · · · · · · · ·		85 84	0 0	A5	1B7	XOD	1A7	X1D	287	X2D	2A7	X3D
24 VDC			83	0 0	A3	1B6	XOE	1A6	X1E	286	X2E	2A6	X3E
281			B1	0 0	A2	1B5	XOF	1A5	X1F	285	X2F	2A5	X3F
2A2 0			-	\square		1B4	Vacan	1A4	Vacant	284	Vacan	2A4	Vacan
2011	2A1			Front view 1B3 Vacant 1A3			Vacant	283	Vacan	(2A3	vacar		
2A1 &				Front vi	ew	163	Vacan		V docum	000	000		Vere
2A1 &				Front vi	ew 1	182	COMI	1A2	Vacant	2B2	СОМ2	2A2	Vacar

*1 : In the pin number column, the pins beginning with "1[][]" are left connector pins and those beginning with "2[][]" are right connector pins.

*2 : With the switch set to the left side position, the status of former half devices (X00 to X1F) is displayed by LEDs. When it is set to the right side, the status of latter half devices (X20 to X3F) is displayed by LEDs.

*3 : Arrangement of pins A and B shown above is opposite to the arrangement of pins of the connector on the module.

5.2.13 A1SX71 DC input module (sink/source common type)



5.2.14 A1SX80 DC input module (sink/source common type)

	Model	DC input Module (Sink/Source Common	Туре)	·	
Specification	5	A1SX80	Арреа	rance	
Number of inp	out points	16 points			
Insulation met	hod	Photocoupler	AISX80		
Rated input vo	oltage	12 VDC 24 VDC		8:	
Rated input cu	urrent	Approx. 3 mA Approx. 7 mA			
Operating volt	age range	10.2 to 26.4 VDC (ripple: less than 5%)	一 ; 🗄	8 f	
Max. simultan points	eous input	100% simultaneously ON (at 26.4 VDC)			
ON voltage/O	N current	8 VDC or higher/2 mA or higher	7 4		
OFF voltage/C	OFF current	4 VDC or lower/1 mA or lower	0		
Input impedar	nce	Approx. 3.3 kΩ		[]	
Response	$OFF \rightarrow ON$	10 ms or less (24 VDC)	2	[
time	$ON \rightarrow OFF$	10 ms or less (24 VDC)			
Common term arrangement	ninal	16 points/common (common terminals: TB9, TB18)	5		
Operating ind	icator	ON state is indicated (LEDs)	6		
External conn	ections	20-point terminal block connector (M3.5 x 7 screws)	7		
Applicable with	re size	8	1		
Applicable cri terminals	mp	1.25-3.5 1.25-YS3A 2-3.5 2-YS3A V1.25-M3 V1.25-YS3A V2-S3 V2-YS3A	9 A		
Accessories None			В		
Insulation wit voltage	hstand	500 VAC	c		
Noise immuni	Noise immunity 1000 VAC				
Internal curre consumption	nt (5 VDC)	50 mA (TYP, all points ON)	F		
Weight kg (lb)	0.2(0.44)			
		External Connections			
			Terminal No.	Signal Name	
		Internal circuit	TB1	X00	
	TB		TB2	X01	
			ТВЗ	X02	
			TB4	X03	
			TB5	X04	
			TB6	X05	
		B ↓	TB7	X06	
	• •••••••••••••••••••••••••••••••••••	Ā	TB8	X07	
1	твэ		1B9	COM	
				X08	
				X09	
			TR13	XOB	
			TR14	XOC	
			TB15	XOD	
	TB1	17	TB16	XOE	
	12/24 VDC		TB17	XOF	
	<u> </u>	°	TB18	COM	
	·- 4F		TB19	Vacant	
			TB20	Vacant	

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5. INPUT AND OUTPUT MODULES

MELSEC-A

5.2.15 A1SX80-S1 DC input module (sink/source common type)

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	Model	DC Input Module (Sink/Sou	urce Common Ty	pe)			
Specification	s	A1SX80-S1		Appea	rance		
Number of inp	out points	16 points					
Insulation met	thod	Photocoupler		A1SX80-S	1		
Rated input vo	oltage	24 VDC					
Rated input co	urrent	Approx. 7 mA			1000		
Operating volt	tage range	19.2 to 26 4 VDC (ripple less than 5%)		,			
Max. simultan points	eous input	100% simultaneously ON (at 26.4 VDC)					
ON voltage/O	N current	17 VDC or higher/5 mA or higher		0			
OFF voltage/C	OFF current	5 VDC or lower/1 7 mA or lower		1			
Input impedar	nce	Approx. 3 3 kΩ		2			
Response	OFF → ON	0 4 ms or less (24 DCV)		3			
time	ON → OFF	0 5 ms or less (24 DCV)		4			
Common term	ninal	16 points/common (common terminals. TB9, TB18)		5			
Operating ind	icator	ON state is indicated (LEDs)		6			
External conn	ections	20-point terminal block connector (M3.5 × 7 screws)	7			
Applicable wit	re size	0 75 to 1.5 mm ²		8			
Applicable cri terminals	mp	1 25-3.5 1 25-YS3A 2-3 5 2-YS3A V1.25-M3 V1 25-YS3A V2-S3 V2-YS3A		9			
Accessories		None		A			
Insulation with voltage	Accessories None Insulation withstand 500 VAC						
Noise immuni	ty	1000 VAC		D			
Internal curre consumption	nt (5 VDC)	50 mA (TYP, all points ON)		E F			
Weight kg (lb))	0.2 (0.44)					
		External connections					
				Terminal	Signal		
		Internal circuit		No.	Name		
		· · · · · · · · · · · · · · · · · · ·	_	TB1	X00		
	TB1		-	TB2	X01		
			-	TB3	X02		
			-	TB5	X04		
			F	TB6	X05		
	TBB		F	TB7	X06		
	• • • • • • • • • • • • • • • • • • •	Ă	ſ	TB8	X07		
	твэ			TB9	COM		
				TB10	X08		
				TB11	X09		
		Circuit		TB12	X0A		
				TB13	X0B		
				TB14	XOC		
1	. TB17			TB15	XOD		
	12/24 VDC		-	TB16	X0E		
	+ -TB18			TB17	XOF		
	· - * + - ·			TB18	СОМ		
	-			TB19	Vacant		
				TB20	Vccant		

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5.2.16 A1SX80-S2 DC input module (sink/source common type)

	Model	DC Input Module (Sink/Source Common T	ype)		
Specification	15	A1SX80-S2	Appear	rance	
Number of inp	out points	16 points			
Insulation met	thod	Photocoupler	AISX80-	52	
Rated input vo	oltage	24 VDC	38	8	
Rated input c	urrent	Approx. 7 mA			
Operating vol	tage range	19 2 to 26.4 VDC (ripple: less than 5%)	;8	吕 ધ	
Max. simultan points	neous input	100% simultaneously ON (at 26.4 VDC)			
ON voltage/O	N current	13 VDC or higher/3.5 mA or higher			
OFF voltage/0	OFF current	6 VDC or lower/1.7 mA or lower			
Input impedar	nce	Approx. 3.3 kΩ			
Response	$OFF \rightarrow ON$	10 ms or less (24 VDC)			
time	$ON \rightarrow OFF$	10 ms or less (24 VDC)			
Common term arrangement	ninal	16 points/common (common terminals: TB9, TB18)	5		
Operating ind	licator	ON state is indicated (LEDs)	6		
External conn	nections	20-point terminal block connector (M3.5 x 7 screws)	7		
Applicable wi	re size	0.75 to 1.5 mm ²	8		
Applicable cri terminals	imp	1.25-3.5 1.25-YS3A 2-3.5 2-YS3A V1.25-3 V1.25-YS3A V2-S3 V2-YS3A	9		
Accessories		в			
Insulation withstand 500 VAC			c		
Noise Immun	ity	1000 VAC			
Internal current consumption (5 VDC) 50 mA (TYP, all points ON)					
consumption	(5 VDC)				
consumption Weight kg (lb	(5 VDC)	0 2(0.44)			
consumption Weight kg (lb	(5 VDC)	0 2(0.44) External Connections			
consumption Weight kg (lb	(5 VDC))	0 2(0.44) External Connections Internal circuit	Terminal No.	Signal Name	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit	Terminal No. TB1	Signal Name X00	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit	Terminal No. TB1 TB2	Signal Name X00 X01	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit	Terminal No. TB1 TB2 TB3	Signal Name X00 X01 X02	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit Internal LED Internal Circuit	Terminal No. TB1 TB2 TB3 TB4	Signal Name X00 X01 X02 X03	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit Internal Circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB5	Signal Name X00 X01 X02 X03 X04 X05	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit Internal Internal Internal Internal Internal In	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6	Signal Name X00 X01 X02 X03 X04 X05 Y06	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8	Signal Name X00 X01 X02 X03 X04 X05 X06 X07	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit Internal circuit Internal circuit R R R R R R R R R R R R R R R R R R R	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10 TB11	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08 X09	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit BI R R LED LED LED LED LED LED LED LED	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10 TB11 TB12	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08 X09 X0A	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit Internal circuit R R R LED Internal circuit LED Internal circuit LED Internal circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10 TB11 TB12 TB13	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08 X09 X0A X0B	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit BI R R R Circuit LED LED LED LED Internal circuit LED LED LED LED LED LED LED LED	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10 TB11 TB12 TB13 TB14	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08 X09 X0A X0B X0C	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit Internal circuit A A Internal circuit Internal circuit Internal circuit Internal circuit Internal circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10 TB11 TB12 TB13 TB14 TB15	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08 X09 X0A X0B X0C X0D	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10 TB12 TB13 TB14 TB15 TB16	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08 X09 X0A X0B X0C X0D X0E	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit Internal circuit Internal circuit Internal circuit Internal circuit Internal circuit Internal circuit Internal circuit Internal circuit Internal circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10 TB11 TB12 TB13 TB14 TB15 TB16 TB17	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08 X09 X0A X0B X0C X0D X0E X0F	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10 TB11 TB12 TB13 TB14 TB15 TB16 TB17 TB18	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08 X09 X0A X0B X0C X0D X0F COM	
consumption Weight kg (lb		0 2(0.44) External Connections Internal circuit	Terminal No. TB1 TB2 TB3 TB4 TB5 TB6 TB7 TB8 TB9 TB10 TB11 TB12 TB13 TB14 TB15 TB16 TB17 TB18 TB19	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 COM X08 X09 X0A X0B X0C X0D X0F COM Vacant	

5. INPUT AND OUTPUT MODULES

MELSEC-A

5.2.17 A1SX81 DC input module (sink/source common type)

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	Model	DC Input Mod	ule (S	Sink/S	ource Co	ommo	on Type)		
Specifications	5	A1SX81		_				Арр	earance	
Number of inpu	ut points	32 points							_	
Insulation meth	hod	Photocoupler						A1SX81	8	
Rated input vo	ltage	12 VDC 24	VDC							
Rated input cu	rrent	Approx. 3 mA App	orox 7	7 mA						
Operating volta	age range	10 2 to 26 4 VDC (ripple: less than 5%	5)					;8;		
Max simultane	eous input	60% simultaneously ON (at 26 4 VDC))							
ON voltage/ON	N current	8 VDC or higher/2 mA or higher								-
OFF voltage/C	OFF current	4 VDC or lower/1 mA or lower								
Input impedan	се	Approx. 3.3 kΩ								` ∃'
Response	OFF → ON	10 ms or less (24 VDC)						['n –€		=
time	$ON \rightarrow OFF$	10 ms or less (24 VDC)	ms or less (24 VDC)							=
Common termi arrangement	: 17,	18, 36)							
Operating indicator ON state is indicated (LEDs)										-
External connections 37-pin D sub-connector										
Applicable wir	e size	0.3 mm ²								
Accessories	_	Connector (1 pce.) for external wiring	(sold	ering t	ype)					3
Insulation withstand 500 VAC									UE	
Noise immunit	ty	1000 VAC						- [^µ - €	<u>₽ ¶E</u>	
Internal curren consumption (nt (5 VDC)	80 mA (TYP, all points ON)						DC12/24	V 3/7mA A1S	X81
consumption (5 VDC)						-				
Weight kg (lb)		0.24(0.53)								
Weight kg (lb)		0.24(0.53) External Conne	ction	s						
Weight kg (lb))	0.24(0.53) External Conne	ction	s	Pin		Pin	Signal	Pin	Signal
Weight kg (lb)) 	0.24(0.53) External Conne Internal circuit	ction	s Arra	Pin angeme	nt	Pin No.	Signal Name	Pin No.	Signal Name
Weight kg (lb) External switch	1	0.24(0.53) External Conne Internal circuit	ction	s Arra	Pin angeme	nt	Pin No. 1	Signal Name X00	Pin No. 9	Signal Name X10 X11
Weight kg (lb) External switch	1	0.24(0.53) External Conne Internal circuit	D	s Arra	Pin angeme	nt	Pin No. 1 20	Signal Name X00 X01	Pin No. 9 28	Signal Name X10 X11 X12
Weight kg (lb)	1	0.24(0.53) External Conne Internal circuit	ction:	20 21	Pin angeme	nt	Pin No. 1 20 2 21	Signal Name X00 X01 X02 X03	Pin No. 9 28 10 29	Signal Name X10 X11 X12 X13
Weight kg (lb)	1	0.24(0.53) External Conne Internal circuit	ction:	Arr 20 21 22	Pin angemen	nt 1 2	Pin No. 1 20 2 21 3	Signal Name X00 X01 X02 X03 X04	Pin No. 9 28 10 29 11	Signal Name X10 X11 X12 X13 X14
Weight kg (lb)	1	0.24(0.53) External Conne Internal circuit		20 21 22 23	Pin angemei	nt 1 2 3 4 5	Pin No. 1 20 2 21 3 22	Signal Name X00 X01 X02 X03 X04 X05	Pin No. 9 28 10 29 11 30	Signal Name X10 X11 X12 X13 X14 X15
Weight kg (lb)	35	0.24(0.53) External Conne Internal circuit		20 21 22 23 24 25	Pin angemei	nt 1 2 3 4 5 6	Pin No. 1 20 2 21 3 22 4	Signal Name X00 X01 X02 X03 X04 X05 X06	Pin No. 9 28 10 29 11 30 12	Signal Name X10 X11 X12 X13 X14 X15 X16
External switch	35	0.24(0.53) External Conne Internal circuit	D	20 21 22 23 24 25 26	Pin angeme 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	nt 1 2 3 4 5 6 6 7 8	Pin No. 1 20 2 21 3 22 4 23	Signal Name X00 X01 X02 X03 X04 X05 X06 X07	Pin No. 9 28 10 29 11 30 12 31	Signal Name X10 X11 X12 X13 X14 X15 X16 X17
External switch	1	0.24(0.53) External Conne Internal circuit		20 21 22 23 24 25 26 27 28	Pin angeme 0	nt 1 2 3 4 5 6 7 8 9 9	Pin No. 1 20 2 21 3 22 4 23 5	Signal Name X00 X01 X02 X03 X04 X05 X06 X07	Pin No. 9 28 10 29 11 30 12 31 13	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X18
Weight kg (lb)	1 35 17 34	0.24(0.53) External Conne Internal circuit	D D	20 21 22 23 24 25 26 27 28 29	Pin angeme 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	nt 1 2 3 3 4 5 5 6 6 7 7 8 9 9 10 11	Pin No. 1 20 2 21 3 22 4 23 5 5 24	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 X08 X09	Pin No. 9 28 10 29 11 30 12 31 13 32	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X18 X19
Weight kg (lb)	1 35 17 34 18	0.24(0.53) External Conne Internal circuit	D D	20 21 22 23 24 25 26 27 28 29 30	Pin angeme 0 0 0 0 0	nt 2 3 4 5 6 6 7 7 8 9 9 10 11 11	Pin No. 1 20 2 21 3 22 4 23 5 5 24 6	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 X08 X09	Pin No. 9 28 10 29 11 30 12 31 13 32 14	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X18 X19 X1A
Weight kg (lb)	1 35 17 34 18 37 9	0.24(0.53) External Conne Internal circuit	D D	20 21 22 23 24 25 26 27 28 29 30 31 32	Pin angemei 0	nt 1 2 3 3 4 5 5 6 7 7 8 9 9 10 11 12 13 14	Pin No. 1 20 2 21 3 22 4 23 5 24 6 25	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 X08 X09 X0A X0B	Pin No. 9 28 10 29 11 30 12 31 13 32 14 33	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X18 X19 X1A X1B
Weight kg (lb)	1 35 17 34 18 37 19 9	0.24(0.53) External Conne Internal circuit	D D	20 21 22 23 24 25 26 27 28 29 30 31 32 33 32	Pin angemei 0	nt 1 2 3 3 4 4 5 6 6 7 7 7 7 7 9 9 10 11 12 13 14 15	Pin No. 1 20 2 21 3 22 4 23 5 24 6 25 7	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 X08 X09 X0A X0B X0C	Pin No. 9 28 10 29 11 30 12 31 13 32 14 33 15	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X18 X19 X1A X1B X1C
Weight kg (lb)	1 35 17 34 18 37 19	0.24(0.53) External Conne Internal circuit	D	20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35	Pin angeme 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	nt 1 2 3 3 4 5 6 6 7 7 10 11 12 13 14 15 16 16 17	Pin No. 1 20 2 21 3 22 4 23 5 24 6 25 7 26	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 X08 X09 X0A X0B X0C X0D	Pin No. 9 28 10 29 11 30 12 31 13 32 14 33 15 34	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X18 X19 X1A X1B X1C X1D
Weight kg (lb)	1 35 17 34 4 18 37 19 9	0.24(0.53) External Conne Internal circuit	D	20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36		nt 1 2 3 4 5 6 7 7 8 9 9 10 11 12 13 14 15 16 117 118	Pin No. 1 20 2 21 3 22 4 23 5 24 6 25 7 26 8	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 X08 X09 X0A X0B X0C X0D	Pin 9 28 10 29 11 30 12 31 13 32 14 33 15 34 16	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X18 X19 X1A X1B X1C X1D X1E
Weight kg (lb)	1 35 17 34 18 37 9 19	0.24(0.53) External Conne Internal circuit	D D	20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37	Pin angeme 0	nt 1 2 3 3 4 5 5 6 7 7 8 8 9 9 10 11 11 12 13 14 15 16 17 18 19	Pin No. 1 20 2 21 3 22 4 23 5 24 6 25 7 26 8 27	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 X08 X09 X00 X08 X09 X00 X00	Pin 9 28 10 29 11 30 12 31 13 32 14 33 15 34 16 35	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X16 X17 X18 X19 X1A X18 X19 X1A X1B X1C X1D X1E X1F
Weight kg (lb)	1 35 17 34 18 37 19 9	0.24(0.53) External Conne Internal circuit	D D	20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37	Pin angeme 0	nt 1 2 3 4 4 5 6 6 7 8 8 9 10 11 12 13 14 15 16 17 18 19	Pin No. 1 20 2 21 3 22 4 23 5 24 6 25 7 26 8 8 27 17	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 X08 X09 X0A X0B X0C X0D X0E X0F	Pin No. 9 28 10 29 11 30 12 31 13 32 14 33 15 34 16 35 37	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X18 X17 X18 X19 X1A X19 X1A X1B X1C X1D X1E X1F Vacant
Weight kg (lb)	1 35 17 34 18 37 19	0.24(0.53) External Conne Internal circuit	D	20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37	Pin angemei 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	nt 1 2 3 4 5 6 7 7 8 9 9 10 11 11 12 13 14 15 16 17 18 19	Pin No. 1 20 2 21 3 22 4 23 5 24 6 25 7 26 8 27 17 36	Signal Name X00 X01 X02 X03 X04 X05 X06 X07 X08 X09 X0A X0B X0C X0D X0E X0F COM	Pin 9 28 10 29 11 30 12 31 13 32 14 33 15 34 16 35 37 19	Signal Name X10 X11 X12 X13 X14 X15 X16 X17 X18 X19 X1A X1B X1C X1E X1F Vacant

5.4 Input/Output Combination Module Specifications

5.4.1 A1SH42 input/output module

	Model	Inp	ut/Output Combination Module	
Specification		Input Spe	cifications	Appearance
Number of inpu	ut points	32 points		
Insulation meth	hod	Photocoupler		
Rated input vo	ltage	12 VDC	24 VDC	
Rated input cu	rrent	Approx. 2 mA	Approx. 5 mA	7
Operating volta	age range	10.2 to 26 4 VDC (ripple less that	in 5%)	
Max. simultane	euos input	60% (20 points/common) simultar	neuosly ON (at 24 VDC)	
ON voltage/ON	l current	8 VDC or higher/2 mA or higher		
OFF voltage/O	FF current	4 VDC or lower/0.6 mA or lower		
Input impedan	ce	Approx. 5 kΩ		
Response	$OFF \rightarrow ON$	10 ms or less (24 VDC)		
time	ON → OFF	10 ms or less (24 VDC)		
Common termi arrangement	inal	32 points/common (common term	inals: 1B1, 1B2)	
Insulation with	stand voltage	500 VAC		
Noise immunity		500 VAC		
		Output Sp	ecifications	
Number of inp	ut points	32 points		
Insulation met	hod	Photocoupler		
Rated input vo	oltage	12/24 VDC		
Operating volt	age range	10.2 to 30 VDC (peak voltage 30	VDC)	
Max. load curr	rent	0.1 A/point, 1.6 A/common		
Max. input cur	rent	0.4 A 10 ms or less		
Leakage curre circuit	ent at OFF	0.1 mA or less		
Max voltage o	drop at ON	1.0 VDC (TYP) 0.1 A, 2.5 VDC (I	MAX) 0.1 A	
Response	$OFF \rightarrow ON$	2 ms or less		
time	ON → OFF	2 ms or less (resistive load)		
Surge absorbe	er	Zender diode		
Fuse rating		Fuse 3.2 A (1 piece/common), no	ot replaceable *1	
Fuse capacity	_	50 <u>A</u>		
Error display		LED goes ON when fuse blows:	signal output to PC CPU *2	
Common term arrangement	inal	32 points/common (common terr	ninals: 2A1, 2A2)	DC1224V 26 mA 0 1 A A1SH42
Insulation with	nstand voltage	500 VAC		
Noise immuni	ty	500 VAC		
External power	Voltage	12/24 VDC (10.2 to 30 VDC)		
supply	Current	8 mA (TYP 24 VDC/common)		_
		Common S	pecifications	
Number of I/C) points	32 (I/O allocation is set as a 32-	point output module)	
Operating ind	icator	ON state is indicated (LEDs), 32	-points indication by switch	
External conn	ections	40-pin connector		
Applicable with	re size	0.3 mm ²		
Accessories		Connector (2 cps.) for external v	wiring (soldering type)	
Internal curre consumption	nt (5 VDC)	500 mA (TYP, all points ON)		
Weight kg (lt))	0.27 (0.59)		

*1: The fuse in the output module is provided to prevent the external wiring form burning in case of a short in the module's output. Therefore, the fuse might not be able to protect output devices. If an output device is damaged in a failure mode other than a short circuit, the fuse might

If an output device is damaged in a failure mode other than a short circuit, the fuse migr not be blown.

*2 : The ERR. indicating LED will also light when the external power supply is shut OFF.

5.4.4 A1SX48Y18 I/O module (24 VDC input (sink type), relay contact output)

	Inpu	It Specifications	Output Specifications						
Number of in	put points	8 points	Number of out	put points	8 points				
Insulation me	thod	Photocoupler	Insulation met	hod	Photocoupler				
Rated input v Rated input o	oltage current	24 VDC, approx. 7 mA	Rated switchin and current	ng voltage	24 VDC 2 A (240 VAC 2A (8 A/common	resistive load) (COSe=1)/poin	t,		
Operating vol	ltage range	19.2 to 26 4 VDC (ripple. less than 5%)	Minimum swite	ching load	5 VDC 1mA				
ON voltage/C	N current	14 VDC or higher/3.5 mA or higher	Maximum swit	ching voltage	264 VDC 125	5 VDC			
OFF voltage/	OFF current	6.5 VDC or lower/1.7 mA or lower	Maximum swit	ching	3600 times/ho	our			
Input resistar	nce	Αρρτοχ 3.3 ΚΩ		Mechanical	20,000,000 ti	mes of switchi	ng or over		
Input method		Sink input (method by which the input current flows out)			At rated switc loads 100,000 time	ching voltage a s of switching	ind current or over		
Response	OFF → ON	10 ms or less (24 VDC)]		At 200 VAC 1	.5 A, 240 VAC	; 1 A		
time	ON → OFF	10 ms or less (24 VDC)	Service life Electrical 100,00		100,000 time	s of switching	or over		
Common me	thod	8 points/common (common terminal: TB9) At			At 200 VAC 1 (COS¢=0.35) 100,000 time	A, 240 VAC (0.5 A or over		
Operation inc	dicator	Provided (The LED lights when the input is ON.)			At 24 VDC 1 (L/R = 7 ms) 100,000 time	A, 100 VDC 0.	1 A or over		
Maximum sin	nultaneous	100 % simultaneous ON (at 26 4 VDC)	Besponse	OFF → ON	10 ms or less	3			
input points			time	ON → OFF	12 ms or less	s (resistive loa	d)		
Insulation wir voltage	thstand	500 VAC	insulation with voltage	hstand	1500 VAC	•			
Noise immur	nty	500 VAC	Noise immunity 1000 V/						
			External power supply (relay		24 VDC ±0%, ripple voltage: 4 V _{P-P} or less				
			Curre about	Current	45 mA (TYP.	24 VDC all po	oints ON)		
			Surge absorb	er	8 points/com	m02			
			Common met	hod	(common ter	minal: TB18)			
Operation In	dicator	Provided (The LED lights when the inpu	t/output is ON.))					
Internal curr	o points ent	16 points (Make I/O allocation as a 16-p	oint output mo	dule.)		•	ę		
consumption External wiri	ng	20-point terminal block connector (M3.5	x 7 screw)						
Applicable c	able size	$0.75 \text{ to } 1.5 \text{ mm}^2$							
Applicable s terminal	olderless	1.25-3 5 1.25-YS3A 2-3.5 2-YS3A V1.	.25-M3 V1.25-	YS3A V2-S3 \	/2-YS3A				
Weight kg (lb)	0.225 (0.495)							
		External	Connection	s					
		Internal circuit				Pin No.	Signal Name		
тв						TB1	X00		
0 1	R					TB2	X02		
	R	$(\Delta \tau) \langle \mathfrak{P} \rangle$		1		TB4	X03		
						TB5	X04		
24 VDC				1		186 T87	X05 X06		
└─┤ ┌─			2	TB10 External la	ad	TB8	X07		
		te te				TB9	COM1		
						TB10	X08		
				_)	1	TB12	XOA		
				17q[L]	•	T813	XOB		
			-4			TB14	XOC		
				TR 24	VDC	T815	XOE		
			K	19 + -		T817	XOF		
				20	power	TB18	COM2		
						TB19	24 VDC		
						1020			

5.4.5 A1SX48Y58 I/O module (24 VDC input (sink type), 12/24 VDC transistor output)

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Number of com	Input				Output	specific	ations	
Number of Inpu	t points		Number of ou	tput p	oints	8 points		
Insulation meth	00		Insulation me	inoa		Photocol		
Rated input voi	tage		Hated load vo	litage		12/24 VI		
Rated input cur			Operating vol	tage	range	10.2 to 3 (peak vo	30 VDC bitage 30 VDC	
Operating volta	N eutrapt	19.2 to 26.4 VDC (ripple: less than 5%)	Maximum las			0.5.4/22		
ON Voltage / O	N current	6 6 VDC or lower/1.7 mA or lower	Maximum loa			0.5 A/po	nt, 2 A/comm	on
OFF Voltage / C	JFF Current		Maximum Inru			4 A 10 II	15 01 1055	
Input resistance	e	Approx. 3.3 KΩ	circuit		0.1 mA c	Dr less		
Input method		current flows out)	ON circuit	age o	srop at	0.9 V (1 1.5 V (M	14X.) 0.5 A	_
Response	OFF → ON	10 ms or less (24 VDC)	Response	OFF	→ ON	2 ms or	less	
1					2 ms or	less (resistive	load)	
Insulation withs	stand voltage	500 VAC	Insulation withstand voltage		500 VAC	<u> </u>		
Noise immunity	/	500 VAC	Noise immuni	ity	r	500 VAC	<u> </u>	
Common metho	od	8 points/common	External power Vo		Voltage	12/24 VI	DC (10.2 to 30	VDC)
			supply		Current	60 mA (TYP. 24 VDC	per common)
Operation indic	ator	Provided (The LED lights when the input is ON.)	Surge absorb	er		Zener dı	ode	
Maximum simu points	Itaneous input	100 % simultaneous ON (at 26.4 VDC)	Fuse rating			Fuse 3.2 replaces	2 A (1 per com able	mon) Not
			Fuse breaking	g cap	acity	5.0 A		
			Common met	hod		8 points. (commo	/common n terminal: TB	19)
Operation Indic	ator	Provided (The LED lights when the input	/output is ON.)					
Number of I/O	points	16 points (Make I/O allocation as a 16-po	oint output mo	dule.)				
Internal current consumption (5	t 5 VDC)	60 mA (TYP, all points ON)	·					
External wiring	connection	20-point terminal block connector (M3.5	x 7 screw), 2 c	onne	ctors			
Applicable cab	le size	0.75 to 1.5 mm ²						
Applicable solo	terless terminal	1.25-3.5 1.25-YS3A 2-3.5 2-YS3A V1.	25-M3 V1.25-	YS3A	V2-S3 V2	2-YS3A		
Weight kg (lb)		0.2 (0 44)						
		External Cor	nnections					
							Pin No	Signal Name
		internal circuit					TB1	X00
] 8T					[TB2	X01
						ļ	<u>T83</u>	X02
	R ()	$\Delta(\mathbf{x}) \mid \langle \mathbf{y} \rangle$					<u>TB4</u>	X03
						ļ	T85	X04
24 V0		Serge o	sbeorber		External lood		186	<u>X05</u>
	3-1-			1910	-[]		16/ TBA	X00
					/		TB9	COM1
			卒				TB10	Yoa
		(± t) ']					TB11	Y09
L				1	1	(TB12	YOA
1			<u> </u>	™17 ↓	-{[]}		TB13	YOB
1		ERR.LED		1B18			TB14	YOC
1		<u>ح</u>	. ``	I			T815	YOD
1		T I		ļ	ļ		TB16	YOE
1	-	Ÿ ()	♥♀)│				TB17	YOF
L	_ _ !	inpr detecting					TB18	12/24 VDC
				7819	12/24 V DC		TB19	COM2
to the f							TB20	Vacant
The fu wiring There If an o circuit	form burning form burning fore, the fuse output device i , the fuse mig	but module is provided to prevent th g in case of a short in the module might not be able to protect output o s damaged in a failure mode other th ht not be blown.	e external e's output. devices. an a short					

*2: The ERR. indicating LED will also light when the external power supply is shut OFF.

5. INPUT AND OUTPUT MODULES

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5.4.6 A1S42X dynamic input module

	Model			Dynamic Input	Module				
Specifications			A1S	42X			Appear	ance	
Number of output poin	nts *1	16/32/48/64 pc	oints (switch set	ting)					
Insulation method		Photocoupler		0,		Г	A15X42		
Rated input voltage		12 VDC		24 VDC			199		
Rated input current		Approx. 4 mA		Approx. 9 mA			33	BB	
Operating voltage ran	ge	10.2 to 26 4 V	DC (ripple : less	than 5 %)	· ·	Ļ	-0-0		
Max. simultaneous inp	out points	100 % simultar	neously ON (at	26.4 VDC)					
ON voltage/ON current	nt	8 VDC or high	er/2 mA or high	er		L	<u> </u>		
OFF voltage/OFF curr	rent	4 VDC or lowe	r/1 mA or lower	¥			DB.F		
Input impedance		Approx. 2.4 kg	2				5.0. E.		
Dessesse time	$OFF \rightarrow ON$	0.4 ms or less	(24 VDC)				1		
Response time	$ON \rightarrow OFF$	0.4 ms or less	(24 VDC)						
Dynamic scan cycle		13.3 ms					ിര		
Operating indicator		On state is ind	licated (LEDs),	32-points indicatio	on by switch				
External connections		24-pin connec	tor						
Applicable wire size		0 3 mm ²							
Accessories		Connector (1 p	oce.) for externa	al wiring (soldering	type)				
Insulation withstand v	oltage	500 VAC							
Noise immunity		500 VAC							
Internal current consumption (5 VDC)		80 mA (TYP, a	all points ON)						
Weight kg (lb)		0.18 (0.40)							
			External Conne	ctions					
Input terr X38 X30 X28 X20 X X39 X31 X29 X21 X X34 X32 X24 X22 X X38 X33 X29 X23 X X38 X33 X29 X23 X X37 X34 X32 X24 X X37 X35 X30 X25 X X37 X35 X30 X X37 X35 X30 X X37 X35 X30 X X37 X35 X X37 X X X X X X X X X X X X X X X X X X X	minals (18 X10 X08 X00 (19 X11 X09 X01 (14 X12 X0A X02 (14 X12 X0A X02 (14 X12 X0A X02 (14 X12 X0A X02 (14 X12 X0A X02 (15 X14 X0C X0A (15 X14 X0C X0A	Pin No B12 XD0 A12 XD1 B11 XD2 A11 XD3 B10 XD4 A10 XD5 B9 XD6 A9 XD7 B8 XSCN0 A8 XSCN1 B7 XSCN2 A7 XSCN3 B6 XSCN4		Internal circuit	Scanned internally at 1/8 duty	Pin No. B12 B11	312 0 311 0 310 0 38 0 88 0 89 0 88 0 88 0 88 0 89 0 88 0 89 0 89 0 89 0 88 0 89 0 80	• A1: • A1: • A1: • A1: • A1: • A1: • A1: • A1: • A1: • A2: • A1: • A2: • A2: • A3: • A2: • A1: • A1: • A1: • A1: • A1: • A1: • A2: • A1: • A1:•	Signal Nane XD1 XD3
		A6 XSCN5				B10	XD4	A10	XD5
		85 XSCN6				B9	XD6	A9	XD7
		45 YEON7	{			B8	XSCNO	AB	XSCN1
		X5UN/			,	P7	VECHO	A7	YSCNO
						B/	ASCN2	A/	XOCH3
		B3, A3	11		1	B6	XSCN4	A6	XSCN5
	12/24 VDC++					B5	XSCN6	A5	XSCN7
	- [82, A2	t1			B4	Vacant	A4	Vacant
						B3	12/24 VDC	A3	12/24 VDC
	mante diede *-	oach awitch wh	en there is a co	se that 2 or more	+	B2	0V	A2	٥V
switches are	pressed simultan	eously. (Refer to	o the figure on th	ne right.)		B1	FG	A1	FG
(1) Number of occupied I/O points setting

The Number of occupied I/O points is set by the DIP switches on the front surface of the module. It is factory-set to 64 points.

Number of occupied I/O points	16 points	32 points	48 points	64 points
Switch setting	sw 1 2 3		SW 1 2 2 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3	sw 1 2 2 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3

(2) Dynamic scan method

In the dynamic scan method, the whole number of occupied I/O points is divided into several groups of specified number of points, and processed in several scans. 64 input points are divided into 8 groups of 8 points, and processed by group as shown in the figure below. Even if the number of occupied I/O points is set at 16, 32, or 48 points, dynamic scan cycle is fixed at 13.3 ms.



5.4.7 A1S42Y dynamic output module



(1) Number of occupied I/O points setting

The number of occupied I/O points is set by the DIP switches on the front surface of the module. It is factory-set to 64 points.

Number of occupied I/O points	16 points	32 points	48 points	64 points	
Switch setting	SW 1 2 N	SW 1 2 0 0	sw 1 2	sw 1 2 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3	

- (2) Dynamic scan method and dynamic scan cycle setting
 - (a) Dynamic scan method

In the dynamic scan method, the whole number of occupied I/O points is divided into several groups of specified number of points, and processed in several scans. 64 input points are divided into 8 groups of 8 points, and processed by group as shown in the figure below. Even if the number of occupied I/O points is set at 16, 32, or 48 points, dynamic scan cycle is fixed at 13.3/106.7 ms.



- (b) Dynamic scan cycle setting
 - Dynamic scan cycle is set by the DIP switches on the rear surface of the module. It is factory-set to FAST mode.

FAST mode	SLOW mode
SW Module top	sw

5. INPUT AND OUTPUT MODULES

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5.5 Blank Cover (A1SG60), Dummy Module (A1SG62) Specifications

The A1SG60 blank cover is used to protect base unit vacant slots against dust etc.

The A1SG62 dummy module is used to reserve a specified number of I/O points at any base unit slot.

 Table 5.1 Dummy Module, Blank Cover Specifications

Model	A1SG60	A1SG62
Occupying I/O points	16 points	Max. 64 (16, 32, 48, or 64 points can be selected by using a select switch on the front of the module.)
I/O allocation specification	16 vacant points	[] input (X) points Designate the number of points set with the select switch in the []
Purpose of use	Used as a dust preventive cover of an unused slot where no input/output module is installed (e. g., a vacant slot between modules).	A module used to reserve 16, 32, 48, or 64 points for the I/O module to be installed in the future.
Other functions		Being equipped with simulation switches for 16 points beginning with the head of I/O numbers, inputs can be turned ON/OFF without using any external switch.
Internal current consumption (5 VDC)	_	60 mA
Outside dimensions (mm)(in)	130(H) x 34.5(W) x 93.6 (D) (5.12 x 1.36 x 3.69)	130(H) x 34.5(W) x 93.6 (D) (5.12 x 1.36 x 3.69)
Weight (kg)(lb)	0 08 (0.18)	0 13 (0.29)

5.6 Names of Parts and Settings



The figures and table below describe the names of parts of I/O modules.

REMARK

When pulling out the terminal symbol card, pick up the edge of the card a little to pull it out smoothly from the terminal cover.

5. I/O MODULES



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5. I/O MODULES

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6. EXTENSION BASE UNIT AND EXTENSION CABLE

6.1 Specifications

6.1.1 Specifications of extension base units

Table 0.1 Extension base unit opecification	Table 6.1	Extension	Base Unit	Specifications
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ltem Model	A1S65B(S1)	A1S68B(S1)	A1S52B(S1)	A1S55B(S1)	A1S58B(S1)		
Loaded I/O modules	5 can be loaded	8 can be loaded	2 can be loaded	5 can be loaded	8 can be loaded		
Power supply module loading	Required		Not required				
Installation hole size	φ6-mm (0.24 inch)	o6-mm (0.24 inch) slot (for M5 screw)					
Terminal screw size	_		M4 x 6 (FG terminal)				
Applicable wire size			0.75 to 2 mm ²				
Applicable solderless terminal size		_	(V)1.25-4, (V)1.25-YS4, (V)2-YS4A (Applicable tightening torque: 12 kg/cm (67.1 lb/inch)				
External dimensions mm(inch)	315 x 130 x 28 (12.40 X 5.12 X 1 10)	420 x 130 x 28 (16.54 X 5.12 X 1.10)	135 x 130 x 28 (5.31 X 5 12 X 1.10)	260 x 130 x 28 (10.24 X 5.12 X 1.10)	365 x 130 x 28 (14.37 X 5.12 X 1.10)		
Weight kg(lb)	0.71 (1.56)	0.95 (2.09)	0.38 (0.84)	0.61 (1.34)	0.87 (1.91)		
Accessory	Four mounting sc	rews (M5 x 25)	*1 One dustproof cover (for I/O module) Four mounting screws (M5 x 25)				

*1: For the installation of the dustproof cover, see Section 8.6.

POINT

When using either base unit A1S52B(S1), A1S52B(S1) or A1S58B(S1) which do not require supply module, refer to Section 6.1.3.

6.1.2 Specifications of extension cables

Table 6.2 shows the specifications of extension cables which can be used for the A1SJCPU system.

Model Item	A1SC01B	A1SC03B	A1SC07B	A1SC12B	A1SC30B	A1SC60B	A1SC05NB	A1SC07NB			
Cable length m(ft)	0.055 (0.18)	0.33 (1.08)	0.7 (2.3)	1.2 (3.94)	3.0 (9.84)	6.0 (19.68)	0.45 (1.48)	0.7 (2.3)			
Resistance value of 5 VDC supply line (Ω at 55 °C)	0.02	0.021	0.036	0.055	0.121	0.182	0.037	0.045			
Application	Connection	Connection between A1SJCPU and A1S5[]B(S1)/A1S6[]B(S1) A1SJCPU and A5[]B/A6[]B									
Weight kg(lb)	0.025 (0.055)	0.1 (0.22)	0.14 (0.31)	0.20 (0 44)	0.4 (0.88)	0.65 (1.43)	0.2 (0.44)	0.22 (0.48)			

Table 6.2 Extension Cable Specifications

(a) If an extension base unit is installed (by series connection) after the A1SJCPU, use an extension cable with a length of 0.7 m (27.56 in.) or greater.

(b) When using an extension cable, do not bundle it together with main circuit (high voltage, large current) wires or allow it to run close to such lines.

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6.1.3 Application standards of extension base unit (A1S52B(S1), A1S55B(S1), A1S58B(S1), A52B, A55B, A58B)

When an extension base unit of models A1S52B(S1), A1S55B(S1), A1S58B(S1), A52B, A55B, or A58B is used, make sure a voltage of 4.75 V or above is supplied to the receiving end (at the module installed in the last slot of the extension base unit).

With the A1S52B(S1), A1S55B(S1), A1S58B(S1), A52B, A55B, or A58B extension base unit, 5 VDC is supplied from the power supply module of the main base unit via extension cable. Therefore, some voltage drop occurs over the extension cable and the specified voltage is not supplied to the receiving end, resulting in mis-input and mis-output.

If the voltage at the receiving end is less than 4.75 V, use an extension base unit of models A1S65B(S1), A1S68B(S1), A65B, or A68B equipped with a power supply unit.

(1) Selection conditions

The voltage received by the module installed in the last slot of an extension base unit A1S52B(S1), A1S55B(S1), A1S58B(S1), A52B, A55B, or A58B must be 4.75 V or above.

Since the output voltage of the power supply module is set at 5.1 V or above, the voltage drop must be 0.35 V or less.

(2) Classification of voltage drop

Voltage drop is classified into (a), (b), and (c) as follows according to the connecting method and type of extension base units.

- (a) Voltage drop of an A1SJCPU
- (b) Voltage drop of an extension base unit
- (c) Voltage drop over an extension cable



(3) Calculation of the receiving-end voltage

	0	1	2	3	4		8	9	10	11	12	13	14	15			
A1SJCPU																	
VCPU	v₀	V1	V2	V3	V₄		v8	٧٩	V10	V11	V12	V13	V14	V15			
ICPU	lo	11	12	13	14		I8	19	I10	111	112	113	114	115			
VCPU, Vot	o V	4	: V u	olta nit	ge	dro	p a	t re	spe	ectiv	ve s	slot	of t	he	A1SJCF	۰U	
ICPU, Io to	14		: C A	urre 1S.	ent JCF	cor νU ι	ısuı unit	mpt	ion	at	resp	bec	tive	slo	t of the		
V8 to V15			: V	olta	ige	dro	p a	t re	spe	ectiv	ve s	slot	of t	the	extensio	on bas	e unit
la to I15			: C e	urr xte	ent nsid	cor on t	nsu	mpt e ur	ion nit	at	res	pec	tive	e slo	ot of the		

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- (a) Voltage drop of the A1SJCPU Each slot of an A1SJCPU has a resistance of 0.022Ω . Calculate voltage drop of each slot, and obtain the total voltage drop of the unit.
 - 1) Voltage drop of the CPU unit: VCPU

 $V_{CPU} = 0.022 \times (0.4 + l_0 + l_1 + l_2 + l_3 + l_4 + l_8 + l_9 + l_{10} + l_{11} + l_{12} + l_{13} + l_{14} + l_{15})$

2) Voltage drop of slot 0: Vo

 $V_0 = 0.022 \times (I_0 + I_1 + I_2 + I_3 + I_4 + I_8 + I_9 + I_{10} + I_{11} + I_{12} + I_{13} + I_{14} + I_{15})$

3) Voltage drop of slot 1: V1

 $V_1 = 0.022 \times (l_1 + l_2 + l_3 + l_4 + l_8 + l_9 + l_{10} + l_{11} + l_{12} + l_{13} + l_{14} + l_{15})$

4) Voltage drop of slot 2: V₂

 $V_2 = 0.022 \times (I_2 + I_3 + I_4 + I_8 + I_9 + I_{10} + I_{11} + I_{12} + I_{13} + I_{14} + I_{15})$

5) Voltage drop of slot 3: V₃

 $V_3 = 0.022 \times (I_3 + I_4 + I_8 + I_9 + I_{10} + I_{11} + I_{12} + I_{13} + I_{14} + I_{15})$

6) Voltage drop of slot 4: V4

 $V_4 = 0.022 \times (I_4 + I_8 + I_9 + I_{10} + I_{11} + I_{12} + I_{13} + I_{14} + I_{15})$

7) Total voltage drop of the A1SJCPU: VK

 $V_{K} = V_{CPU} + V_{0} + V_{1} + V_{2} + V_{3} + V_{4}$

(b) Voltage drop of an extension base unit (A1S52B(S1), A1S55B(S1), A1S58B(S1))

Each slot of an extension base unit has a resistance of 0.006 Ω .

Calculate voltage drop of each slot, and obtain the total voltage drop of a base unit.

1) Voltage drop of slot 8: V₈

 $V_{8} = 0.006 \times (I_{8} + I_{9} + I_{10} + I_{11} + I_{12} + I_{13} + I_{14} + I_{15})$

2) Voltage drop of slot 9: V9

 $V_9 = 0.006 \times (l_9 + l_{10} + l_{11} + l_{12} + l_{13} + l_{14} + l_{15})$

3) Voltage drop of slot 10: V₁₀

 $V_{10} = 0.006 \times (|_{10} + |_{11} + |_{12} + |_{13} + |_{14} + |_{15})$

4) Voltage drop of slot 11: V11

 $V_{11} = 0.006 \times (I_{11} + I_{12} + I_{13} + I_{14} + I_{15})$

5) Voltage drop of slot 12: V₁₂

 $V_{12} = 0.006 \times (l_{12} + l_{13} + l_{14} + l_{15})$

6) Voltage drop of slot 13: V₁₃

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7) Voltage drop of slot 14: V14

 $V_{14} = 0.006 \times (I_{14} + I_{15})$

8) Voltage drop of slot 15: V_{15}

 $V_{15} = 0.006 \times (I_{15})$

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9) Voltage drop of an extension base unit: Vz

 $V_Z = V_8 + V_9 + V_{10} + V_{11} + V_{12} + V_{13} + V_{14} + V_{15}$

.

(c) Voltage drop over extension cables

 $V_{C} = (Resistance of an extension cable) x (I_8 + I_9 + I_{10} + I_{11} + I_{12} + I_{13} + I_{14} + I_{15})$

(d) Voltage at the receiving end

 $(5.1 - V_{K} - V_{Z} - V_{C}) \ge 4.75$ (V)

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POINT

If 3 extension base units are installed, determine the voltage at the receiving end as follows:

(1) Calculation of voltage drop at the A1SJCPU

Determine the voltage drop at individual slots by multiplying the resistance of one slot $(0.022 \ \Omega)$ by the [sum of current consumptions of all slots in the AISJCPU + sum of current consumptions of all slots in the 1st, 2nd and 3rd extension base units], then sum the voltage drops at the individual slots.

(2) Calculation of voltage drop at 1st extension base unit

Determine the voltage drop at individual slots by multiplying the resistance of one slot (0.006Ω) by the [sum of current consumptions of all slots in the 1st extension base unit + sum of current consumptions of all slots in the 2nd and 3rd extension base units], then sum the voltage drops at the individual slots.

(3) Calculation of voltage drop at 2nd extension base unit

Determine the voltage drop at individual slots by multiplying the resistance of one slot $(0.006 \ \Omega)$ by the [sum of current consumptions of all slots in the 2nd extension base unit + sum of current consumptions of all slots in the 3rd extension base unit], then sum the voltage drops at the individual slots.

(4) Calculation of voltage drop at 3rd extension base unit

Determine the voltage drop at individual slots by multiplying the resistance of one slot $(0.006 \ \Omega)$ by the [sum of current consumptions of all slots in the 3rd extension base unit], then sum the voltage drops at the individual slots.

(5) Calculation of voltage drop in the extension cable

Calculate the sum of (a) + (b) + (c):

- (a) (Resistance of the extension cable that connects the AISJCPU and 1st extension base unit) x (sum of current consumptions of 1st, 2nd and 3rd extension base units)
- (Besistance of the extension cable that connects the 1st extension base unit and 2nd extension base unit) x (sum of current consumptions of 2nd and 3rd extension base units)
- (c) (Resistance of the extension cable that connects the 2nd extension base unit and 3rd extension base unit) x (total current consumption of 3rd extension base unit)
- (6) Checking the voltage at the receiving end
 - 5.1 (sum of (1) through (5)) \ge 4.75 (V)

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- (4) Examples



(a) Voltage drop of an A1SJCPU

 $V_{\rm K} = 0.022 \times \{0.4 + (0.27 \times 5) \times 2 + (0.27 \times 4) + (0.27 \times 3) + (0.27 \times 2) + 0.27 + (0.05 \times 8) \times 6\} = 0.1804$

(b) Voltage drop of an extension base unit

 $Vz = 0.006 \times 0.05 \times (8 + 7 + 6 + 5 + 4 + 3 + 2 + 1) = 0.0108$

(c) Voltage drop over an extension cable

 $Vc = 0.036 \times (0.05 \times 8) = 0.0144$

(d) Voltage at the receiving end

5.1 - 0.1804 - 0.0108 - 0.0144 = 4.8944 (V) Since the voltage at the receiving end is more than 4.75 V, the above system can be put into operation.

(5) Minimizing the voltage drop

Try the following to minimize the voltage drop.

(a) Change the positions of modules.

Install the modules beginning with slot 0 of an A1SJCPU in the order of current consumption from large to small. Install the modules of small current consumption to extension base units.

(b) Use a short cable for extension.

The shorter an extension cable, the smaller the resistance it has, consequently minimizing its voltage drop. Make extension cables as short as possible.

6.2 Names and Purposes of Parts and Settings



The names and purposes of parts of the base units are explained below.

6.3 Extension Base Number Setting (A1S[][]B-S1 Extension Base Units Only)

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This section describes the method for setting the extension base unit numbers when extension base units are used.



Extension base unit number setting

		Setting	
	1st	2nd	3rd
Setting of number- setting connectors	TUNIT 7 1 2 2 3 0 0 3 3 0 0 3 3 0 0 3 3 0 0 3 3 0 0 1 3 1 1 1 2 1 1 1 2 1 2 1 3 1 1 1 2 1 3 1 1 1 2 1 3 1 1 1 2 1 3 1 1 1 1	Г UNIT ¬ 1-00-1 2-00-2 3-00-3	

POINT

Set one of the connectors, 1 through 3, whose number corresponds to the number to be set for the extension base unit. Do not set more than one connector, set the same connector number at more than one unit, or fail to set any connector number, since erroneous inputs and outputs will result.

6.4 Installing a DIN Rail

Both the main base units and extension base units are equipped with hooks used for mounting to a DIN rail.

The following explains the method of mounting a DIN rail:

- (1) Applicable DIN rails type
 - (a) form and dimentions



w	н		
(1 Seinch)	7.5mm(0.30inch)		
35mm(1.38inch)	15mm(0.60inch)		

(b) material

Material	Applicable Dimension (W x H) mm(inch)
Iron	35 x 7.5(1.38 x 0.30), 35 x 15(1.38 x 0.60)
Aluminum	35 x 7.5(1.38 x 0.30)

(2) Intervals of mounting screws

When a dimension 35×7.5 rail is mounted, fix it with screws with intervals of 200 mm or less between each of the screws.



- (3) Mounting to/removal from a DIN rail
 - (a) Mounting procedure

Mount a base unit to a DIN rail as follows:

- 1) Engage the hook of the base unit with the rail from above.
- 2) Push the base unit onto the rail to secure it in position.



(b) Removing procedure

Remove a base unit from a DIN rail as follows:

- 1) Pull down the bottom hook of the base unit using a flat blade screwdriver (6 x 100).
- 2) Pull the base unit away from the rail while pulling down the bottom hook.



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7. MEMORY ICs AND BATTERY

7.1 Memory ICs

This section describes specifications, handling instructions and installation of the memory ICs used in the A1SJCPU.

7.1.1 Specifications

Table 7.1 shows specifications of the ROMs.

ltem Model	A1SMCA-2KE	A1SMCA-8KE	A1SMCA-8KP		
Memory specifications	EEP-ROM		EP-ROM		
Memory capacity (bytes)	8 K bytes (max. 2 K steps)	32 K bytes (max. 8 K steps)	32 K bytes (max. 8 K steps)		
Outside dimension mm (in)	15 x 68.6 x 42 (0.59 x 2.7 x 1.65)				
Weight (kg) (lb)	0.03 (0 06)				

Table 7.1 Memory Specifications

7.1.2 Handling instructions

- (1) Handle with care memory cassettes and pin connectors since their plastic body cannot resist strong impacts.
- (2) Do not remove the printed circuit board from the memory cassette.
- (3) Use caution not to let chips of wires and other foreign material enter the memory cassette.
- (4) When installing a memory cassette to an A1SJCPU unit, engage the connectors securely.
- (5) Never place the memory on metal, which may allow current flow, or on an object which is charged with static electricity, such as wood, plastic vinyl, fiber, cable and paper.
- (6) Do not touch or bend the memory leads.
- (7) Do not touch by hand the connector of a memory cassette. Touching it by hand may lead to incomplete contact.

IMPORTANT

- (1) Always turn OFF the power to the A1SJCPU unit when installing or removing a memory cassette. If a memory cassette is installed or removed with the power to the CPU ON, contents of the memory will be destroyed.
- (2) If the power is turned ON when the memory cassete is installed, the contents of the RAM memory incorporated in the A1SJCPU is overwritten.

If the contents of the RAM memory needs to be saved, install a memory cassette after making a backup of the contents using a peripheral device.

7.1.3 Installing and removing a memory cassette

Follow the procedures below when installing or removing a memory cassette.

(1) Installing a memory cassette



- (a) Hold a memory cassette vertically so that its model name is right side up and its connector faces the A1SJCPU unit. Insert the memory cassette all the way in the A1SJCPU unit so that the hooks of the memory cassette are completely engaged (they "click").
- (b) Make sure the hooks are completely engaged. (If the memory cassette is not inserted all the way, the front lid of the A1SJCPU cannot be closed.)
- (2) Removing a memory cassette



(a) Pull out the memory cassette while pushing the hook releasing lugs that are provided at the top and the bottom of the memory cassette.

7.1.4 Writing a sequence program to an A1SMCA-8KP

A sequence program can be written to, or erased from, an A1SMCA-8KP using a ROM writer/eraser.

If an A1SMCA-8KP is installed to the ROM socket of an A6GPP or A6WU, use a memory write adaptor (A6WA-28P).

Use an A6WA-28P as follows:

- (1) Install an A1SMCA-8KP to an A6WA-28P so that their connectors couple correctly with each other.
- (2) Install the A6WA-28P that is coupled with an A1SMCA-8KP to the ROM socket of an A6GPP or A6WU. The pin next to the cut corner of the A6WA-28P is pin No. 1. Make sure the A6WA-28P is installed correctly to the ROM socket.



7.2 Battery

7.2.1 Specifications

Table 7.2 shows specifications of the battery used to retain memory stored if power failure occurs.

 Table 7.2 Battery Specifications

Item Model	A6BAT
Normal voltage	3.6 VDC
Guaranteed life	5 years
Application	For IC-RAM memory backup and power failure compensation function
External dimen- sion mm(in)	φ16(0.63)×30(1.18)

7.2.2 Handling instructions

- (1) Do not short circuit.
- (2) Do not disassemble.
- (3) Do not expose to open flame.
- (4) Do not heat.
- (5) Do not solder its terminals.
- (6) Route the battery cable as shown below so that the battery connector is not strained.

7.2.3 Installation

Battery lead connector is disconnected from the battery connector on the A1SJCPU board to prevent discharge during transportation and storage.

Before starting the A1SJCPU, plug the battery connector into the battery connector on the A1SJCPU board.

- To use a sequence program stored in the user program area in the A1SJCPU if a power failure occurs.
- To retain the data if a power failure occurs.



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7) Voltage drop of slot 14: V₁₄

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 $V_{14} = 0.006 \times (I_{14} + I_{15})$

8) Voltage drop of slot 15: V15

 $V_{15} = 0.006 \text{ x} (I_{15})$

9) Voltage drop of an extension base unit: Vz

 $V_Z = V_8 + V_9 + V_{10} + V_{11} + V_{12} + V_{13} + V_{14} + V_{15}$

(c) Voltage drop over extension cables

 $V_{C} = (Resistance of an extension cable) \times (I_8 + I_9 + I_{10} + I_{11} + I_{12} + I_{13} + I_{14} + I_{15})$

(d) Voltage at the receiving end

 $(5.1 - V_{K} - V_{Z} - V_{C}) \ge 4.75$ (V)

POINT

If 3 extension base units are installed, determine the voltage at the receiving end as follows:

- (1) Calculation of voltage drop at the A1SJCPU
 - Determine the voltage drop at individual slots by multiplying the resistance of one slot (0.022Ω) by the [sum of current consumptions of all slots in the AISJCPU + sum of current consumptions of all slots in the 1st, 2nd and 3rd extension base units], then sum the voltage drops at the individual slots.
- (2) Calculation of voltage drop at 1st extension base unit

Determine the voltage drop at individual slots by multiplying the resistance of one slot (0.006Ω) by the [sum of current consumptions of all slots in the 1st extension base unit + sum of current consumptions of all slots in the 2nd and 3rd extension base units], then sum the voltage drops at the individual slots.

(3) Calculation of voltage drop at 2nd extension base unit

Determine the voltage drop at individual slots by multiplying the resistance of one slot $(0.006 \ \Omega)$ by the [sum of current consumptions of all slots in the 2nd extension base unit + sum of current consumptions of all slots in the 3rd extension base unit], then sum the voltage drops at the individual slots.

(4) Calculation of voltage drop at 3rd extension base unit

Determine the voltage drop at individual slots by multiplying the resistance of one slot (0.006Ω) by the [sum of current consumptions of all slots in the 3rd extension base unit], then sum the voltage drops at the individual slots.

(5) Calculation of voltage drop in the extension cable

Calculate the sum of (a) + (b) + (c):

- (a) (Resistance of the extension cable that connects the AISJCPU and 1st extension base unit) x (sum of current consumptions of 1st, 2nd and 3rd extension base units)
- (b) (Resistance of the extension cable that connects the 1st extension base unit and 2nd extension base unit) x (sum of current consumptions of 2nd and 3rd extension base units)
- (c) (Resistance of the extension cable that connects the 2nd extension base unit and 3rd extension base unit) x (total current consumption of 3rd extension base unit)
- (6) Checking the voltage at the receiving end
 - 5.1 (sum of (1) through (5)) \ge 4.75 (V)

7. EXTENSION BASE UNIT AND EXTENSION CABLE

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(4) Examples



(a) Voltage drop of an A1SJCPU

 $V_{K} = 0.022 \times \{0.4 + (0.27 \times 5) \times 2 + (0.27 \times 4) + (0.27 \times 3) + (0.27 \times 2) + 0.27 + (0.05 \times 8) \times 6\} = 0.1804$

(b) Voltage drop of an extension base unit

 $V_Z = 0.006 \times 0.05 \times (8 + 7 + 6 + 5 + 4 + 3 + 2 + 1) = 0.0108$

(c) Voltage drop over an extension cable

 $V_{C} = 0.036 \times (0.05 \times 8) = 0.0144$

(d) Voltage at the receiving end

5.1 - 0.1804 - 0.0108 - 0.0144 = 4.8944 (V) Since the voltage at the receiving end is more than 4.75 V, the above system can be put into operation.

(5) Minimizing the voltage drop

Try the following to minimize the voltage drop.

(a) Change the positions of modules.

Install the modules beginning with slot 0 of an A1SJCPU in the order of current consumption from large to small.

Install the modules of small current consumption to extension base units.

(b) Use a short cable for extension.

The shorter an extension cable, the smaller the resistance it has, consequently minimizing its voltage drop. Make extension cables as short as possible.

7.2 Names and Purposes of Parts and Settings



The names and purposes of parts of the base units are explained below.

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7.3 Extension Base Number Setting (A1S[][]B-S1 Extension Base Units Only)

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This section describes the method for setting the extension base unit numbers when extension base units are used.

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Extension base unit number setting

/	Setting			
	1st	2nd	3rd	
Setting of number- setting connectors	F UNIT	⊂ UNIT ¬ 1+00+1 2+ 00 +2 3+00+3		

POINT

Set one of the connectors, 1 through 3, whose number corresponds to the number to be set for the extension base unit. Do not set more than one connector, set the same connector number at more than one unit, or fail to set any connector number, since erroneous inputs and outputs will result.

7.4 Installing a DIN Rail

Both the main base units and extension base units are equipped with hooks used for mounting to a DIN rail.

The following explains the method of mounting a DIN rail:

(1) Applicable DIN rails (JIS-C2B12)

TH35-7.5 Fe TH35-7.5 Al TH35-15 Fe

(2) Intervals of mounting screws

When a TH35-7.5 Fe or TH35-7.5 Al rail is mounted, fix it with screws with intervals of 200 mm or less between each of the screws.



8. LOADING AND INSTALLATION

8.1 Installation Environment

Avoid the following places when installing the A1SJCPU system:

- (1) Places where ambient temperature is out of 0 to 55 °C range.
- (2) Places where ambient humidity is out of 10 to 90 %RH range.
- (3) Places where dewing (condensation) occurs due to sudden temperature changes.
- (4) Places where corrosive or inflammable gas exists.
- (5) Places where a large amount of dust, iron powder and other conductive power, oil mist, salt, of organic solvent exists.
- (6) Places exposed to direct sunlight.
- (7) Places where a strong electric or magnetic field exists.
- (8) Places where mechanical vibrations of impacts are transmitted directly to the module body.

8.2 Calculation of Heat Generated by the Programmable Controller System

The operating ambient temperature inside the panel in which the programmable controller is installed must be kept below 55 °C. In order to design heat-dissipating measures inside the panel where the PC is installed, the average power consumption (amount of heat generated) of the units and equipment inside the panel must be known. The method for determining the average power consumption of the A1SJCPU system is presented here. Calculate the temperature rise inside the panel from this power consumption

Average power consumption

Power is consumed by the following PC parts:



(1) Power consumption of a power supply module

Approximately 70% of the power supply module current is converted into power and 30% of that 70% is dissipated as heat, i.e., 3/7 of the output power is actually used:

 $Wpw = \frac{3}{7} \{ (1_{5V} \times 5) + (1_{24V} \times 24) \} \quad (W)$

15V : 15V= 5 VDC logic circuit current consumption of each module

124V : 124V= Average current consumption of 24 VDC for output module internal consumption (with average number of points switche ON)

This is not relevant if 24 VDC is supplied from an external source and a power supply module with no 24 VDC output is used.

(2) Total 5 VDC logic circuit power consumption

The 5 VDC output circuit power consumption of the power supply module is the power consumption of each of the modules.

 $W_{5V} = I_{5V} \times 5 \quad (W)$

(3) Total 24 VDC average power consumption of output modules (with an average number of points switched ON.

The 24 VDC output circuit average power consumption of the power supply module is the total power consumption of each of the modules:

 $W_{24V} = I_{24V} \times 24$ (W)

(4) Average power consumption due to voltage drop in output circuits of output modules (with an average number of points switched ON)

Wout = Iout x Vdrop x number of output points x average number of outputs on at one time (W)

lout : Output current (actual operating current) (A)

Vdrop : Voltage drop across each output module (V)

(5) Average power consumption of input circuits of input modules (with an average number of points switched ON)

 $W_{IN} = I_{IN} \times E \times X$ number of input points x average number of inputs on at one time (W)

- IN : Input current (effective value for AC) (A)
- E : Input voltage (actual operating voltage) (V)
- (6) Power consumption of special function modules is expressed as follows:

 $Ws = I_5vx 5 + I_{24}vx 24 + I_{100}v x 100 (W)$

The sum of each of the values calculated above is the power consumption of the entire PC system.

 $W = W_{PW} + W_{5V} + W_{24V} + W_{OUT} + W_{IN} + W_{S} (W)$

The amount of heat generated and the temperature rise in the panel can be calculated from this total power consumption (W).

Generally, the temperature rise in the panel is expressed as follows:

$$T = \frac{W}{UA} [^{\circ}C]$$

- W : Power consumption of the entire PC system (obtained as shown above.
- A : Panel internal surface area (m₂)
- U = 6: if the temperature inside the panel is controlled by a fan, etc
- U = 4: if the air in the panel is not circulated

POINT

If the temperature inside the panel exceeds 55 °C, the temperature must be reduced by installing a heat exchanger.

If a fan is used, it will suck in dust together with air from outside, with adverse effects on the programmable controller.

8.3 Precautions Relating to the Installation of the Base Unit

The following precautions must be observed when installing a PC to an operation panel or other bases considering fully the operability, maintainability, and resistance to the environmnt.

(1) Base unit mounting position

Provide a clearance between the top and bottom sides of the unit and the wall of structure or components as given below. This is required for ventilation and replacing ease.

- A5[]B, A6[]B..... 80 mm (3.15 inch) or oveR



- (2) Installing direction
 - (a) Install the PC in the direction shown below for good ventilation



(b) The following installing directions must be avoided.



(3) Install the base unit on a flat surface.

It it is mounted on an uneven surface, the PC board in the module is starained and malfunction will occur.

- (4) Avoid installing the base unit near a vibrating source such as a large electromagnetic switch and no-fuse circuit breaker. Install it to a separate panel or away form such vibrating source.
- (5) Provide a wiring duct if necessary.

However, if the clearance with the top/bottom of the PC is less than 30 mm (1.18 inch), note the following points:

(a) When the duct is located above the PC, the height of the duct should be 50 mm (1.97 inch) or less to allow for sufficient ventilation.

Set the distance from the top of the PC so that the hook latch at the top of the module can be pressed. If it cannot be pressed, it will be impossible to replace the module.

(b) When the duct is located under the PC, provide sufficient clearance so that there is no effect on the 100/200 VAC input line of the power supply module, I/O wires of I/O modules, and 12/24 VDC wires.

8. LOADING AND INSTALLATION

- (6) Provide clearances, mentioned below, between the PC and other devices (contactors and relays) to avoid the influence of radiating noise and heat.
 - Between the PC and a device installed in front of the PC: 100 mm (3.94 inch) or over
 - Between the PC and devices installed on the right and left sides of the-PC: 50 mm (1.97 inch) or over



8-5

Mounting and Removing Modules 8.4

POINTS

This section explains how to mount power supply modules, PC CPU modules, I/O modules, special function modules, etc., to a base unit, and how to remove them.

Module mounting (1)

The module mounting procedure is as follows.



(2) Module removal

The module removal procedure is as follows.



POINTS

- (1) When removing a module, be sure to remove the module mounting screw before attempting to disengage the module fixing projections from the module fixing hole. If the module is forcibly removed, the module fixing projections will be damaged.
- (2) Always turn the power supply OFF before mounting or removing any module.
8.5 Installing and Removing the Dustproof Cover

When an A1S52B(S1), A1S55B(S1), or A1S58B(S1) is used, the dustproof cover which is supplied with the base unit must be fitted to the I/O module loaded at the left end in order to prevent foreign matter from entering the I/O. module: If this cover is not fitted, foreign-matter will enter the I/O module and cause malfunctions. The following explains how to fit and remove the dust-proof cover.



To fit the dustproof cover onto the I/O module, first insert the cover at the terminal side and then press the cover against the I/O module as shown in the figure.

(2) Removal



Fit the tip of a flat blade screwdriver into the notch on the left side of the dustproof cover. While keeping the screwdriver tip in the notch, gently move the screwdriver to the left (as shown above) until the cover snaps open.

8.6 Failsafe Circuits

When the power to the programmable controller is turned ON or OFF, the process output may not perform normally at times due to the difference between the delay time and the rise time of the power supply of the PC CPU module and the external power supply (especially DC).

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For example, when the PC main power supply is turned on after turning on the process external power supply to a DC output module, the DC output module may momentarily issue faulty outputs when thePC power is turned on. To avoid this problem, the circuit must be configured so that the PC main power supply is turned on first.

Erroneous operation may also occur due to faults of the external power supply or programmable controller.

In order to prevent faults such as these from causing erroneous operation of the entire system, and also for safety reasons, configure circuits external to the programmable controller (such as emergency stop, protection, and interlock circuits) that prevent machine damage and accidents.

An example circuit for a system design based on the above points is presented overpage.

POINT

Some A1S series output modules detect a blown fuse error when the external power supply is turned OFF.

In the example circuit shown overpage, since the start-up of the A1SJCPU takes place earlier than the rise of the external power supply to the output module, a blown fuse error is detected.

To solve this problem, the system is designed to keep M9084 on until the external power supply has risen, so as not to check for blown fuses. (When M9084 is ON, the I/O module verification and battery checks are not performed.)

(1) System design circuit example

ALL AC



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- *1: RUN/STOP circuit interlocked with RA1 (run monitor relay)
- *2: Low battery alarm
- *3: RA1 switched ON by M9039 (run monitor relay)
- *4: Power to output equipment switched OFF when the STOP signal is given.
- *5: Input switched when power supply established.
- Set time for DC power sup-*6: ply to be established.
- •7: ON when run by M9039
- *8: Interlock circuits as necessary.

The power-ON procedure is as follows:

For AC

- 1) Set the CPU to RUN.
- 2) Switch ON the power.
- 3) Turn ON the start switch.
- 4) When the magnetic contactor (MC) comes in, the output equipment is powered and may be driven by the program.

For AC/DC

- 1) Set the CPU to RUN
- 2) Switch ON the power.
- 3) Turn ON the start switch.
- 4) When DC power is established, RA2 comes ON.
- 5) Timer (TM) times out after the DC power reaches 100%

(The TM set value should be the penod of time from when RA2 comes ON to the establishment of 100% DC voltage., Set this value to approximately 0.5 seconds.)

6) When the magnetic contractor (MC) comes in, the output equipment is powered and may be driven by the program. (If a voltage relay is used at RA2, no timer (TM) is required in the program.)

8. LOADING AND INSTALLATION

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(2) Fail-safe measures against PC failures

Problems with the CPU or memory can be detected by the self diagnosis function. However, problems with the I/O control area may not be detected by the CPU.

In such cases, all I/O points turn ON or OFF depending on the condition of problem, and normal operating conditions and operating safety cannot sometimes be maintained.

Though Mitsubishi PCs are manufactured under strict quality control, they may cause failure or abnormal operations due to unspecific reasons. To prevent the abnormal operation of the whole system, machine breakdown, and accidents, build a fail-safe circuit outside the PC. The following gives an example of a fail-safe circuitry.



- *1: Y00 repeats turning ON and then OFF at 0.5 second intervals. Use a no-contact output module (transistor in the example shown above).
- *2: If an OFF delay timer (especially a miniature timer) is not available, use ON delay timers to make a fail-safe circuit as shown on the next page.



A fail-safe circuit built with ON delay timers

*1: Use a solid-state relay for the M1 relay.

8.7 Power Supply Connection

Observe the following precautions when making the power supply wiring.

(1) Power supply connection

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 (a) Provide separate wiring systems for the PC power, I/O devices, and operating devices as shown below.

If the wiring is influenced by intensive noise, connect an insulating transformer.



(b) Do not connect the 24 VDC outputs from more than one power supply module in parallel to supply to one I/O module. If they are connected in parallel, the power supply modules will break.



(c) The 100 VAC, 200 VAC, and 24 VDC wires should be twisted as tightly as possible, and connect the modules at the shortest distance between them.

To minimize the voltage drop, use thick wires (MAX. 2 mm²) as much as possible.

- (d) Do not bind the 100 VAC and 24 VDC wires together with the main circuit (high tension and large current) wires or I/O signal wires nor place them near each other. Provide a 100 mm (3.94 inch) clearance between the wires if possible.
- (e) As a measure against surges caused by lightning, insert a lightning surge absorber as shown below.



POINTS

- (1) Provide separate grounding for the lightning surge absorber (E1) and the PC (E2).
- (2) Select a lightning surge absorber whose maximum allowable circuit voltage is larger than the circuit voltage at the maximum power supply voltage.

- Wiring of I/O equipment (2)
 - (a) The applicable size of wire to the terminal block connector is 0.75 to 1.5 mm2. However, you are recommended to use wires of 0.75 mm2 for convenience.
 - (b) Separate the input and output lines.
 - (c) I/O signal wires must be at least 100 mm (3.94 in.) away from high-voltage and large-current main circuit wires.
 - (d) When the I/O signal wires cannot be separated from main circuit wires and power wires, ground on the PC side with batch-shielded cables. Under some conditions it may be preferable to ground on the other side.



- (e) If the wiring is routed through piping, ground the piping properly.
- (f) Separate the 24 VDC I/O cables from the 100 VAC cables and 200 VAC cables.
- (g) If wiring over 200 m (7.87 inch) or a greater distance, problems can be caused by leakage current due to line capacity. Take corrective action as described in Section 10.4.
- (3) Grounding

Grounding must be carried out as described in (a) to (d) below.

- (a) Ground independently if possible. Class 3 grounding should be used (grounding resistance of 100 Ω or less).
- (b) When independent grounding is impossible, use common grounding as shown in the figure below (2).



- Common grounding ... Good (3) Independent grounding ... Best (2)
 - (c) The grounding wire used must have a cross sectional area of at least 2 mm₂.

Make the grounding point as close as possible to the PC and the grounding wire as short as possible

(d) Should incorrect operation occur due to grounding, disconnect one or both of the LG and FG terminals of the base units from the ground. (4) The following is an example of wiring of the power supply and grounding wires to the A1SJCPU and extension base unit.

When the power supply voltage for the power supply module(a1S61P, A1S61PEU, A1S62P, A1S62PEU) is set at 100V, put a shorting strip on the voltage switching terminals of the power supply module.

Since the voltage switching terminals are factory-set for the open state, it is not necessary to put the shorting strip when the power supply boltage 200 VAC is used.

The A1SJCPU can operate with the 85 to 264 VAC power supply voltage range without switching the voltavge setting.



(a) Wiring example

Ground

9. MAINTENANCE AND INSPECTION

This chapter describes items for daily and periodic maintenance and inspection in order to maintain the programmable controller in the normal and best conditions.

9.1 Daily Inspection

Table 9.1 shows the inspection and items which are to be checked daily.

No.	Ch	eck Item	Check Point	Judgment	Corrective Action
1	Bas mou cone	e unit Inting ditions	Check for loose mounting screws and cover.	The base unit should be securely mounted.	Retighten screws.
2	Mounting conditions of I/O module, etc.		Check if the module is disengaged or the hook is securely engaged.	Check if the nodule is lisengaged or the nook is securely engaged. The hook should be securely engaged and the module should be positively mounted.	
			Check for loose terminal screws.	Screws should not be loose.	Retighten terminal screws.
3	Con	necting ditions	Check distance between solderless terminals.	Proper clearance should be provided between solderless terminals.	Correct.
			Check connectors of extension cable. be loose.		Retighten connector mounting screws.
		"POWER" LED	Check that the LED is ON.	ON (OFF indicates an error.)	See Section 10.2.2.
	sdw	"RUN" LED	Check that the LED is ON during RUN.	ON (OFF or flash indicates an error.)	See Section 10.2.3 and 10.2.4.
	dicator la	"ERROR" LED	Check that the LED is ON when an error occurred.	OFF (ON when an error occurred.)	See Section 10.2.5. and 10.2.6.
4	U module in	Input LED	Check that the LED turns ON and OFF.	ON when input is ON. OFF when input is OFF. (Display, which is not as mentioned above, indicates an error.)	See Section 10.2.7.
	Ċ	Output LED	Check that the LED turns ON and OFF.	ON when output is ON. OFF when output is OFF. (Display, which is not as mentioned above, indicates an error.)	See Section 10.2.7.

Table 9.1 Daily Inspection

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9.2 Periodic Inspection

This section explains the inspection items which are to be checked every six months to one year. If the equipment have been moved or modified or wiring has been changed, also make the inspection.

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No.	Check Item		Checking Method	Judgment	Corrective Action								
	nment	Ambient temperature	Measure with	0 to 55°C	When PC is used								
1	enviro	Ambient humidity	thermometer and hygrometer.	10 to 90 %RH	inside a panel, the temperature in the								
	Ambient	Ambience	gas.	There should be no corrosive gases.	panel is ambient temperature.								
2	Line	e voltage	Measure voltage	85 to 132 VAC	Change supply								
2	che	ck.	VAC terminal.	170 to 264 VAC	transformer tap.								
3	conditions	Looseness, play	Move the unit	The module should be mounted securely and positively.	Retighten screws.								
3	Mounting	Ingress of dust or foreign material	Visual check.	There should be no dust or foreign material, in the vicinity of the PC.	Remove and clean.								
	tions	Loose terminal screws	Retighten.	Connectors should not be loose.	Retighten.								
4	Connecting condi	necting condi	necting condi	necting condi	necting condi	necting condi	necting condi	necting condi	necting cond	distances between solderless terminals	Visual check.	Proper clearance should be provided between solderless terminals.	Correct.
		Loose connector	Visual check.	Connectors should not be loose.	Retighten connector mounting screws.								
5	Battery		Check battery status by mounting special auxiliary relays M9006 and M9007. Retighten battery if necessary.	Preventive maintenance	If battery capacity reduction is not indicated, change the battery when specified service life is exceeded.								

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9.3 Replacement of Battery

M9006 or M9007 turns ON when the voltage of battery for program backup and power failure compensation reduces.

Even if this special rely turns ON,-the-contents-of-the-program-and power failure compensation are not lost immediately.

However, if the ON state is overlooked, the PC contents may be lost.

Special auxiliary relays M9006 and M9007 are switched ON to indicate that the battery life has reduced to the time (minimum) indicated in Table 9.3 and it must be replaced if continued power failure RAM and /or data backup is required.

The following sections give the battery service life and the battery changing procedure.

9.3.1 Service life of battery

Table 9.3 shows the service life of battery.

Battery Life (Total Power Failure Time) [Hr]					
Guaranteed value (MIN)	Actually applied value (TYP)	After M9006 or M9007 is turned ON			
5400	13000	168			

Table 9.3 Battery Life

* The actually applied value indicates a typical value and the guaranteed value indicates the minimum value.

Preventive maintenance is as described below.

- (1) Even if the total power failure time is less than the guaranteed value in the above table, change the battery after four to five years.
- (2) When the total power failure time has exceeded the guaranteed value in the above table and M9006 has turned ON, change the battery.

9. MAINTENANCE AND INSPECTION

9.3.2 Replacing the battery

Follow the procedure given below when replacing the battery. The data in memory is backed up by a capacitor for several minutes (see Table 9.4 below) after the battery is removed.

Memory data will not be held by the capacitor over the time specified below.



(2) Fail-safe measures against PC failures

Problems with the CPU or memory can be detected by the self diagnosis function. However, problems with the I/O control area may not be detected by the CPU.

In such cases, all I/O points turn ON or OFF depending on the condition of problem, and normal operating conditions and operating safety cannot sometimes be maintained.

Though Mitsubishi PCs are manufactured under strict quality control, they may cause failure or abnormal operations due to unspecific reasons. To prevent the abnormal operation of the whole system, machine breakdown, and accidents, build a fail-safe circuit outside the PC. The following gives an example of a fail-safe circuitry.



- *1: Y00 repeats turning ON and then OFF at 0.5 second intervals. Use a no-contact output module (transistor in the example shown above).
- *2: If an OFF delay timer (especially a miniature timer) is not available, use ON delay timers to make a fail-safe circuit as shown on the next page.



A fail-safe circuit built with ON delay timers

*1: Use a solid-state relay for the M1 relay.

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Observe the following precautions when making the power supply wiring.

 Provide separate wiring systems for the PC power, I/O devices, and operating devices as shown below.
 If the wiring is influenced by intensive noise, connect an insulating



(2) Do not connect the 24 VDC outputs from more than one power supply module in parallel to supply to one I/O module. If they are connected in parallel, the power supply modules will break.



(3) The 100 VAC, 200 VAC, and 24 VDC wires should be twisted as tightly as possible, and connect the modules at the shortest distance between them.

To minimize the voltage drop, use thick wires (MAX. 2 mm²) as much as possible.

- (4) Do not bind the 100 VAC and 24 VDC wires together with the main circuit (high tension and large current) wires or I/O signal wires nor place them near each other. Provide a 100 mm (3.94 inch) clearance between the wires if possible.
- (5) As a measure against surges caused by lightning, insert a lightning surge absorber as shown below.



POINTS

- (1) Provide separate grounding for the lightning surge absorber (E1) and the PC (E2).
- (2) Select a lightning surge absorber whose maximum allowable circuit voltage is larger than the circuit voltage at the maximum power supply voltage.



9. LOADING AND INSTALLATION

- (6) The following is an example of wiring of the power supply and grounding wires to the A1SJCPU and extension base unit.
 - (a) When the power supply voltage for the power supply module (A1S61P, A1S61PEU, A1S62P, A1S62PEU) is set at 100 V, put a shorting strip on the voltage switching terminals of the power supply module.
 - Since the voltage switching terminals are factory-set for the open state, it is not necessary to put the shorting strip when the power supply voltage 200 VAC is used.

The A1SJCPU can operate with the 85 to 264 VAC power supply voltage range without switching the voltage setting.

- Ο A1SJCPU 000 $\bigcirc \mathbf{0}$ 100/110 VAC ||ģ ą AC INPUT Select the transformer AC100/200V by reference to σ LG Section 8.7.1 (C). Fuse σ FG AC DC 24 VDC 0 Connect to the 24 VDC teminals of an I/O module that requires 24 VDC internally. Extension base unit (A1S58B-S1) I/01/0 POINTS (1) Use thick wires (MAX. 2 mm²) as 5 VDC line much as possible for the 100/200 VAC and 24 VDC power supply, and twist the wires beginning with the connecting terminal. When a solderless terminal is used, use a solderless terminal with an insulation FG sleeve to prevent short-circuit when Ю the terminal screw becomes loose. Extension base unit (A1S68B-S1) (2) When the LG and FG terminals are connected, they must be grounded. A1S61P Ο 100/110 VAC () If they are not grounded, the 8 operation processing will be easily influenced by noise.Use caution not to touch the LG terminal since it has O an electric potential of half the input Ο 0-5 VDC line 8000 voltage. O-FG (3) If the voltage switching terminals Orshort 100 VAC СИ are shorted for use with 100 VAC and Shorting OJOPEN 200 VAC \mathcal{O} strip if a 200 VAC power is supplied to the Ю O- LG terminals, the power supply module O7 INPUT will break. 10 OJ 100/200 VAC Grounding wire
- (b) Wiring example

Ground

This section describes various procedures for troubleshooting, as well as corrective actions.

10.1 Basic Troubleshooting

System reliability not only depends on reliable equipment but also on short down-times in the event of faults.

The three basic points to be kept in mind in troubleshooting are:

(1) Visual checks

Check the following points

- (a) Machine motion (in stop and operating states)
- (b) Power ON or OFF
- (c) Status of I/O equipment
- (d) Condition of wiring (I/O wires, cables)
- (e) Display states of various indicators (such as POWER LED, RUN LED, ERROR LED, and I/O LED)
- (f) States of various setting switches (such as extension base and power failure compensation)

After checking (a) to (f), connect the peripheral equipment and check the running status of the PC CPU and the program contents.

(2) Trouble check

Observe any changes in the error condition during the following:

- (a) Set the RUN/STOP keyswitch to the STOP position.
- (b) Reset using the RUN/STOP keyswitch.
- (c) Turn the power ON and OFF.
- (3) Narrow down the possible causes of the trouble

Deduce where the fault lies, i.e:

- (a) Inside or outside the PC CPU.
- (b) I/O module or another module.
- (c) Sequence program.

10.2 Troubleshooting

This section explains the procedure for determining the cause of problems as well as the errors and corrective actions for error codes.

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10.2.1 Troubleshooting flowcharts

The procedures for troubleshooting are given in the following flowcharts:



10.2.2 Flowchart used when the POWER LED goes OFF



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10.2.3 Flowchart used when the RUN LED goes OFF



10.2.4 Flowchart used when the RUN LED flashes



10.2.5 Flowchart used when the ERROR LED is lit

The following shows the corrective measures when the ERROR LED is lit at RUN.



10.2.6 Flowchart used when the ERROR LED flashes

The following shows the corrective measures when the ERROR LED flashes.



10.2.7 Flowchart used when the output load of the output module does not go ON



POINT

If the input or load signals are not switched OFF, see Section 10.4 and take corrective measures.

10.2.8 Flowchart used when a program cannot be written to the PC CPU

The following shows the corrective measures when a program cannot be written to the PC CPU.



10.3 Error Code List

If an error occurs in the RUN mode, an error display or error code (including a step number) is stored in the special register by the self-diagnostic function. The error code reading procedure and the causes of and corrective actions for errors are shown in Table 10.1.

Error Message	Contents of Special Register D9008 (BIN value)	CPU State	Error and Cause		Corrective Action
	x		An instruction code, which cannot be decoded by CPU, is included in the program.	(1)	Read the error step by use of peripheral device and correct the program at that step.
INSTRUCT CODE ERR.	10	STOP	 A memory cassette containing invalid instruction code, has been loaded. 	(2)	In the case of the memory cassette, rewrite the contents of the ROM, or replace with a
			(2) The occurrence of an error destroyed the memory contents, adding an instruction code that cannot be read to the memory.		have been correctly written.
			The contents of the memory installed in the PC CPU have been destroyed because of (a) the occurrence of noise, or (b) the failure of the memory cassette.		Check the loading of the PC CPU memory cassette and load it correctly.
ERROR	11	STOP			Read the parameter data from the PC CPU by use of a periperhal device. Make any necessary corrections and write it again to the PC CPU
MISSING END	12	STOP	 There is no END(FEND) instruction in the program. 	(1)	Write END at the end of the program.
		13 STOP	 There is no jump destination for plural destinations specified by the CJ, SCJ, CALL, CALLP or JMP instruction. 	(1)	Read the error step by use of a peripheral device and correct the program at that step. (Make corrections such as the
			(2) Although there is no CALL instruction, the RET instruction exists in the program and has been executed.		insertion of jump destination or the changing of jump destinations to one)
			(3) The CJ, SCJ, CALL, CALLP or JMP instruction has been executed with its jump destination located below the END instruction.		
CAN'T EXECUTE (P)	13		(4) The number of FOR instructions does not match the number of NEXT instructions.		
			(5) The JMP instruction specified between FOR to NEXT has caused the execution to deviate from between FOR to NEXT.		
			(6) The JMP instruction has caused the execution to deviate from the subroutine before the RET instruction is executed.		
			(7) The JMP instruction has caused execution to jump to a step or subroutine between FOR to NEXT.		

Table 10.1 Error Codes

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Error Message	Contents of Special Register D9008 (BIN value)	CPU State	Error and Cause	Corrective Action
			(1) There are instructions (including NOP) other than LDX, LDIX, ANDX and ANIX in the CHK instruction circuit block.	(1) Check the program of the CHK instruction circuit block (1) to (7) in the left column. Correct errors using a peripheral device and restart the operation.
			(2) There is more than one CHK instruction.	(2) This error code is only valid when the I/O control uses the direct
			(3) The number of contact points in the CHK instruction circuit block exceeds 150.	metrica.
			(4) The X device number in the CHK instruction circuit block exceeds X7FE.	
CHK FORMAT ERR.	14	STOP	(5) There is no circuit block in front of the CHK instruction circuit block.	
			(6) D1 device (number) of the CHK/D1/D2 instruction is different from the contact device (number) above the CJI instruction.	
			(7) Pointer P254 is not attached to the start of the CHK instruction circuit block.	
041VT			 Although the interrupt module is used, there is no number for interrupt pointer I, which corresponds to that module, in the program or several numbers of pointer I exist in the program. 	 Check for the presence of interrupt program which corresponds to the interrupt module and create and interrupt program or reduce the numbers of i to one.
EXECUTE (I)	15	STOP	(2) No IRET instruction has been entered in the interrupt program.	(2) Check if there is IRET instruction in the interrupt program and enter the IRET instruction.
			(3) There is an IRET instruction somewhere besides the interrupt program.	(3) Check if there is an IRET instruction somewhere besides the interrupt program and delete that IRET instruction.
BOM EB8	17	STOP	(1) Parameters and/or sequence programs are not correctly written to the installed memory cassette (EPROM or EEPROM)	(1) Write parameters and/or sequence programs correctly to the memory cassette (EPROM or FEPROM)
			(,	 Remove a memory cassette which does not have any parameter and/or sequence program.
RAM ERROR	20	STOP	(1) The PC CPU has checked if write and read operations can be performed properly to the data memory area of the PC CPU. Normal writing and/or read/write turned out to be impossible.	Since this is a PC CPU hardware fault, consult your nearest Mitsubishi representative.
OPE. CIRCUIT ERR.	21	STOP	 The operation circuit, which performs the sequence processing in the PC CPU, does not operate properly. 	
			Scan time exceeds watchdog monitoring time.	 Calculate and check the scan time of the user program and reduce the scan time by the use of CJ instructions, etc.
WDT ERROR	22	STOP	 Scan time of user program is excessive. Scan time has lengthened due to instantaneous power failure which occurred during the scan. 	(2) Monitor the content of special register D9005 by use of a peripheral device. If the content is other than 0, line voltage is insufficient. Therefore, check the power and eliminate the voltage fluctuation.

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Error Message	of Special Register D9008 (BIN value)	CPU State	Error and Cause	Corrective Action	
	24	STOP	 When the END instruction is executed, another instruction code has been read due to noise, etc. The END instruction has changed to another instruction code. 	(1) Perform reset and RUN. If the same error is displayed again, it is a PC CPU hardware fault. Therefore, consult your nearest Mitsubishi representative.	
WDT ERROR	_ 25	STOP	The END instruction cannot be executed with the program looped	Check for an endless loop and correct he program.	
UNIT VERIFY ERR.	31	STOP (RUN)	 I/O module data is different from that at power ON. The I/O module (including the special-function module) is (a) incorrectly disengaged or has been removed, or (b) a different module has been loaded 	 Among special registers D9116 to D9123, the bit corresponding to the module verify error is "1". Therefore, monitor the registers by use of a peripheral device and check for the module with "1". When the fault has been corrected, reset the PC CPU. 	
FUSE BREAK OFF	32	STOP (RUN)	 There is an output module with a blown fuse. The external power supply for the output load is OFF or not connected. 	 Check the blown fuse indicator LED of the output module and change the module whose LED is ON. Checking the module for a blown fuse can also be done with a peripheral device. Among special registers D9100 to D9107, the bit corresponding to the module of verify error is "1". Therefore, check by monitoring the registers. Check the ON/OFF state of the external power supply for the output load 	
CONTROL-BUS ERR.	40	STOP	 The FROM and TO instructions cannot be executed (1) Error of control bus with special- function module. 	(1) This is a special-function module, CPU module or base unit hardware fault. Therefore, change the unit and check the defective module. Consult your nearest Mitsubishi representative about the defective module	
SP. UNIT DOWN	41	STOP	 When FROM and TO instructions cannot be executed. (1) Control bus error in the special-function module. 	This is a special-function module, CPU module or base unit hardware fault. Therefore, change the unit and check the defective module. Consult your nearest Mitsubishi representative about the defective module.	
i/O INT. ERROR	43	STOP	Although the interrupt module is not installed, an interruption has occurred.	(1) This is a certain module hardware fault. Therefore, change the module and check the defective module. Consult your nearest Mitsubishi representative about the defective module.	
SP. UNIT LAY. ERR.	44	STOP	 Three or more computer link modules are installed into a single CPU module. Two or more modules of A1SJ71AP21, A1SJ71AR21, A1SJ71T21B, A1SJ71LP21, A1SJ71BR11 are installed. Two or more interrupt modules are installed. In the parameter setting of the peripheral device, while an I/O module is actually installed, a special-function module has been set in the I/O assignment, and vice versa. 	 reduce the computer link modules to two or less. Use one A1SJ71AP21, A1SJ71AR21, A1SJ71T21B, A1SJ71LP21, A1SJ71BR11. Use one interrupt module. Reset the I/O assignment of parameter setting by use of peripheral device according to the actually loaded special-function module. 	
SP. UNIT ER- ROR	46	STOP (RUN)	 Access (execution of FROM/TO instruction) has been made to a location where there is no special- function module. 	 Read the error step by use of peripheral device, and check and correct the content of the FROM/TO instruction at that step by using a peripheral device. 	

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Error Message	Contents of Special Register D9008 (BIN value)	CPU State		Error and Cause		Corrective Action
SP. UNIT ER- ROR	46	STOP (RUN)	(1)	Access (execution of FROM/TO instruction) has been made to a location where there is no special- function module.	(1)	Read the error step by use of peripheral device, and check and correct the content of the FROM/TO instruction at that step by using a peripheral device.
LINK PARA. ER- ROR	47	RUN	(1)	The contents, which have been written to the parameter area of the link by setting the link range in the parameter setting of peripheral device, are different from the link parameter contents.	(1)	Write the parameters again and check.
i i i i i i i i i i i i i i i i i i i			(2)	The setting of the total number of slave stations is 0.	(2)	If this message is displayed again, it is a hardware fault. Therefore, consult your nearest Mitsubishi representative.
			(1)	The result of BCD conversion has exceeded the specified range (9999 or 99999999).	(1)	Use a peripheral device to read the error step and check and correct the program at that step.
OPERATION ER- ROR	50	RUN (STOP)	(2)	A setting has been done which exceeds the specified device range and the operation cannot be done.		(Check device setting range, BCD conversion value, etc.)
			(3)	File registers are used in the program without performing the capacity setting of file registers.		
MAIN CPU			(1)	An interrupt instruction (INT instruction) was used in a microcomputer program.	(1)	Do not use INT instructions in microcomputer programs (reomove the INT instruction)
DOWN	60	STOP	(2)	CPU has malfunctioned due to noise or other cause.	(2)	Implement measures against noise
			(3)	CPU hardware fault.	(3)	Replace the CPU.
BATTERY ER-	70		(1)	The battery voltage is below 24 VDC.	(1)	Change the battery.
ROR	70	HUN	(2)	The battery lead is disconnected.	(2)	When RAM or power failure compensation is used, connect the battery.

10.4 I/O Connection Troubleshooting

This section explains possible problems with I/O circuits.

10.4.1 Input circuit troubleshooting

This section describes possible problems with input circuits, as well as corrective actions.

 Table 10.2 Input Circuit Problems and Corrective Actions

	Condition	Cause	Corrective Action
		Leakage current of input switch (such as a drive by non-contact switch).	 Connect an appropriate register which will make the voltage across the terminals of the input module lower than the OFF voltage value.
Example 1	Input signal does not turn OFF.	AC input	AC input
			It is recommended to use 0.1 to 0.47 μF + 47 to 120 Ω (1/2 W) for the constant.
Example 2	Input signal does not turn OFF.	Drive by a limit switch with neon lamp. AC input Leakage Input module Power supply	 Same as Example 1. Or make up another independent display circuit.
Example 3	Input signal does not turn OFF.	Leakage current due to line capacity of wiring cable. Line capacity C of twisted pair wire is approx. 100 PF/m). AC input Leakage current Power supply	 Same as Example 1. However, leakage current is not generated when power supply is located on the input equipment side as shown below. AC input Input module Power Supply
Example 4	Input signal does not turn OFF.	Drive by switch with LED indicator.	Connect a register which will make the voltage across input module terminal and common higher than the OFF voltage, as shown below. DC input (sink) Resistor Input module A sample calculation of a connected resistor value is given on the following page.

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	Condition	Cause	Corrective Action
-		 Sneak path due to the use of two power supplies. 	 Use only one power_supply. Connect a sneak path prevention diode. (Figure below)
-Example 5	Input signal does not turn OFF.	E1 $E2$ input module E1 > E2	E1 E2 C- Input module

Table 10.2 Input Circuit Problems and Corrective Actions (Continued)

Sample calculation for Example 4

The switch with the LED indicator is connected to A1SX40 and there is a 4 mA leakage current.



(1) Since this voltage does not satisfy the OFF voltage of 1 [mA] or lower, the input signal does not go OFF. Therefore, connect a resistor as shown below.



(2) Calculate the resistance value of R as follows: To obtain the 1 mA OFF current for the A1SX40, a 3 mA current or larger must flow to R.

I_R : I_Z = Z (input impedance) : R
R ≤
$$\frac{I_Z}{I_R}$$
 x (input impedance) = $\frac{1}{3}$ x 3.3 = 1.1 [kΩ]

 $\mathsf{R} < 1.1\mathsf{K}\Omega$

If the resistance value of R is 1 k Ω , the power capacity W of the resistor R is calculated as follows:

W = (current value)² x R = 0.003^2 (A) x 1000 (Ω) = 0.009 (W)

(3) Since the power capacity of the resistor is usually selected as 3 to 5 times the actual power consumption, a 1 k Ω 0.5 W resistor must be connected to the terminals concerned.

10.4.2 Output circuit failures and corrective actions



Table 10.3 Output Circuit Failures and Corrective Actions

This section describes various procedures for troubleshooting, as well as corrective actions.

11.1 Basic Troubleshooting

System reliability not only depends on reliable equipment but also on short down-times in the event of faults.

The three basic points to be kept in mind in troubleshooting are:

(1) Visual checks

Check the following points

- (a) Machine motion (in stop and operating states)
- (b) Power ON or OFF
- (c) Status of I/O equipment
- (d) Condition of wiring (I/O wires, cables)
- (e) Display states of various indicators (such as POWER LED, RUN LED, ERROR LED, and I/O LED)
- (f) States of various setting switches (such as extension base and power failure compensation)

After checking (a) to (f), connect the peripheral equipment and check the running status of the PC CPU and the program contents.

(2) Trouble check

Observe any changes in the error condition during the following:

- (a) Set the RUN/STOP keyswitch to the STOP position.
- (b) Reset using the RUN/STOP keyswitch.
- (c) Turn the power ON and OFF.
- (3) Narrow down the possible causes of the trouble

Deduce where the fault lies, i.e:

- (a) Inside or outside the PC CPU.
- (b) I/O module or another module.
- (c) Sequence program.

11.2 Troubleshooting

This section explains the procedure for determining the cause of problems as well as the errors and corrective actions for error codes.

11.2.1 Troubleshooting flowcharts

The procedures for troubleshooting are given in the following flowcharts:



11.2.2 Flowchart used when the POWER LED goes OFF



11.2.3 Flowchart used when the RUN LED goes OFF


11.2.4 Flowchart used when the RUN LED flashes



11.2.5 Flowchart used when the ERROR LED is lit

The following shows the corrective measures when the ERROR LED is lit at RUN.



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11.2.6 Flowchart used when the ERROR LED flashes

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The following shows the corrective measures when the ERROR LED flashes.



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11.2.7 Flowchart used when the output load of the output module does not go ON



POINT

If the input or load signals are not switched OFF, see Section 11.4 and take corrective measures.

11.2.8 Flowchart used when a program cannot be written to the PC CPU

The following shows the corrective measures when a program cannot be written to the PC CPU.



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11.3 Error Code List

If an error occurs in the RUN mode, an error display or error code (including a step number) is stored in the special register by the self-diagnostic function. The error code reading procedure and the causes of and corrective actions for errors are shown in Table 11.1.

Error Message	Contents of Special Register D9008 (BIN value)	CPU State	Error and Cause		Corrective Action
			An instruction code, which cannot be decoded by CPU, is included in the program.	(1)	Read the error step by use of peripheral device and correct the program at that step.
INSTRUCT CODE ERR.	10	STOP	 A memory cassette containing invalid instruction code, has been loaded. The occurrence of an error destroyed the memory contents, adding an instruction code that cannot be read to the memory. 	(2)	In the case of the memory cassette, rewrite the contents of the ROM, or replace with a memory cassette whose contents have been correctly written.
		;	The contents of the memory installed in the PC CPU have been destroyed	(1)	Check the loading of the PC CPU memory cassette and load it correctly.
ERROR	11	STOP	because of (a) the occurrence of noise, or (b) the failure of the memory cassette.		Read the parameter data from the PC CPU by use of a periperhal device. Make any necessary corrections and write it again to the PC CPU.
MISSING END INS.	12	STOP	(1) There is no END(FEND) (instruction in the program.		Write END at the end of the program.
			 There is no jump destination for plural destinations specified by the CJ, SCJ, CALL, CALLP or JMP instruction. Although there is no CALL instruction, the RET instruction 	(1)	Read the error step by use of a peripheral device and correct the program at that step. (Make corrections such as the insertion of jump destination or the changing of jump destinations
			exists in the program and has been executed.		to one.)
CAN'T EXECUTE (P)			(3) The CJ, SCJ, CALL, CALLP or JMP instruction has been executed with its jump destination located below the END instruction.		
	13	STOP	(4) The number of FOR instructions does not match the number of NEXT instructions.		
			(5) The JMP instruction specified between FOR to NEXT has caused the execution to deviate from between FOR to NEXT.		
			(6) The JMP instruction has caused the execution to deviate from the subroutine before the RET instruction is executed.		
			(7) The JMP instruction has caused execution to jump to a step or subroutine between FOR to NEXT.		

Table 11.1	Error	Codes
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Error Message	Contents of Special Register D9008 (BIN value)	CPU State	Error and Cause		Corrective Action
			(1) There are instructions (including NOP) other than LDX, LDIX, ANDX and ANIX in the CHK instruction circuit block.	(1)	Check the program of the CHK instruction circuit block (1) to (7) in the left column. Correct errors using a peripheral device and restart the operation.
			(2) There is more than one CHK instruction.	(2)	This error code is only valid when the I/O control uses the direct
			(3) The number of contact points in the CHK instruction circuit block exceeds 150.		method.
			(4) The X device number in the CHK instruction circuit block exceeds X7FE.		
CHK FORMAT ERR.	14	STOP	(5) There is no circuit block in front of the CHK instruction circuit block.		
			 (6) D1 device (number) of the CHK/D1/D2 instruction is different from the contact device (number) above the CJ[] instruction. (7) Pointer P254 is not attached to 		
			the start of the CHK instruction circuit block.		
CANUT			 Although the interrupt module is used, there is no number for interrupt pointer I, which corresponds to that module, in the program or several numbers of pointer I exist in the program. 	(1)	Check for the presence of interrupt program which corresponds to the interrupt module and create and interrupt program or reduce the numbers of i to one.
EXECUTE (I)	15	STOP	(2) No IRET instruction has been entered in the interrupt program.	(2)	Check if there is IRET instruction in the interrupt program and enter the IRET instruction.
	•		(3) There is an IRET instruction somewhere besides the interrupt program.	(3)	Check if there is an IRET instruction somewhere besides the interrupt program and delete that IRET instruction.
ROM ERR	17	STOP	 Parameters and/or sequence programs are not correctly written to the installed memory cassette (EPROM or EEPROM). 	(1)	Write parameters and/or sequence programs correctly to the memory cassette (EPROM or EEPROM).
				(2)	Remove a memory cassette which does not have any parameter and/or sequence program.
RAM ERROR	20	STOP	(1) The PC CPU has checked if write and read operations can be performed properly to the data memory area of the PC CPU. Normal writing and/or read/write turned out to be impossible.		ce this is a PC CPU hardware fault, sult your nearest Mitsubishi esentative.
OPE. CIRCUIT ERR.	21	STOP	 The operation circuit, which performs the sequence processing in the PC CPU, does not operate properly. 		
			Scan time exceeds watchdog monitoring time.	(1)	Calculate and check the scan time of the user program and reduce the scan time by the use of CJ instructions, etc.
WDT ERROR	22	STOP	 Scan time of user program is excessive. Scan time has lengthened due to instantaneous power failure which occurred during the scan. 	(2)	Monitor the content of special register D9005 by use of a peripheral device. If the content is other than 0, line voltage is insufficient. Therefore, check the power and eliminate the voltage fluctuation.

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Error Message	Contents of Special Register D9008 (BIN value)	CPU State	Error and Cause	Corrective Action
END NOT EXECUTE	24	STOP	 When the END instruction is executed, another instruction code has been read due to noise, etc. The END instruction has changed to another instruction code. 	 Perform reset and RUN. If the same error is displayed again, it is a PC CPU hardware fault. Therefore, consult your nearest Mitsubishi representative.
WDT ERROR	25	STOP	The END instruction cannot be executed with the program looped.	Check for an endless loop and correct the program.
UNIT VERIFY ERR.	31	STOP (RUN)	 I/O module data is different from that at power ON. (1) The I/O module (including the special-function module) is (a) incorrectly disengaged or has been removed, or (b) a different module has been loaded. 	 Among special registers D9116 to D9123, the bit corresponding to the module verify error is "1". Therefore, monitor the registers by use of a peripheral device and check for the module with "1". When the fault has been corrected, reset the PC CPU.
FUSE BREAK OFF	32	STOP (RUN)	 There is an output module with a blown fuse. The external power supply for the output load is OFF or not connected. 	 Check the blown fuse indicator LED of the output module and change the fuse in the module whose LED is ON. Checking the module for a blown fuse can also be done with a peripheral device. Among special registers D9100 to D9107, the bit corresponding to the module of verify error is "1". Therefore, check by monitoring the registers. Check the ON/OFF state of the external power supply for the output load.
CONTROL-BUS ERR.	40	STOP	The FROM and TO instructions cannot be executed. (1) Error of control bus with special- function module	(1) This is a special-function module, CPU module or base unit hardware fault. Therefore, change the unit and check the defective module. Consult your nearest Mitsubishi representative about the defective module.
SP. UNIT DOWN	41	STOP	 When FROM and TO instructions cannot be executed. (1) Control bus error in the special-function module. 	This is a special-function module, CPU module or base unit hardware fault. Therefore, change the unit and check the defective module. Consult your nearest Mitsubishi representative about the defective module.
I/O INT. ERROR	43	STOP	Although the interrupt module is not installed, an interruption has occurred.	 This is a certain module hardware fault. Therefore, change the module and check the defective module. Consult your nearest Mitsubishi representative about the defective module.
SP. UNIT LAY. ERR.	44	STOP	 Three or more computer link modules are installed into a single CPU module. Two or more modules of A1SJ71T21B are installed. Two or more interrupt modules are installed. In the parameter setting of the peripheral device, while an I/O module is actually installed, a special-function module has been set in the I/O assignment, and vice versa. 	 reduce the computer link modules to two or less. Use one A1SJ71T21B. Use one interrupt module. Reset the I/O assignment of parameter setting by use of peripheral device according to the actually loaded special-function module.
SP. UNIT ERROR	46	STOP (RUN)	 Access (execution of FROM/TO instruction) has been made to a location where there is no special- function module. 	 Read the error step by use of peripheral device, and check and correct the content of the FROM/TO instruction at that step by using a peripheral device.

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Error Message	Contents of Special Register D9008 (BIN value)	CPU State	Error and Cause		Corrective Action		
LINK PARA. ERROR	47	RUN	(1)	The contents, which have been written to the parameter area of the link by setting the link range in the parameter setting of peripheral device, are different from the link parameter contents.	(1)	Write the parameters again and check.	
			(2)	The setting of the total number of slave stations is 0.	(2)	If this message is displayed again, it is a hardware fault. Therefore, consult your nearest Mitsubishi representative.	
			(1)	The result of BCD conversion has exceeded the specified range (9999 or 99999999).	(1)	Use a peripheral device to read the error step and check and correct the program at that step.	
OPERATION ERROR	50	RUN (STOP)	(2)	A setting has been done which exceeds the specified device range and the operation cannot be done.		(Check device setting range, BCD conversion value, etc.)	
			(3)	File registers are used in the program without performing the capacity setting of file registers.			
BATTERY			(1)	The battery voltage is below 24 VDC.	(1)	Change the battery.	
ERROR	70	RUN	(2)	The battery lead is disconnected.	(2)	When RAM or power failure compensation is used, connect the battery.	

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11. TROUBLESHOOTING

11.4 I/O Connection Troubleshooting

This section explains possible problems with I/O circuits.

11.4.1 Input circuit troubleshooting

This section describes possible problems with input circuits, as well as corrective actions.

Table 11.2 Input Circuit Problems and Corrective Actions

	Condition	Cause	Corrective Action
		Leakage current of input switch (such as a drive by non-contact switch).	 Connect an appropriate register which will make the voltage across the terminals of the input module lower than the OFF voltage value.
Example 1	Input signal does not turn OFF.	AC input	AC input input module
			It is recommended to use 0.1 to 0.47 μ F + 47 to 120 Ω (1/2 W) for the constant.
Example 2	Input signal does not turn OFF.	Drive by a limit switch with neon lamp. AC input Leakage current Power supply	 Same as Example 1. Or make up another independent display circuit.
Example 3	Input signal does not turn OFF.	Leakage current due to line capacity of wiring cable. Line capacity C of twisted pair wire is approx. 100 PF/m). AC input Leakage current Power supply	 Same as Example 1. However, leakage current is not generated when power supply is located on the input equipment side as shown below. AC input Input module Power Supply
Example 4	Input signal does not turn OFF.	Drive by switch with LED indicator.	Connect a register which will make the voltage across input module terminal and common higher than the OFF voltage, as shown below. DC input (sink) Resistor Input module * A sample calculation of a connected resistor value is given on the following page.

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	Condition	Cause	Corrective Action
		 Sneak path due to the use of two power supplies. 	 Use only one power supply. Connect a sneak path prevention diode. (Figure below)
Example 5	Input signal does not turn OFF.	E1 $E2$ Input module E1 > E2	E1 E2

Table 11.2 Input Circuit Problems and Corrective Actions (Continued)

Sample calculation for Example 4

The switch with the LED indicator is connected to A1SX40 and there is a 4 mA leakage current.



(1) Since this voltage does not satisfy the OFF voltage of 1 [mA] or lower, the input signal does not go OFF. Therefore, connect a resistor as shown below.



 (2) Calculate the resistance value of R as follows: To obtain the 1 mA OFF current for the A1SX40, a 3 mA current or larger must flow to R.

$$I_R$$
 : I_Z = Z (input impedance) : R
R ≤ $\frac{I_Z}{I_R}$ x (input impedance) = $\frac{1}{3}$ x 3.3 = 1.1 [kΩ]

$R < 1.1 K\Omega$

If the resistance value of R is 1 k Ω , the power capacity W of the resistor R is calculated as follows:

W = (current value)² x R = 0.003^2 (A) x 1000 (Ω) = 0.009 (W)

(3) Since the power capacity of the resistor is usually selected as 3 to 5 times the actual power consumption, a 1 k Ω 0.5 W resistor must be connected to the terminals concerned.

11.4.2 Output circuit failures and corrective actions



Table 11.3 Output Circuit Failures and Corrective Actions

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APPENDICES

APPENDIX 1 INSTRUCTIONS

This section describes the sequence instructions, basic instructions, and application instructions that can be used with an A1SJCPU.

The ACPU Programming Manual (Common Instructions) gives details about each instruction.

The descriptions of instructions used with the A2NCPU can be applied to the A1SJCPU.

1.1 Sequence Instructions

Classification	Instruction Symbol	Symbol	Contents of Processing
	LD	<u> </u>	Logical operation start (NO contact operation start)
	LDI	<u> </u>	Logical NOT operation start (NC contact operation start)
Contact instructions	AND		Logical product (NO contact series connection)
Contact instructions	ANI	<i>t</i> r	Logical product NOT (NC contact series connection)
	OR		Logical add (NO contact parallel connection)
	ORI	<u>_</u>	Logical add NOT (NC contact parallel connection)
	ANB	╶┐╴┤┝╶┍═┱╶┥┝╶┍╴ ┖╺┤┝┙┕╴┥┝╼┙	ANDs logical blocks. (Series connection of blocks)
	ORB	- <u>_</u> +- <u>-</u> ↓_++-J	ORs logical blocks. (Parallel connection of blocks)
Connection instructions	MPS		Stores the operation result.
	MRD		Reads the operation result from MPS.
	MPP		Reads the operation result from MPS and clears the result.
	OUT	———ОН	Device output
	SET	- SET (D)	Device set
	RST	RST (D)	Device reset
OUT instructions	PLS	- PLS (D) -	Generates one-program cycle pulses on the leading edge of input signal.
	PLF	PLF (D)	Generates one-program cycle pulses on the trailing edge of input signal.
	Снк	- <u>СНК (D1)(D2)</u> -	Inversion of device outputs (at I/O refresh)
Shift instructions	SFT	- SFT (D)	
	SFTP	- SFTP (D)	Shifts device 1 bit

Table 1 Sequence Instructions

Classification		Instruction Symbol	Symbol	Contents of Processing
- Master control Instructions		MC ~	MC n (D)	Master control start
		MCR		Master control reset
Termination	Program	FEND	HFENDH	Always used at the end of the main routine program to terminate processing.
instructions end	END	—	Always used at the end of the sequence program to return to step 0.	
Other	Stop	STOP		Resets output after input condition is enabled, and stops the sequence program. The sequence program is resumed by setting the RUN keyswitch to RUN.
instructions	No operation	NOP	_	No operation For program erasure or space
	Page change	NOPLF	_	Changes hard copy pages. Written in the operation list mode.

Table 1 Sequence Instructions (Continued)

1.2 Basic Instructions

Classif	ication	Instruction Symbol	Symbol	Contents of Processing
		LD=	LO- (S1) (S2)-	
		AND=	- AND- (S1) (S2)-	Continuity when (S1) = (S2) Non-continuity when (S1) ≠ (S2)
		OR=	GR- (S1) (S2)	
		LD<>	LD<> (S1) (S2)	
		AND<>	- AND<> (S1) (S2)	Continuity when (S1) ≠ (S2) Non-continuity when (S1) = (S2)
	OR<>	└ <u>OR<> (S1) (S2)</u> ┘		
	LD>	LD> (S1) (S2)		
	AND>	- AND> (S1) (S2)-	Continuity when (S1) > (S2) Non-continuity when (S1) \leq (S2)	
Comparison	Comparison 16-bit data	OR>	└ <u>OR> (S1) (S2</u>)┘	
instructions	comparison	LD<=	LD< (S1) (S2)	
		AND<=	- AND<- (S1) (S2)-	Continuity when (S1) ≤ (S2) Non-continuity when (S1) > (S2)
		OR<=	└── OR<= (S1) (S2) ┘┘	
		LD<	LD< (S1) (S2)	
		AND<	- AND< (S1) (S2)	Continuity when (S1) < (S2) Non-continuity when (S1) ≥ (S2)
		OR<		
	LD>=	LD>= (S1) (S2)		
		AND>=	- AND>= (S1) (S2)-	Continuity when (S1) ≥ (S2) Non-continuity when (S1) < (S2)
		OR>=		

Table 2 Basic Instructions

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Classif	ication	Symbol	Symbol	Contents of Processing			
		LDD=	LDD- (S1) (S2)				
~		ANDD=	- ANDD= (S1) (S2)-	Continuity when (S1 + 1, S1) = (S2 + 1, S2) Non-continuity when (S1 + 1, S1) ≠ (S2 + 1, S2)			
		ORD=					
		LDD<>	LDD<> (S1) (S2)				
		ANDD<>	- ANDD<> (S1) (S2)-	Continuity when $(S1 + 1, S1) \neq (S2 + 1, S2)$ Non-continuity when $(S1 + 1, S1) = (S2 + 1, S2)$			
		ORD<>	GRD<> (S1) (S2)				
		LDD>	LDD> (S1) (S2)				
	Comparison 32-bit data	ANDD>	- ANDD> (S1) (S2)-	Continuity when $(S1 + 1, S1) > (S2 + 1, S2)$ Non-continuity when $(S1 + 1, S1) \leq (S2 + 1, S2)$			
Comparison		ORD>	ORD> (S1) (S2)				
Instructions	comparison	LDD<=	LDD<= (S1) (S2)				
		ANDD<=	- ANDD <= (S1) (S2)-	Continuity when $(S1 + 1, S1) \le (S2 + 1, S2)$ Non-continuity when $(S1 + 1, S1) > (S2 + 1, S2)$			
		ORD<=	└── ORD<- (S1) (S2) └				
		LDD<	LDD< (S1) (S2)				
		ANDD<	- ANDD< (S1) (S2)-	Continuity when $(S1 + 1, S1) < (S2 + 1, S2)$ Non-continuity when $(S1 + 1, S1) \ge (S2 + 1, S2)$			
		ORD<	ORD< (S1) (S2)				
		LDD>=	LDD>= (S1) (S2)				
		ANDD>=	- ANDD>= (S1) (S2)-	Continuity when (S1 + 1, S1) ≥ (S2 + 1, S2) Non-continuity when (S1 + 1, S1) < (S2 + 1, S2)			
		ORD>=	GRD>= (S1) (S2)				

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Table 2 Basic Instructions (Continued)

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MELSEC-A

Classif	ication	Instruction Symbol	Symbol	Contents of Processing
		+	- + (S) (D)	
		+P		$(D) + (S) \to (D)$
		+	- + (S1) (S2) (D)	
	BIN 16-bit	+P	-+P (S1) (S2) (D)	(S1) + (S2) → (U)
	subtraction		- (S) (D)	
		P	P (S) (D)	$(0) = (0) \rightarrow (0)$
			- (S1) (S2) (D)	
		P		$(51) - (52) \rightarrow (0)$
		D+	D+(S) (D)	
		D+P	D+P(S)(D)	$(D + 1, D) + (S + 1, S) \rightarrow (D + 1, D)$
		D+	D+ (S1) (S2) (D)	
Arithmetic	BIN 32-bit	D+P	D+P (S1) (S2) (D)	$(51 + 1, 5) + (52 + 1, 52) \rightarrow (0 + 1, 0)$
instructions	subtraction	D		$(D + 1, D)$ $(e + 1, e) \rightarrow (D + 1, D)$
		D-P	- D-P (S) (D)	$(U \neq 1, U) = (3 \neq 1, 3) \rightarrow (U \neq 1, U)$
		D-	— D- (S1) (S2) (D) —	
		D-P	— D-P (S1) (S2) (D)	$(S1 + 1, S1) - (S2 + 1, S2) \rightarrow (U + 1, U)$
		*	- · (S1) (S2) (D)	
	Bin 16-bit	*P	- P (S1) (S2) (D)	$(S1) \times (S2) \rightarrow (D + 1, D)$
	subtraction	/	- / (S1) (S2) (D)	
		/P	/P (S1) (S2) (D)	$(S1) + (S2) \rightarrow Quotient (D), Remainder (D + 1)$
		D•	D· (S1) (S2) (D)	(S1 + 1, S1) x (S2 + 1, S2) → (D + 3, D + 2, D +
1	BIN 32-bit	D*P	D•P (S1) (S2) (D)	1,D)
	subtraction	D/		$(S1 + 1, S1) + (S2 + 1, S2) \rightarrow Quotient$
		D/P	D/P (S1) (S2) (D)	(D + 1, D), Remainder (D + 3, D + 2)

Table 2 Basic Instructions (Continued)

	Table 2 Basic Instructions (Continued)					
Classi	Classification		Symbol	Contents of Processing		
		B+		$(D) + (S) \rightarrow (D)$		
		B+P	B+P (S) (D)	(0) + (0) - (0)		
		B+	B+ (S1) (S2) (D)	- (S1) + (S2) → (D)		
	BCD 4-digit	B+P	B+P (S1) (S2) (D)			
	division	B-	B- (S) (D)	$(D) + (S) \rightarrow (D)$		
		BP				
		B –	B- (S1) (S2) (D)	(S1) – (S2) → (D)		
Arithmetic		B-P	B-P (S1) (S2) (D)			
instructions		DB+	- DB+ (S) (D)	$(D + 1, D) + (S + 1, S) \rightarrow (D + 1, D)$		
		DB+P	DB+P(S)			
		DB+	DB+(S1)(S2)(D)	(S + 1, S1) + (S2 + 1, S2) → (D + 1, D)		
	BCD 8-digit multiplication.	DB+P				
	division	DB-	DB(S) (D)	(D + 1, D) – (S + 1, S) → (D + 1, D)		
		DB-P	DB_P (S) (D)			
		DB-	DB- (S1) (S2) (D)	$(S1 + 1, S1) + (S2 + 1, S2) \rightarrow (D' + 1, D)$		
		DB-P	DBP (S1) (S2) (D)			

 Table 2 Basic Instructions (Continued)

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Classification		Instruction Symbol	Symbol	Contents of Processing	
		B *	B• (\$1) (\$2) (D)	(S1) x (S2) → (D + 1, D)	
	BCD 4-digit	B⁺P	B*P (S1) (S2) (D)		
	division	B/	B/ (S1) (S2) (D)	(S1) = (S2) = Outtight (D) Perminder (D + 1)	
		B/P	B/P (S1) (S2) (D)	$(51) + (52) \rightarrow \text{Quotient}(D)$ Remainder $(D + 1)$	
		DB*	- DB* (S1) (S2) (D)	$(S1 + 1, S1) \times (S2 + 1, S2) \rightarrow (D + 3, D + 2, D + 2)$	
	BCD 8-digit multiplication, division	DB*P		1, D)	
		DB/	DB/ (S1) (S2) (D)	$(S1 + 1, S1) \div (S1 + 1, S2) \rightarrow Quotient$	
Arithmetic		DB/P	DB/P (S1) (S2) (D)	(D + 1, D), Remainder (D + 3, D + 2)	
instructions	BIN data increment	INC			
		INCP		$(D) + 1 \rightarrow (D)$	
		DINC			
-		DINCP	DINCP (D)	(U + 1, U) + 1 → (U + 1, U)	
		DEC	DEC (D)		
	BIN data	DECP	DECP (D)	(U) − 1 → (U)	
	increment	DDEC	DDEC (D)		
		DDECP	DDECP (D)	(U + 1, U) - 1 → (U + 1, U)	

Table 2 Basic Instructions (Continued)

Instruction Classification Symbol **Contents of Processing** Symbol BCD conversion (D) 7 BCD BCD (S) (D) (S) - BIN (0 to 9999) BCDP BCDP (S) (D) BCD conversion (S1 + 1, S1) BCD conversion (D1 + 1, D) DBCD DBCD (S) (D) -BCD ↔ DBCDP (S) (D) DBCDP BIN (0 to 99999999) BIN BIN conversion (D) conversion BIN BIN (S) (0) -┥ (S) instructions - BCD (0 to 9999) BINP BINP (S) (D) BIN conversion $(S1 + 1, S1) \xrightarrow{BIN \text{ conversion}} (D1 + 1, D)$ DBIN DBIN (S) (D) DBINP DBINP (S) (D) BCD (0 to 99999999) 1 MOV MOV (S) (D) $(\mathsf{S}) \to (\mathsf{D})$ MOVP (S) (D) -MOVP Transfer DMOV DMOV (S) (D) $(S + 1, S) \rightarrow (D + 1, D)$ DMOVP (D) (S) DMOVP (S) CML CML (D) $(S) \rightarrow (D)$ CMLP CMLP (S) (D) |-Negation transfer DCML DCML (S) (D) $\overline{(S + 1, S)} \rightarrow (D + 1, D)$ DCMLP DCMLP (S) BMOV (S) (D) n BMOV (D) (S) Data transfer _ _ instructions n Ξ _ _ -BMOVP (S) (D) n BMOVP Block transfer FMOV (S) (D) n FMOV (S) n FMOVP (S) (D) n FMOVP (01) (02) хсн XCH (D1) ↔ (D2) (D1) (D2) XCHP XCHP Exchange DXCH (D1) (D2) DXCH $(D1 + 1, D1) \leftrightarrow (D2 + 1, D2)$ DXCHP (D1) (D2) DXCHP

Table 2 Basic Instructions (Continued)

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Classification		Instruction Symbol	Symbol	Contents of Processing
		CJ	CJ P**	Jumps to P** after the input condition is enabled.
	Jump	SCJ	SCJ P"	Jumps to P** beginning with the next scan after the input condition is enabled.
		JMP		Unconditionally jumps to P**.
		CALL	- CALL P** H	Executes the subroutine program at P** after the input
	Subroutine call	CALLP	-CALLP P** H	condition is enabled.
Program branch		RET		Returns execution from the subroutine program to the sequence program.
instructions		EI		Cancels execution disable setting of an interrupt program. Valid when M9053 is OFF.
	Interrupt program	DI	HH	Execution of an interrupt program is disabled. Valid when M9053 is OFF.
		IRET	HH	Returns operation from an interrupt program to a sequence program.
	Micro-	SUB	- SUB n -	
	program call	SUBP	- SUBP n H	Executes the microcomputer program specified by n.
	Link refresh	СОМ	H <u>com</u> H	Executes link refresh, general data processing.
Petrech	Link refresh	EI		Enables link refresh. Valid when M9053 is ON.
instructions	enable/ disable	DI	НН	Disables link refresh. Valid when M9053 is ON.
· ·	Partial refresh	SEG		Corresponding devices are partial-refreshed during one scan. Valid when M9052 is ON.

Table 2 Basic Instructions (Continued)

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1.3 Application Instructions

Classif	ication	Instruction Symbol	Symbol	Contents of Processing
		WAND	WAND (S) (D)	
		WANDP	WANDP (S) (D)	$(D) \text{ AND } (S) \to (D)$
	Logical	WAND	WAND (S1) (S2) (D)	(C1) AND (C2)
	product	WANDP		$(51) \text{ AND } (52) \rightarrow (0)$
		DAND	DAND (S) (D)	$(D \pm 1, D) \text{ AND } (S \pm 1, S) \rightarrow (D \pm 1, D)$
		DANDP	DANDP (S) (D)	
		WOR	- WOR (S) (D)	$(D) OB (S) \rightarrow (S)$
		WORP	WORP (S) (D)	
	Logical sum	WOR		$(S1) \cap B(S2) \rightarrow (D)$
		WORP	WORP (S1) (S2) (D)	
		DOR	DOR (S) (D)	$(D + 1, D) OB (S + 1, S) \rightarrow (D + 1, D)$
		DORP	DORP (S) (D)	
Logical operation		WXOR	WXOR (S) (D)	(D) XOB (S) → (D)
instructions		WXORP	WXORP (S) (D)	
	Exclusive	WXOR	WXOR (S1) (S2) (D)	(S1) XOB (S2) → (D)
	logical sum	WXORP	WXORP (S1) (S2) (D)	
		DXOR	DXOR (S) (D)	$(D + 1, D) XOB (S + 1, S) \rightarrow (D + 1, D)$
		DXORP	DXORP (S) (D)	
		WXNR	WXNR (S) (D)	$(D) XOB(S) \rightarrow (D)$
		WXNRP	WXNRP (S) (D)	
	NOT	WXNR	WXNR (S1) (S2) (D)	$(S1) XOB (S2) \rightarrow (D)$
	logical sum	WXNRP	WXNRP (S1) (S2) (D)	
		DXNR	DXNR (S) (D)	$(D + 1, D) \text{ XOB } (S + 1, S) \rightarrow (D + 1, D)$
		DXNRP	DXNRP (S) (D)	
	2's	NEG	NEG (D)	$\overline{(D)} + 1 \rightarrow (D)$
	complement	NEGP	NEGP (D)	$(U) + T \rightarrow (U)$

Table 3 Application Instructions

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Classif	ication	Instruction Symbol	Symbol	Contents of Processing
		ROR		15 A0 0 Carry
	Rightward	RORP		"n" bit rotate to right
	rotation	RCR		Carry 15 A0 0
		RCRP		"n" bit rotate to right
		ROL		Carry 15 A0 0
	Leftward rotation	ROLP		"n" bit rotate to left
		RCL	- RCL n	15 A0 0 Carry
Rotation		RCLP	RCLP n	"n" bit rotate to left
instructions	Rightward rotation	DROR		A1 A0 15 0 15 0 Carry
		DRORP		"n" bit rotate to right
		DRCR	DRCR n	A1 A0 Carry 15 0 15 0
		DRCRP	DRCRP n	"n" bit rotate to right
		DROL	DROL n	$\begin{array}{c c} Carry & 15 \\ \hline \\ $
	Leftward	DROLP	DROLP n	"n" bit rotate to left
	rotation	DRCL		15 A1 0 15 A0 0 Carry
		DRCLP		"n" bit rotate to left

Table 3 Application Instructions (Continued)

Instruction Classification Symbol **Contents of Processing** Symbol SFR 0 15 'n SFR (D) n |---| 0 15 to Carry SFRP SFRP (D) n ł 0 to 0 n bit shift Ľ 15 0 SFL SFL (D) n \vdash 0 15 to Carry SFLP (D) SFLP n Н 0 to 0 n BSFR BSFR (D) -(D) n Carry BSFRP BSFRP ο (D) n H Shift 1 bit shift instructions BSFL 8SFL (D) n \vdash (D) Carry BSFLP BSFLP (D) Н n 0 n DSFR DSFR (D) n +(ð) DSFRP DSFRP (D) n Н 0 1 ward shift DSFL DSFL (D) n \vdash (D) DSFLP DSFLP (D) n $\left| \right|$ -0

Table 3 Application Instructions (Continued)

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Classif	ication	Instruction Symbol	Symbol	Contents of Processing
	Data search	SER	SER (S1) (S2) n	(S2) (S1) =======
		SERP		A0 Coinciding number A1 Coinciding quantity
		SUM	- SUM (S)	(S) 15 0 A0 Quantity of 1 and D9003
	- Bit check	SUMP		
		DSUM		$(S+1) \qquad (S)$
		DSUMP		
	Decode/ Encode	DECO	DECO (S) (D) n	8 → 256 decode (S) (D)
Data Processing		DECOP	-DECOP (S) (D) n	n Decode 2n bits
Instructions		ENCO		$\begin{array}{c} 256 \rightarrow 8 \text{ encode} \\ (S) \qquad \qquad$
		ENCOP		bits Encode n
	7 segment decode	SEG	SEG (S) (D)	(S) 7SEG (D) 0 Valid for A □ N, A3H Decode when M9052 is OFF
		BSET	-BSET (D) n	(D) 15 n O
	Bit	BSETP	BSETP (D) n	
	set/reset	BRST	BRST (D) n	(D) 15 n 0
		BRSTP	BRSTP (D) n	

Table 3 Application Instructions (Continued)

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Classif	ication	Instruction Symbol	Symbol	Contents of Processing
		DIS		$\begin{array}{c} All 0 \\ 4 \text{ bits} \\ (D) + 2 \\ (D) + 2 \end{array}$
Data Processing	Association/Dis sociation			4 bits 4 bits
instructions		UNIP		S (S) + 1 (S) + 2 When n = 3
	ASCII conversion	ASC	ASC Alphanumeric (D)	Converts alphanumeric characters into ASCII codes and stores into 4 points beginning with the device, D.
i	Write	FIFW	FIFW (S) (D)	(D) <u>Pointer</u> (S) Pointer + 1
FIFO		FIFWP	FIFWP (S) (D)	
Instructions	Read	FIFR	FIFR (D1) (D2)	(D2) <u>Pointer</u> (D1) Pointer _ 1
		FIFRP	FIFRP (D1) (D2)	
	Data read	FROM	- FROM n1 n2 (D) n3	
		DFRO	DFRO n1 n2 (0) n3	Reads data from the special function module.
Buffer		DFROP	DFROP n1 n2 (D) n3	
instructions		ТО	TO n1 n2 (S) n3	
	Data write	ТОР	TOP n1 n2 (S) n3	Write data to the special function module.
FOR-NEXT instructions	Repetition	FOR		Processing between [FOR] and [NEXT] is repeated "n" times.
		NEXT		х.

Table 3 Application instructions (Continued)

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Clas	sification	1	Instruction Symbol	Symbol	Contents of Processing
Local station	Local station data		LRDP	LRDP n1 (S) (D) n2	Reads data from the local station.
access instructions	read/write	•	LWTP	LWTPn1_(D)_(S)n2	
Remote I/O station	Remote I/ station da	'O Ita	RFRP	RFRP n1 n2 (D) n3	Reads data from the special function module in the remote I/O station.
access instructions	read/write	•	RTOP	RTOP n1 n2 (D) n3	
			PR		Outputs 16 ASCII codes beginning with a designated device to an output module.
Display	ASCII prir	nt	PR	—	Outputs ASCII codes beginning with a designated device to NUL(00H) to an output module. Valid when M9049 is OFF.
	Display reset		PRC	- PRC (S) (D)	Converts the comment of a designated device to ASCII code and outputs it to an output module. Comment of device 1 is also output.
			LEDR		Resets the display indication.
			WDT	WDT	Resets WDT with a sequence program.
	WD1 rese	et	WDTP		
	Failure ch	neck	СНК		Failure \rightarrow (D1) : ON, (D2) : Failure NO Normal \rightarrow (D1) : OFF, (D2) : 0 When A[]N uses I/O direct method.
	Status	Set	SLT		At the condition set by parameter setting, data are stored into memory for status latch.
	latch	Reset	SLTR		Status latch is reset and [SLT] instruction is enabled.
Other instructions	Sampling	Set	STRA	STRA	At the condition set by parameter setting, sampling data are stored into memory for status latch.
	uace	Reset	STRAR	STRAR	Sampling trace is resumed. ([STRA] instruction is enabled.)
	Corry	Set	STC	- STC -	Carry flag contact (M9012) is turned on.
	Carry	Reset	CLC		Carry flag contact (M9012) is turned off.
	Timing cl	ock	DUTY	- DUTY n1 n2 (D)	Timing clock shown below is generated. Special relay (D)

Table 3 Application Instructions (Continued)

APPENDIX 2 SPECIAL RELAY, SPECIAL REGISTER LIST

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2.1 Special Relay List

(1) Special relay list

The special relays are internal relays used for specific purposes. Therefore, they cannot be used as coils in the program. The special relays are used a contacts in the program.

Number	Name	Description	Details
*1 M9000	Fuse blown	OFF: Normal ON: Presence of fuse blow module	 Turned on when there is one or more output modules of which fuse has been blown. Remains on if normal status is restored.
*1 M9002	I/O module verify error	OFF: Normal ON: Presence of error	 Turned on if the status of I/O module is different from entered status when power is turned on. Remains on if normal status is restored.
*1 M9005	AC DOWN detection	OFF: AC is good ON: AC is down	 Turned on if power failure of within 10ms occurs. Reset when POWER switch is moved from OFF to ON position.
M9006	Battery low	OFF: Normal ON: Battery low	 Turned on when battery voltage reduces to less than specified. Turned off when battery voltage becomes normal.
*1 M9007	Battery low latch	OFF: Normal ON: Battery low	 Turned on when battery voltage reduces to less than specified. Remains on if battery voltage becomes normal.
*1 M9008	Self-diagnostic error	OFF: Absence of error ON: Presence of error	 Turned on when error is found as a result of self- diagnosis.
M90(09	Annunciator detection	OFF: Absence of ON: Presence of	 Turned on when OUT F or SET F instruction is executed. Switched off when D9124 value is set to 0.
M9010	Operation error flag	OFF: Absence of error ON: Presence of error	 Turned on when operation error occurs during execution of application instruction. Turned off when error is eliminated.
*1 M9011	Operation error flag	OFF: Absence of error ON: Presence of error	 Turned on when operation error occurs during execution of application instruction. Remains on if normal status is restored.
M9012	Carry flag	OFF: Carry off ON: Carry on	Carry flag used in application instruction.
M9016	Data memory clear flag	OFF: No processing ON: Output clear	 Clears all data memory (except special relays and special registers) in remote run mode from computer, etc. when M9016 is 1.
M9017	Data memory clear flag	OFF: No processing ON: Output clear	 Clears all unlatched data memory (except special relays and special registers) in remote run mode from computer, etc. when M9017 is 1.
M9020	User timing clock No.0	· ·	 Relay which repeats on/off at intervals of predetermined scan.
M9021	User timing clock No.1	n2 scan n2 scan	 When power is turned on or reset is performed, the clock starts with off.
M9022	User timing clock No.2	n1 scan	Set the intervals of on/off [DUTY] instruction.
M9023	User timing clock No.3		DUTY n1 n2 M9020
M9024	User timing clock No.4		, , , , , , , , , , , , , , , , , , ,
*2 M9025	Clock data set request	OFF: No processing ON: Data set request	 Writes clock data from D9025-D9028 to the clock devices after the END instruction is executed at the scan when M9025 is switched on.
M9026	Clock data error	OFF: No error ON: Error	Switched on when a clock data error occurs.

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Number	Name	Description	Details
*2 M9028	Clock data read request	OFF: No processing ON: Read request	 reads clock data in BCD to D9025-D9028 when M9028 is switched on.
M9030	0.1 second clock	0 05 0 05 seconds	 0.1 second, 0.2 second, 1 second, 2 second, and 1 minute clocks are generated.
M9031	0.2 second clock	01 seconds seconds	• Not turned on and off per scan but turned on and off even during scan if corresponding time has elapsed.
M9032	1 second clock	05 seconds seconds	• Starts when power is turned on or reset is performed.
M9033	2 second clock	1 1 seconds	
M9034	1 minute clock	30 30 seconds seconds	
M9036	Normally ON	ON OFF	Used as dummy contacts of initialization and application instruction in sequence program.
M9037	Normally OFF	ON OFF	M9036 and M9037 are switched on/off independently of the CPU RUN/STOP switch position. M9038 and
M9038	On only for 1 scan after run	ON 1 scan	M9039 are switched on/off in accordance with the RUN/STOP switch position, i.e. switched off when the switch is set to STOP. When the switch is set to
M9039	RUN flag (off only for 1 scan after run)	ON 1 scan	other than STOP, M9038 is only switched on during 1 scan and M9039 is only switched off during 1 scan.
M9040	PAUSE enable coil	OFF: PAUSE disabled ON: PAUSE enabled	• When RUN key switch is at PAUSE position or remote pause contact has turned on and if M9040 is
M9041	PAUSE status contact	OFF: During pause ON: Not during pause	on, PAUSE mode is set and M9041 is turned on.
M9042	Stop status contact	OFF: During stop ON: Not during stop	 Switched on when the RUN/STOP switch is set to STOP.
M9043	Sampling trace completion	OFF: During sampling trace ON: Sampling trace completion	 Turned on upon completion of sampling trace performed the number of times preset by parameter after STRA instruction is executed. Reset when STRAR instruction is executed.
M9046	Sampling trace	OFF: Except during trace ON: During trace	On during sampling trace.
M9047	Sampling trace preparation	OFF: Sampling trace stop ON: Sampling trace start	 Sampling trace is not executed until M9047 is turned on. By turning off M9047, sampling trace is stopped.
100.00	Number of characters output	OFF: Characters up to NULL code output	• When M9049 is off, characters up to NULL (00H) code are output.
M9049	switching	ON: 16 characters output	When M9049 is on, ASCII codes for 16 characters are output.
	SEG instruction switching	OFF: 7SEG display	Serves as an I/O partial refresh instruction when M9052 is on.
⁻² M9052		ON: I/O partial refresh	Serves as a 7SEG display instruction when M9052 is off.
*2 M9053	EI/DI instruction switching	OFF: Sequence interrupt control ON: Link interrupt control	Switch on to execute the link refresh enable, disable (EI, DI) instructions.
M9054	STEP RUN flag	OFF: Not during step run ON: During step run	Switched on when the RUN/STOP switch is in STEP RUN.
M9055	Status latch completion flag	OFF: Uncompleted ON: Completed	 Turned on when status latch is completed. Turned off by reset instruction.
*2 M9084	Error check setting	OFF: Error checked	• Used to set whether or not the following error checks are made at the execution of the END instruction.
1		ON: Error unchecked	Fuse blown, I/O unit verify error batter error

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POINTS

- (1) All special relays are switched off by any of the power-off, latch clear and reset operations. The special relays remain unchanged when the RUN/STOP switch is set to STOP.
- (2) The above relays with numbers marked *1 remain "on" if-normal status is restored. Therefore, to turn them "off", use the following method:
 - 1) Method by user program

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Insert the circuit shown at right into the program and turn on the reset execution command contact to clear the special relay M.



Enter a number desired to be reset

2) Method by peripheral equipment.

Cause forced reset by the test function of peripheral equipment. For the operation procedure, refer to equipment. For the operation procedure, refer to the manual of each peripheral equipment.

3) By moving the RESET key switch at the CPU front to the RESET position, the special relay is turned "off".

(3) Special relays marked *2 are switched on/off in the sequence program.

2.2 Special Registers D

The special registers are data registers used for specific purposes. Therefore, do not write data to the special registers in the program (except the ones with numbers marked * in the table).

Number	Name	Stored Data	Explanation
D9000	Fuse blown	Fuse blow module number	 When fuse flow modules are detected, the lowest number of detected units is stored in hexadecimal. (Example: When fuses of Y50 to 6F output modules have blown, "50" is stored in hexadecimal) The module number monitored by the peripheral is hexadecimal. (Cleared when all contents of D9100 are reset to 0.)
D9002	I/O unit verify error	I/O module verify error module number	 If I/O module data is different from data entered are detected when the power is turned on, the first I/O number of the lowest number module among the detected modules stored in hexadecimal. (Storing method is the same as that of D9000.) The module number monitored by the peripheral is hexadecimal. (Cleared when all contents of D9116 of D9123 are reset to 0.)
*1 D9005	AC DOWN counter	AC DOWN time count	 1 is added each time input voltage becomes 80% or less of rating while the CPU unit is performing operation, and the value is stored in BIN code.
*1 D9008	Self- diagnostic error	Self-diagnostic error number	 When error is found as a result of self-diagnosis, error number is stored in BIN code.
D9009	Annunciator detection	F number at which external failure has occurred	 When one of to 255 is turned on by [OUT F] or [SET F], the F number, which has been detected earliest among the F numbers which have turned on, is stored in BIN code.
			 D9009 can be cleared by [RST F] or [LEDR] instruction. If another F number has been detected, the clearing of D9009 causes the next number to be stored in D9009.
D9010	Error step	Step number at which operation error has occurred	• When operation error has occurred during execution of application instruction, the step number, at which the error has occurred, is stored in BIn code. Thereafter, each time operation error occurs, the contents of D9010 are renewed.
D9011	Error step	Step number at which operation error has occurred	 When operation error has occurred during execution of application instruction, the step number, at which the error has occurred, is stored in Bln code. Since storage into D9011 is made when M9011 changes from off to on, the contents of D9010 cannot be renewed unless M9011 is cleared by user program.
	I/O control	I/O control mode number	The set mode is represented as follows:
D9014	mode		0 ≂ I/O in direct mode
1	1		3 = 1/O in refresh mode

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Number	Name	Stored Data	Explanation
	CPU operating states	Operating states of CPU Depreting states of C	The operating states of CPU as shown below are stored in D9015. B15 B12 B11 B8 B7 B4 B3 B0 I I I I I I I I I I I I I I I I I I I I
D9015			CPU RUN/STOP Remains un-changed in remote run/stop mode. 0 RUN 1 STOP Remote RUN/STOP by parameter setting 0 0 RUN 1 STOP 2 PAUSE*1 Status in program 0 0 Except below 1 [STOP] instruction execution Remote RUN/STOP by computer 0 0 Except below 1 [STOP] instruction execution Remote RUN/STOP by computer 0 0 RUN 1 STOP 2 PAUSE*1
			*1 When the CPU is in RUN mode and M9040 is off, the CPU remains in RUN mode if changed to PAUSE mode.
D9016	ROM/RAM setting	0: ROM 1: RAM 2: E2PROM	 Indicates the setting of memory select chip. One value of 0 to 2 is stored in BIN code.
D9017	Scan time	Minimum scan time (per 10ms)	 If scan time is smaller than the content of D9017, the value is newly stored at each END. Namely, the minimum value of scan time is store into D9017 in BIN code.
D9018	Scan time	Scan time (per 10ms)	 Scan time is stored in BIN code at each END and always rewritten.
D9019	Scan time	Maximum scan time (per 10ms)	 If scan time is larger than the content of D9019, the value is newly stored at each END. Namely, the maximum value of scan time is stored into D9019 in BIN code

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Number	Name	Stored Data	Explanation
*2 D9020	Constant scan	Constant scan time (User specified in 10ms increments)	 Sets user program execution intervals in 10ms increments. 0: Constant scan function unused 1 to 200: Constant scan function used, program executed at intervals of (set value) × 10ms.
*2 D9025	Clock data	Clock data (Year, month)	• Stores the year (least significant digits) and month in BCD. B15 B12 B11 B8 B7 B4 B3 B0 Year month Example: 1987, July H8707
*2 D9026	Clock data	Clock data (Day, hour)	• Stores the day and hour in BCD. B15 B12 B11 B8 B7 B4 B3 B0 Day hour Example: 31st, 10 0'clock, H3110
•2 D9027	Clock data	Clock data (Minute, second)	Stores the minute and second in BCD. B15 B12 B11 B8 B7 B4 B3 B0 I I I I I I I I I I I I I I I I I
*2 D9028	Clock data	Clock data (, day of the week)	 Stores the day of the week in BCD. B15 B12 B11 B8 B7 B4 B3 B0 i i i i i i i i i i i i i i i i i i i

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Number	Name	Stored Data	Explanation
*2 D9038	LED display priority	Priority 1 to 4	 Set the error item numbers to the ERROR LED display (flashing) priority setting registers (1 to 4 at D9038 and 5 to 7 at D9039).
		-	B15 B12 B11 B8 B7 B4 B3 B0
			$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$
		Priority 5 to 7	Even when "0" is set, the ERROR LED display is given for
			those errors with 0. No display is given.
			operation stops 1. I/O verify and fuse (parameter setting break errors
*2 D9039			errors are also included).2.Special-function module, link parameter, SFC parameter, and SFC operation errors
			D9039 = H0006 3. CHK instruction error
			4. Annunciator (F)
			6. Battery error
	Fuer blown		
*1 D9100	module	of 16 points of fuse blow modules (Y000 to Y0FF)	 Output module numbers (in units of 16 points), of which fuses have blown, are entered in bit pattern. (Preset output number when parameter setting has been performed.)
			$\begin{array}{c ccccccccccccccccccccccccccccccccccc$
			Indicated fuse blow. (If normal status is restored, clear is not performed.
			Therefore, it is required to perform clear by user program.)
*1 D9116	I/O module verify error	Bit pattern in modules of 16 points of verify error modules (Y000 to Y0FF)	 When I/O module data is different from those entered at power-on have been detected, the I/O module numbers (in units of 16 points) are entered in bit pattern. (Preset I/O module numbers when parameter setting has been performed.)
			$\begin{array}{c ccccccccccccccccccccccccccccccccccc$
			(If normal status is restored, clear is not performed. Therefore, it is required to perform clear by user program.)

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Number	Name	Stored Data	Explanation
D9124	Annunciator detection quantity	Annunciator detection quantity	 When one of F0 to 255 is turned on by [OUT F] or [SET F], 1 is added to the contents of D9124. When [RST F] or [LED R] instruction is executed, 1 is subtracted from the contents of D9124. Quantity, which has been turned on by [OUT F] or [SET F] is stored into D9124 in BIN code. The value of D9124
D9125 D9126 D9127 D9128 D9129 D9130 D9131 D9132	Annunciator detection number	Annunciator detection number	F] is stored into D9124 in BIN code. The value of D9124 is maximum 8. • When one of F0 to 255 is turned on by [OUT F] or [SET F], F number, which has turned on, is entered into D9125 to D9132 in due order in BIN code. F number, which has been turned off by [RST F], is erased from D9125 to D9132, and the contents of data registers succeeding the data register, where the erased F number was stored, are shifted to the preceding data registers. By executing [LED R] instruction, the contents of D9125 to D9132 are shifted upward by one. When there are 8 annunciator detections, the 9th one is not stored into D9125 to 9132 even if detected. SET SET SET SET SET SET SET SET SET SET
			D9131 0 0 0 0 0 0 0 0 0 0 0 110110110151 D9132 0 0 0 0 0 0 0 0 0 0 0 0 151151210
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POINTS

- (1) All special register data is cleared by any of the power-off, latch clear and reset operations. The data is retained when the RUN/STOP switch is set to STOP.
- (2) For the above special registers with numbers marked *1, the contents of register are not cleared if normal status is restored. Therefore, to clear the contents, use the following method:
 - 1) Method by user program.

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Insert the circuit shown at right into the program and turn on the clear execution command contact to clear the contents of register.



2) Method by peripheral equipment.

Set the register to "0" by changing the present value by the test function of peripheral equipment or set to "0" by forced reset. For the operation procedure, refer to the manual of each peripheral equipment.

- 3) By moving the RESET key switch at the CPU front to the RESET position, the special register is set to "0".
- (3) Data is written to the special registers marked *2 by the sequence program.
APPENDIX 3 OUTSIDE DIMENSIONS

3.1 CPU Module

3.1.1 A1SJCPU module



3.1.2 A1SJCPU-S3 module

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4-66 mounting screws (M5 × 25) 00 0 0 0 00 ¢ MITSUBISHI POWER O Φ **...................... 20R O** HELIER AISJow-sa (OUT) õ OUTPUT UUUUUUUU D -00 MPUT AC100/200V 100 (_) (_) NP (س **ሕ**ነ ∕≜≣ Φ Ф PULL 164 (065 310 (12.2 330 (13.0 82 (3.23) 5 (0.2)

Unit: mm (in)

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3.2 Power Supply Module

3.2.1 A1S61P/A1S62P/A1S63P power supply module



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3.2.2 A1S61PEU/A1S62PEU power supply module



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3.3 Extension Base Units

3.3.1 A1S65B, A1S65B-S1 extension base unit



Unit: mm (in)

3.3.2 A1S68B, A1S68B-S1 extension base unit





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3.3.4 A1S55B, A1S55B-S1 extension base unit



Unit: mm (in)

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3.3.5 A1S58B, A1S58B-S1 extension base unit



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3.4 Memory Cassette (A1SMCA-[])



3.5 A6WA-28P Memory Write Adaptor



3.6 40-Pin Connectors

3.6.1	A6CON1 soldering-type 40-pin connector	, A6CON2 crimp-contact-type 40-pin connector
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3.6.2 A6CON3 pressure-displacement-type 40-pin connector





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3.7 37-Pin D Sub-Connectors

3.7.1 A6CON1E soldering type 37-pin D sub-connector A6CON2E crimp-contact-type 37-pin D sub-connector



Unit: mm (inch)

3.7.2 A6CON3E pressure-displacement-type 37-pin D sub-connector





APPENDIX 4 INSTRUCTION PROCESSING TIME

An A1SJCPU requires the instruction processing time as much as an An CPU does except the following instructions. See the ACPU Programming Manual (Common Instructions) for the processing time for each instruction.

Instruction	Condition	Processing Time (µsec)	
Instruction		Direct Method	Refresh Method
OUT F	When not executed	61	62
	When executed	267	270
SET F	When not executed	3.2	2.7
	When executed	237	232
RST F	When not executed	3.0	3.6
	When executed	283	296
LEDR	When not executed	54	55
	When executed	283	283
СНК	With 1 contact condition	240	
	With 50 contact conditions	3905	—
	With 100 contact conditions	7820	
	With 150 contact conditions	11470	-

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3.4.4 Dynamic I/O module



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3.4.5 A1SJ-56[] I/O combination module



Unit: mm (in)

Unit: mm (in)

3.5 Dummy Module, Blank Cover

3.5.1 A1SG60 blank cover



3.5.2 A1SG62 dummy module



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3.6 Memory Cassette (A1SMCA-[])



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3.7 A6WA-28P Memory Write Adaptor



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3.8 40-Pin Connectors





3.8.2 A6CON3 pressure-displacement-type 40-pin connector





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- 3.9 37-Pin D Sub-Connectors
- 3.9.1 A6CON1E soldering type 37-pin D sub-connector A6CON2E crimp-contact-type 37-pin D sub-connector



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Unit: mm (inch)

3.9.2 A6CON3E pressure-displacement-type 37-pin D sub-connector





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SET F	When not executed	3.2	2.7
	When executed	237	232
RST F	When not executed	3.0	3.6
	When executed	283	296
LEDR	When not executed	54	55
	When executed	283	283
снк	With 1 contact condition	240	_
	With 50 contact conditions	3905	
	With 100 contact conditions	7820	
	With 150 contact conditions	11470	

IMPORTANT

- (1) Design the configuration of a system to provide an external protective or safety inter locking circuit for the PCs.
- (2) The components on the printed circuit boards will be damaged by static electricity, so avoid handling them directly. If it is necessary to handle them take the following precautions.
 - (a) Ground human body and work bench.
 - (b) Do not touch the conductive areas of the printed circuit board and its electrical parts with and non-grounded tools etc.

Under no circumstances will Mitsubishi Electric be liable or responsible for any consequential damage that may arise as a result of the installation or use of this equipment.

All examples and diagrams shown in this manual are intended only as an aid to understanding the text, not to guarantee operation. Mitsubishi Electric will accept no responsibility for actual use of the product based on these illustrative examples.

Owing to the very great variety in possible applications of this equipment, you must satisfy yourself as to its suitability for your specific application.

type A1SJCPU(S3)

User's Manual

A1SJCPU-U-E

MODEL CODE

MODEL

13J791

IB(NA)66446-C(9701)MEE

MITSUBISHI ELECTRIC CORPORATION

HEAD OFFICE : MITSUBISHI DENKI BLDG MARUNOUCHI TOKYO 100-0005 TELEX ; J24532 CABLE MELCO TOKYO NAGOYA WORKS : 1-14 , YADA-MINAMI 5 , HIGASHI-KU, NAGOYA , JAPAN

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